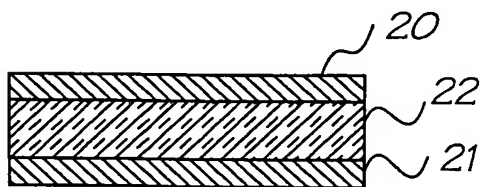


FIG. 3



↓ Cooling

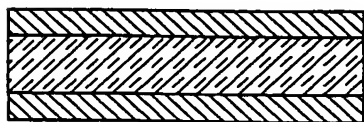
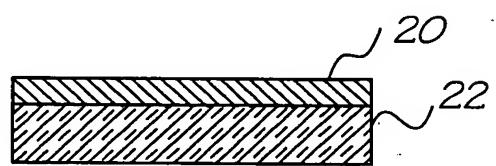


FIG. 4



↓ Cooling

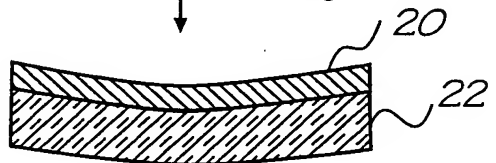


FIG. 5

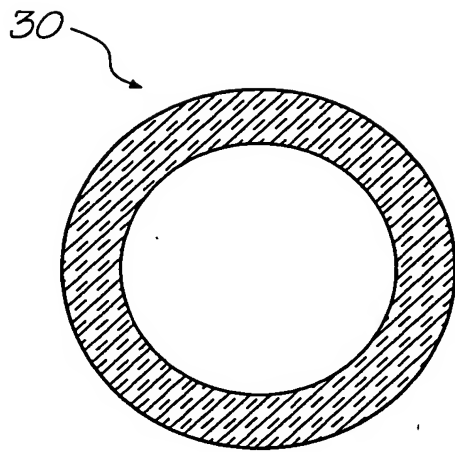


FIG. 6

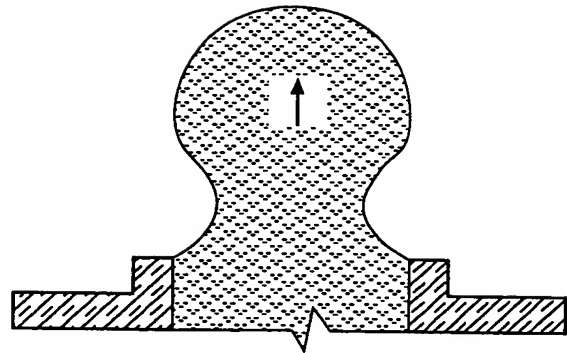


FIG. 7

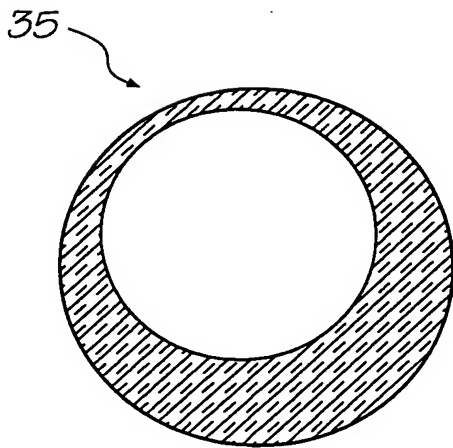


FIG. 8

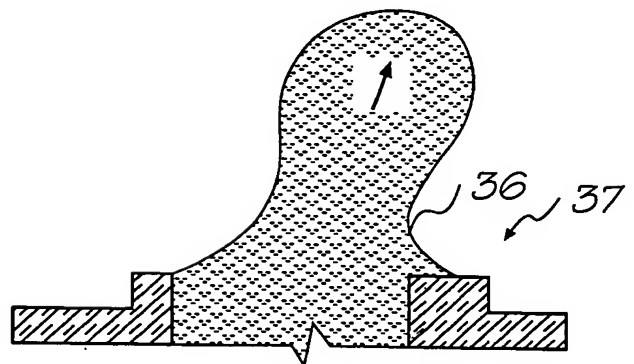


FIG. 9

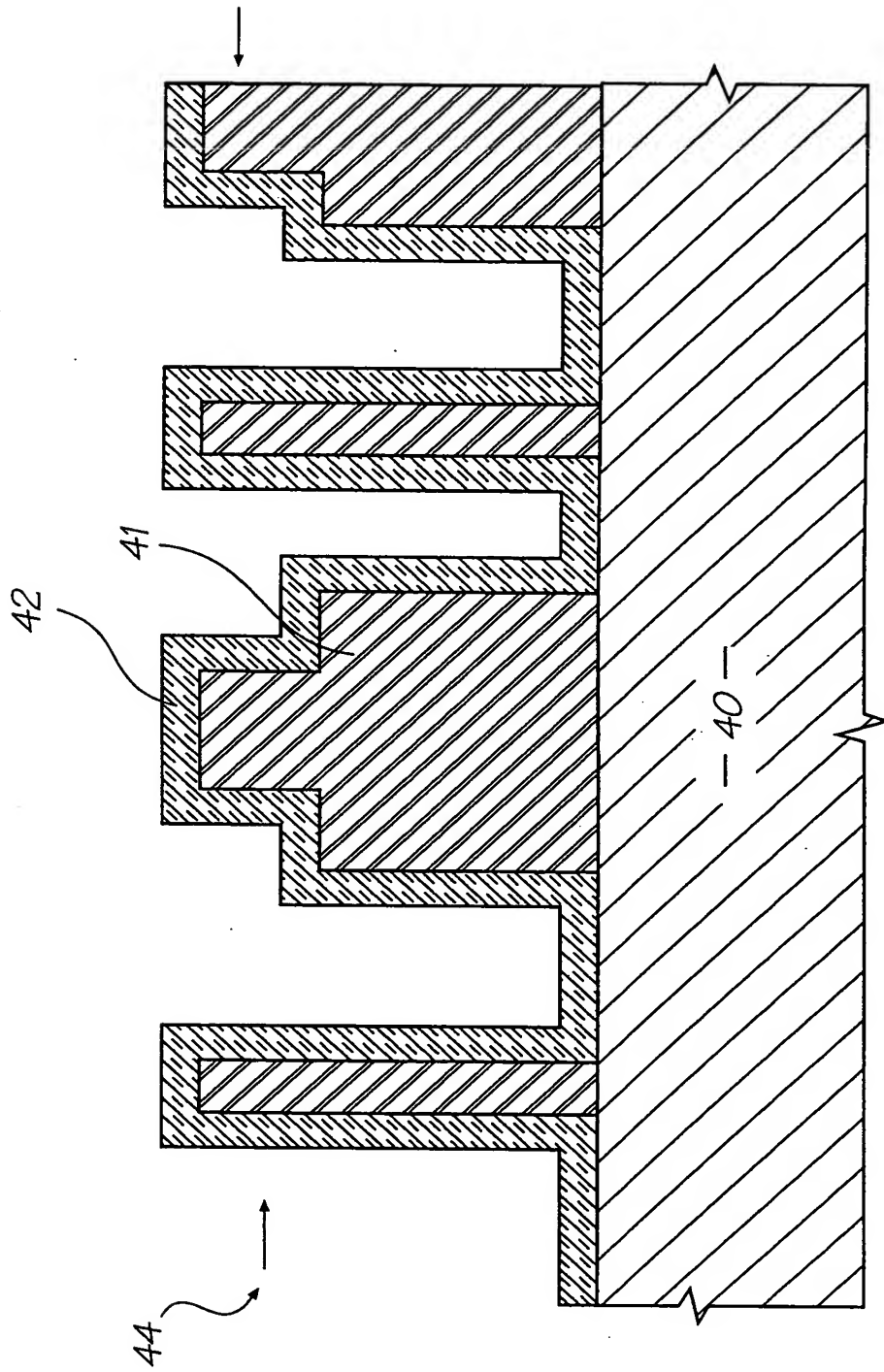


FIG. 10

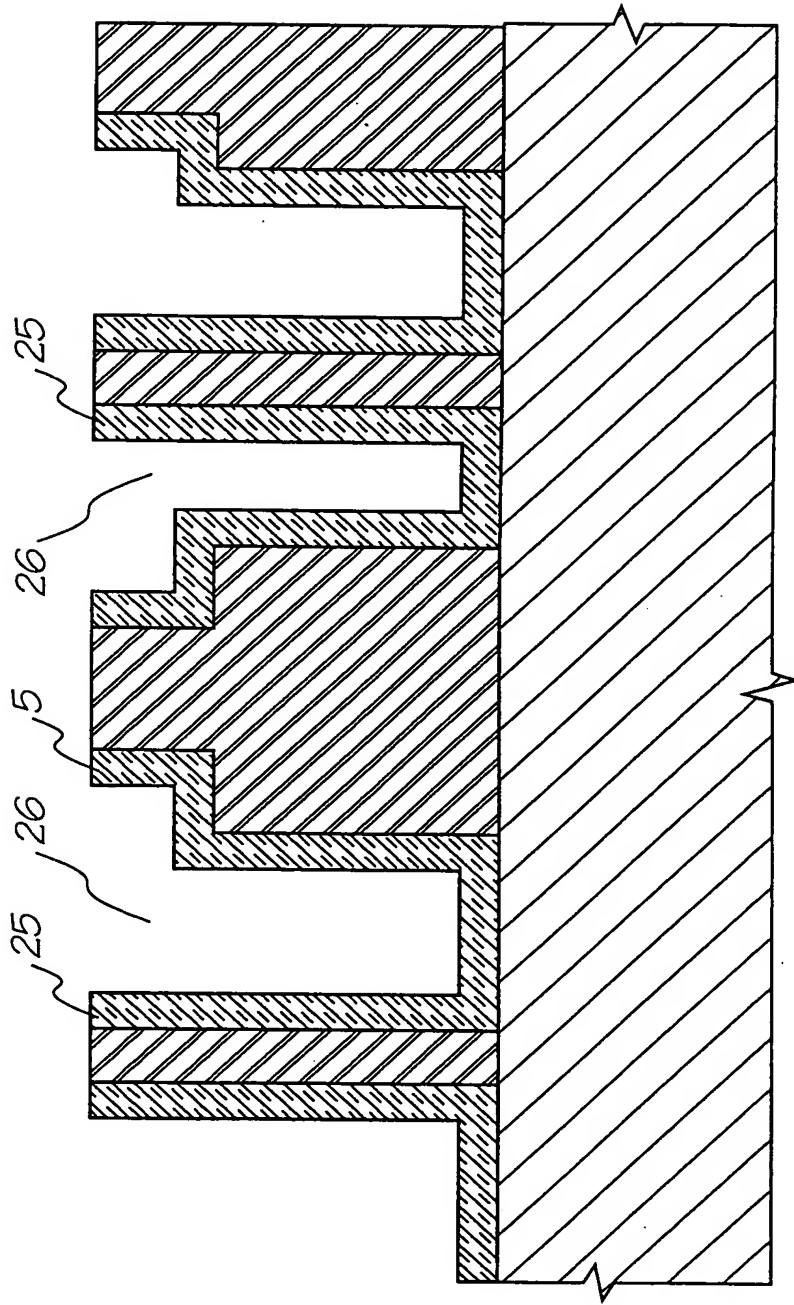


FIG. 11

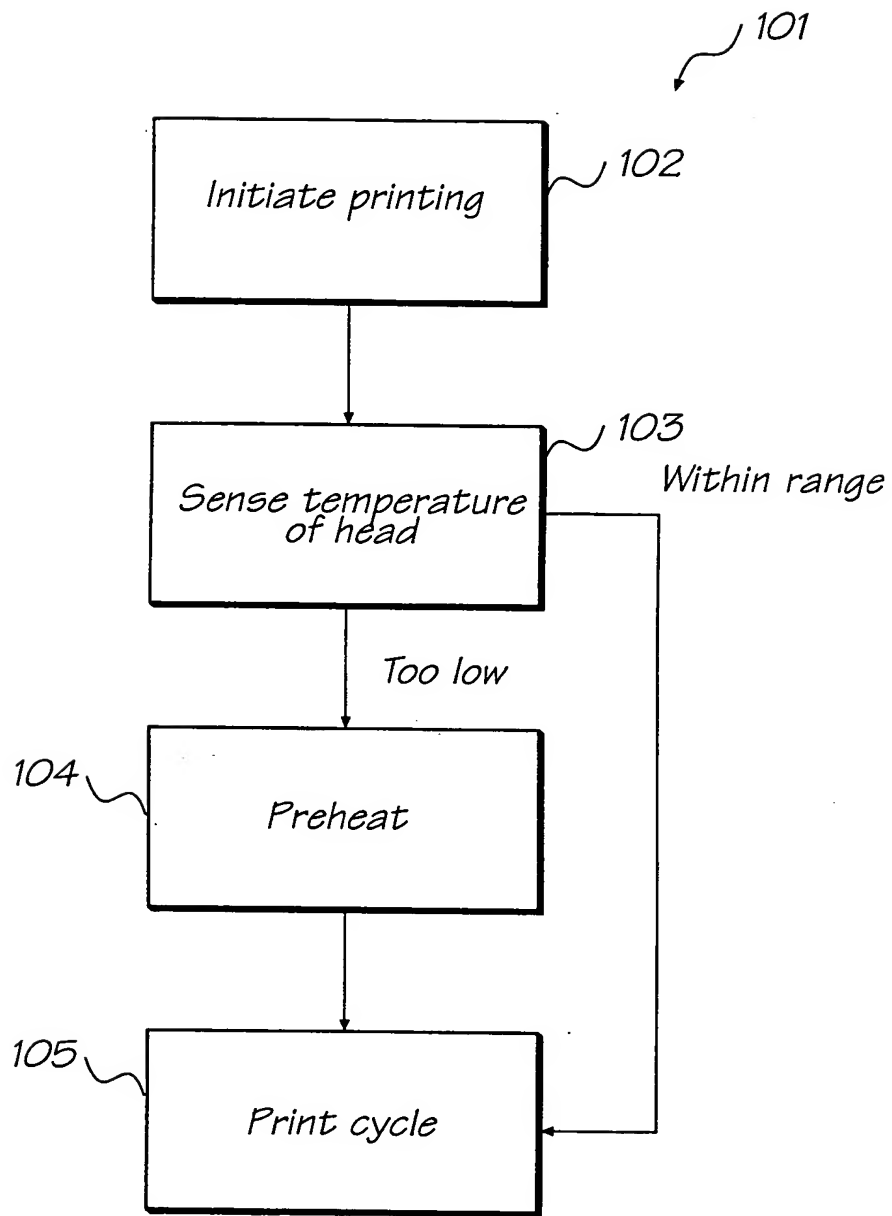


FIG. 12

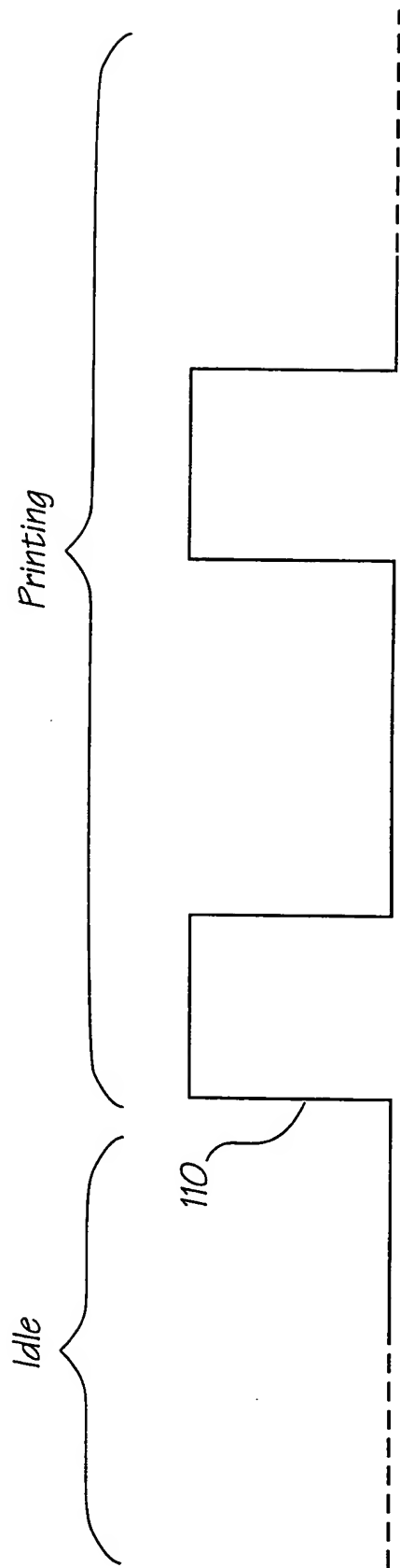


FIG. 13

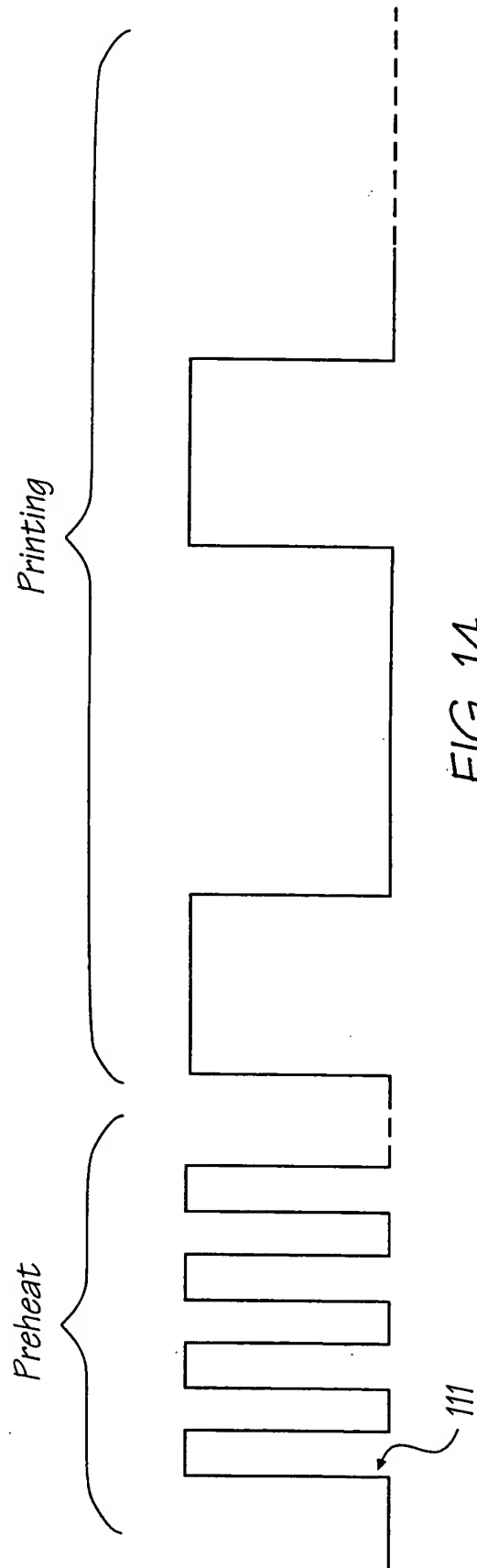


FIG. 14

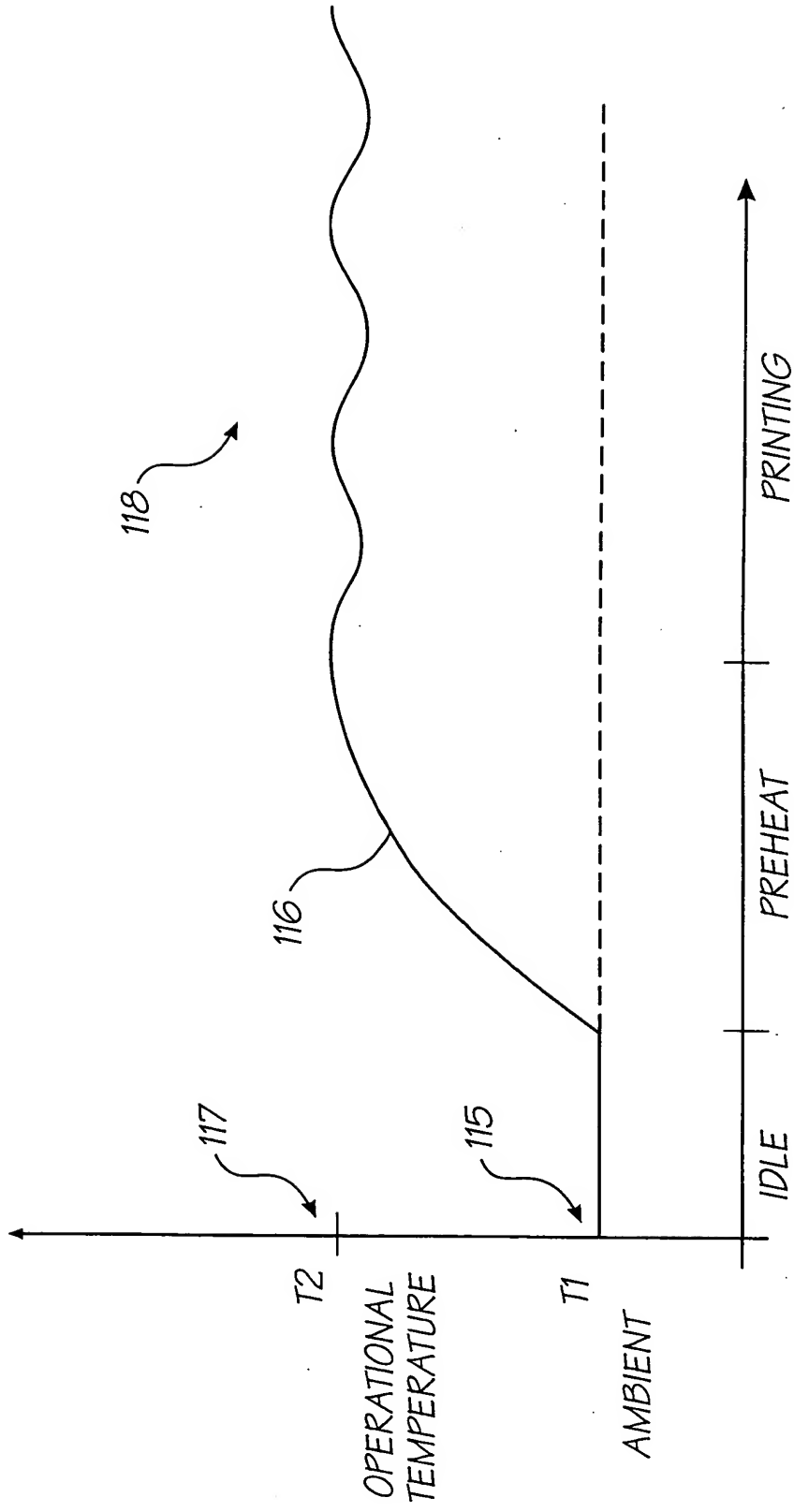


FIG. 15

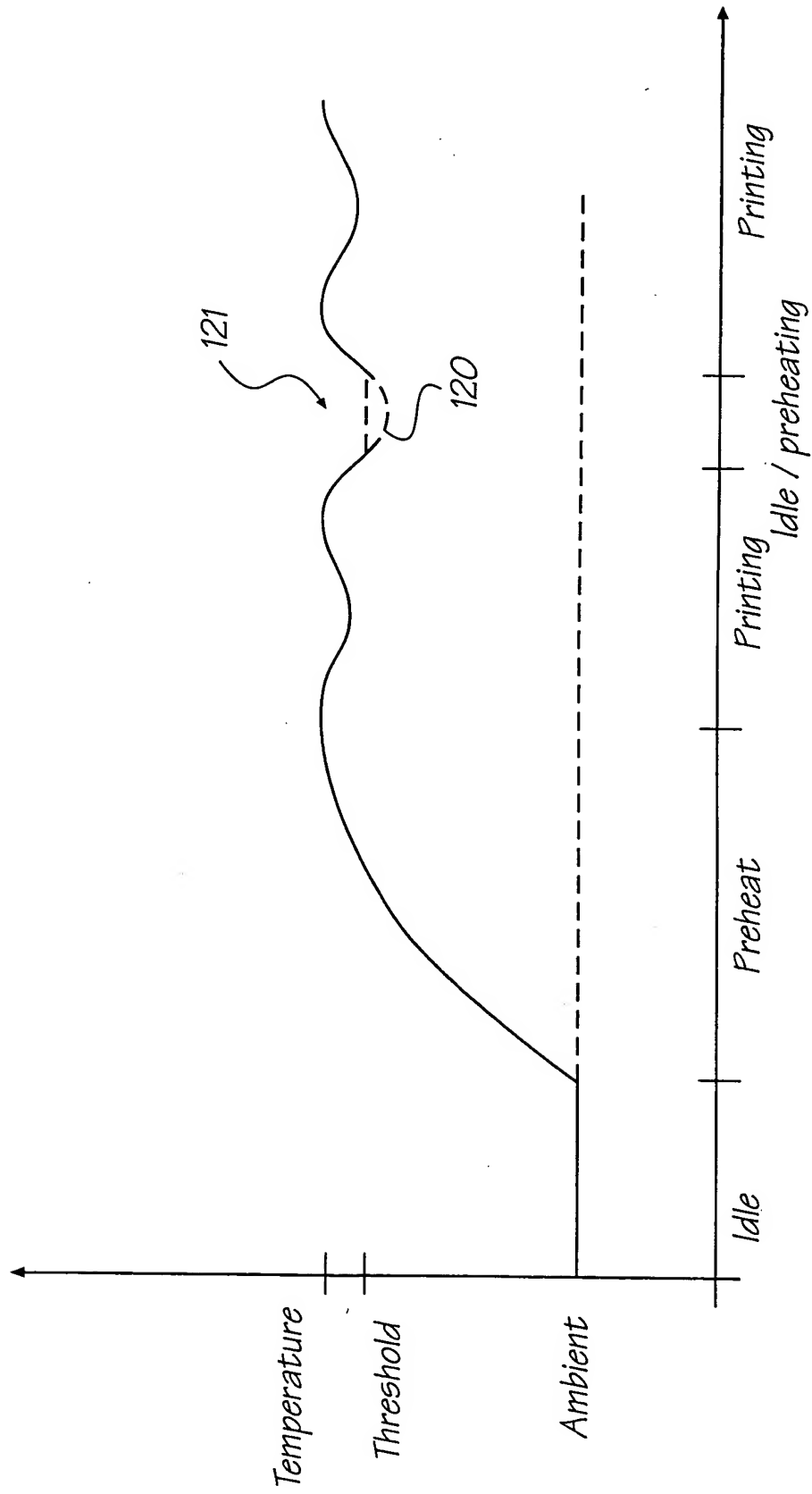


FIG. 16

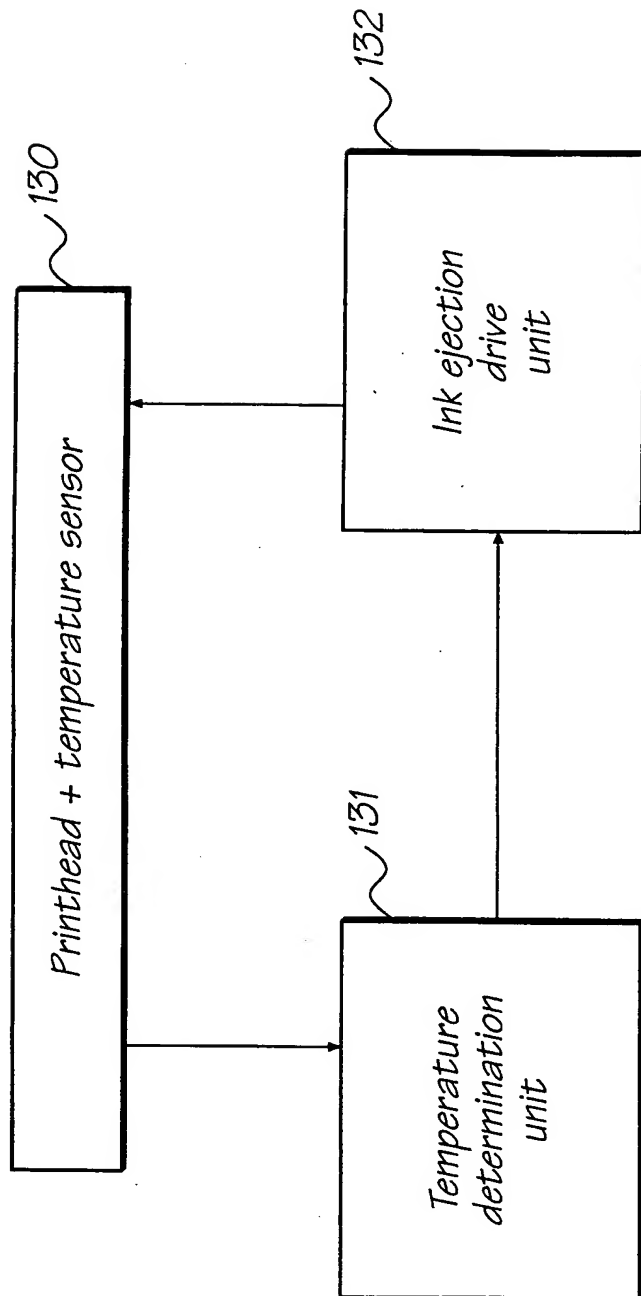


FIG. 17

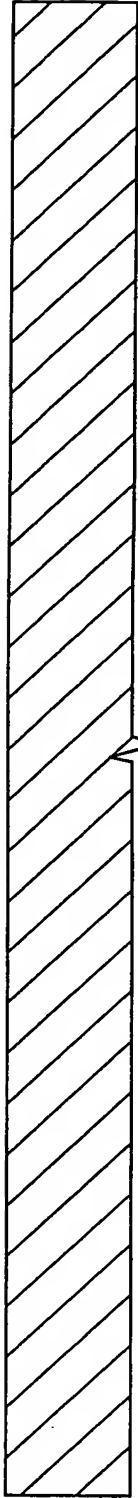
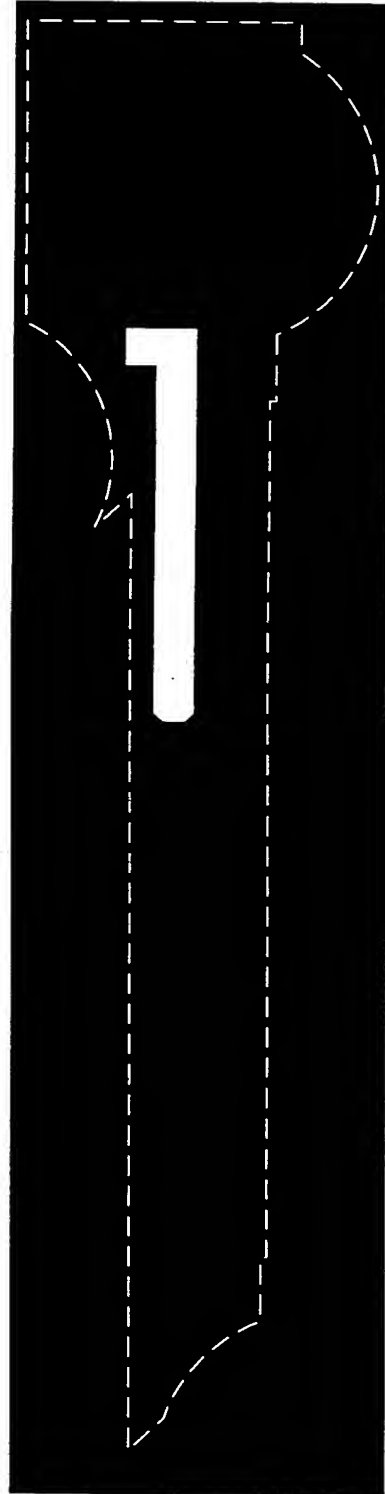
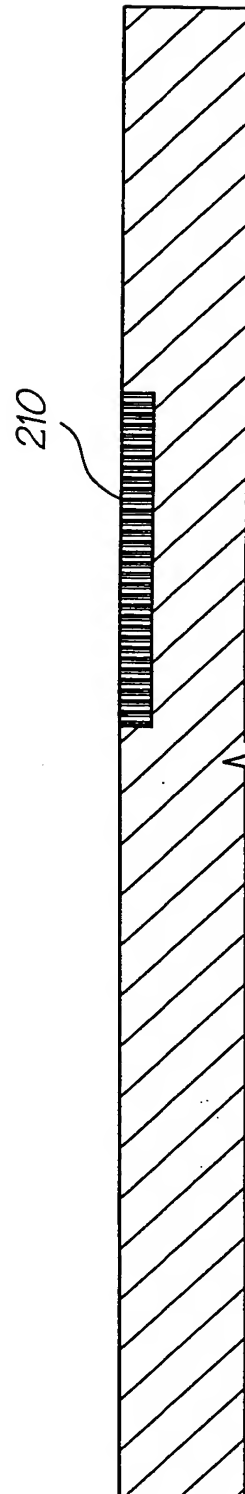


FIG. 18



N-Well mask

FIG. 19



Implant N-Well

FIG. 20

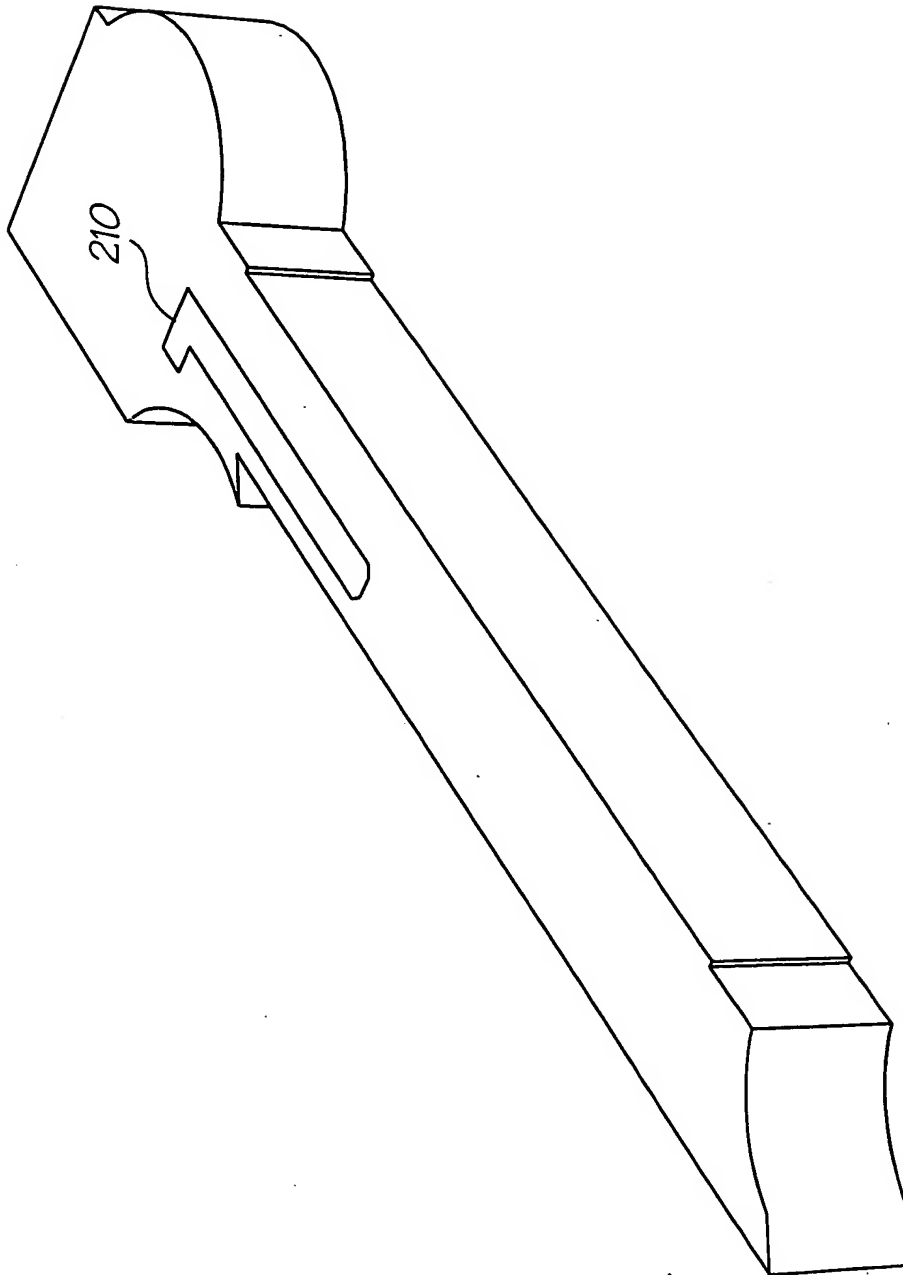
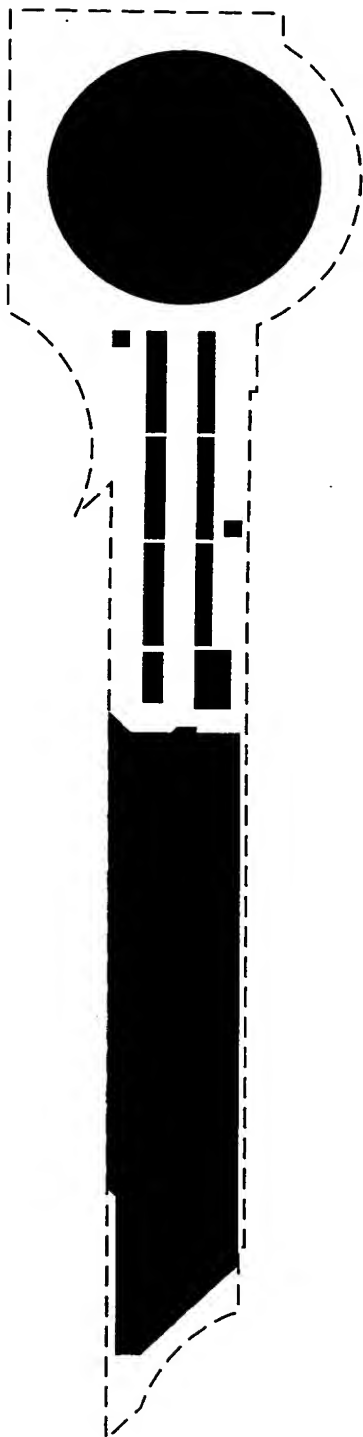
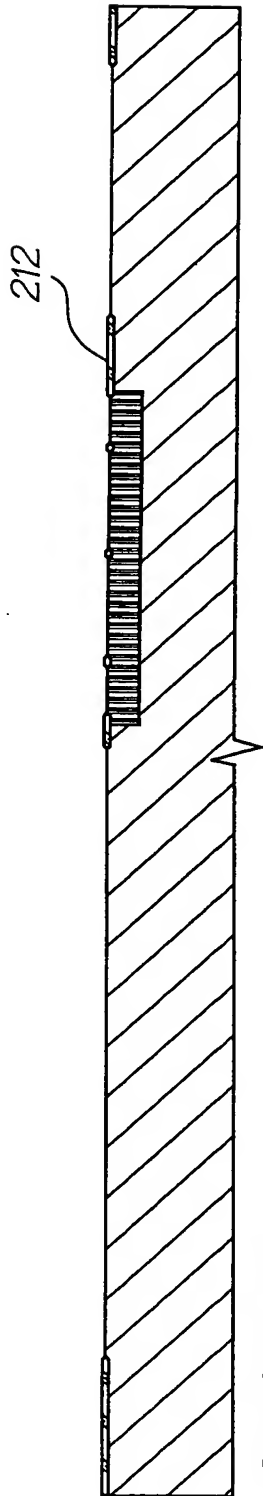


FIG. 21



Active mask

FIG. 22



Grow field oxide

FIG. 23

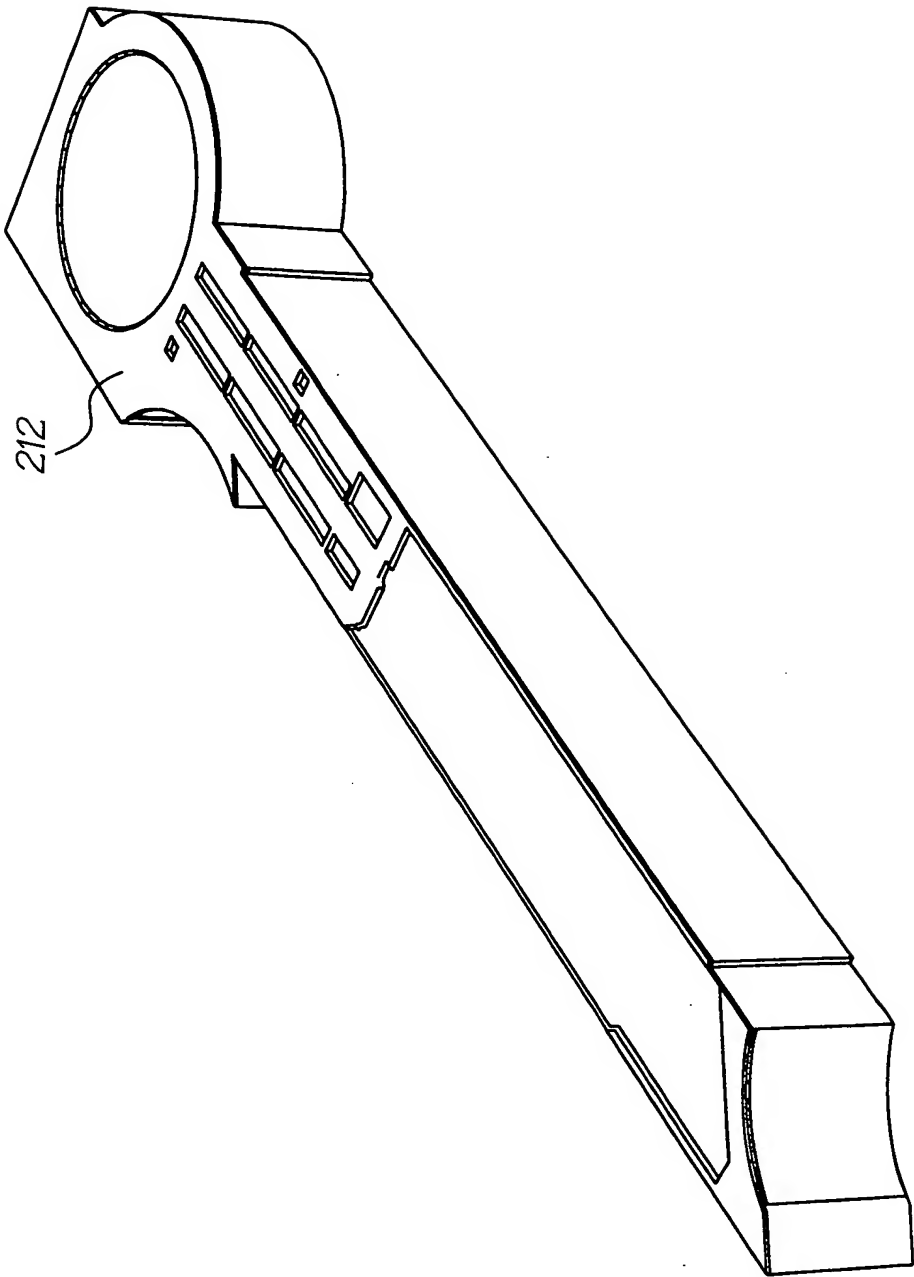
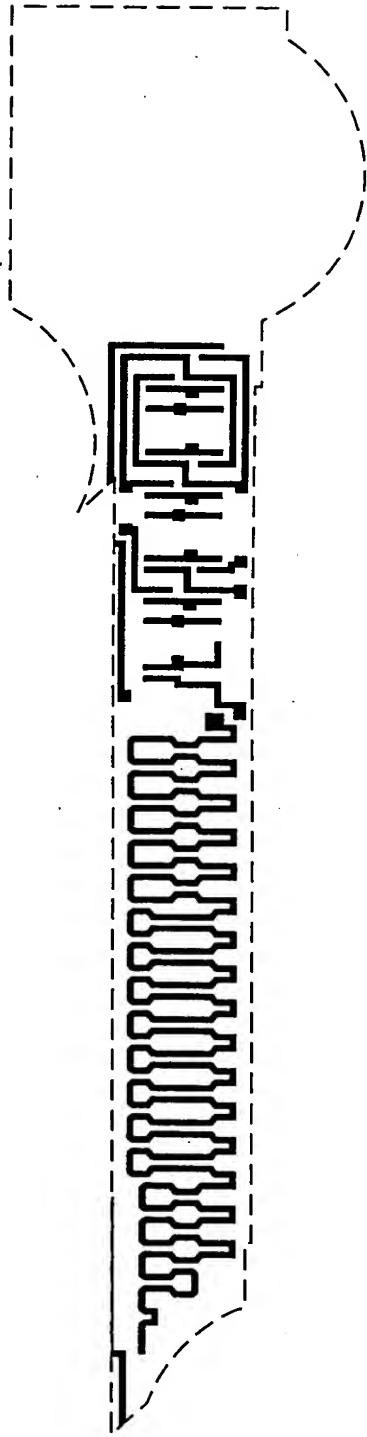
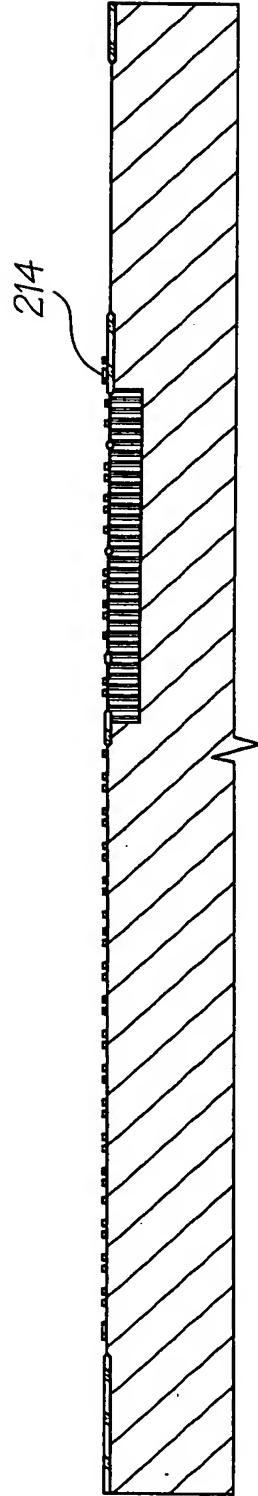


FIG. 24



Poly mask

FIG. 25



Deposit poly

FIG. 26

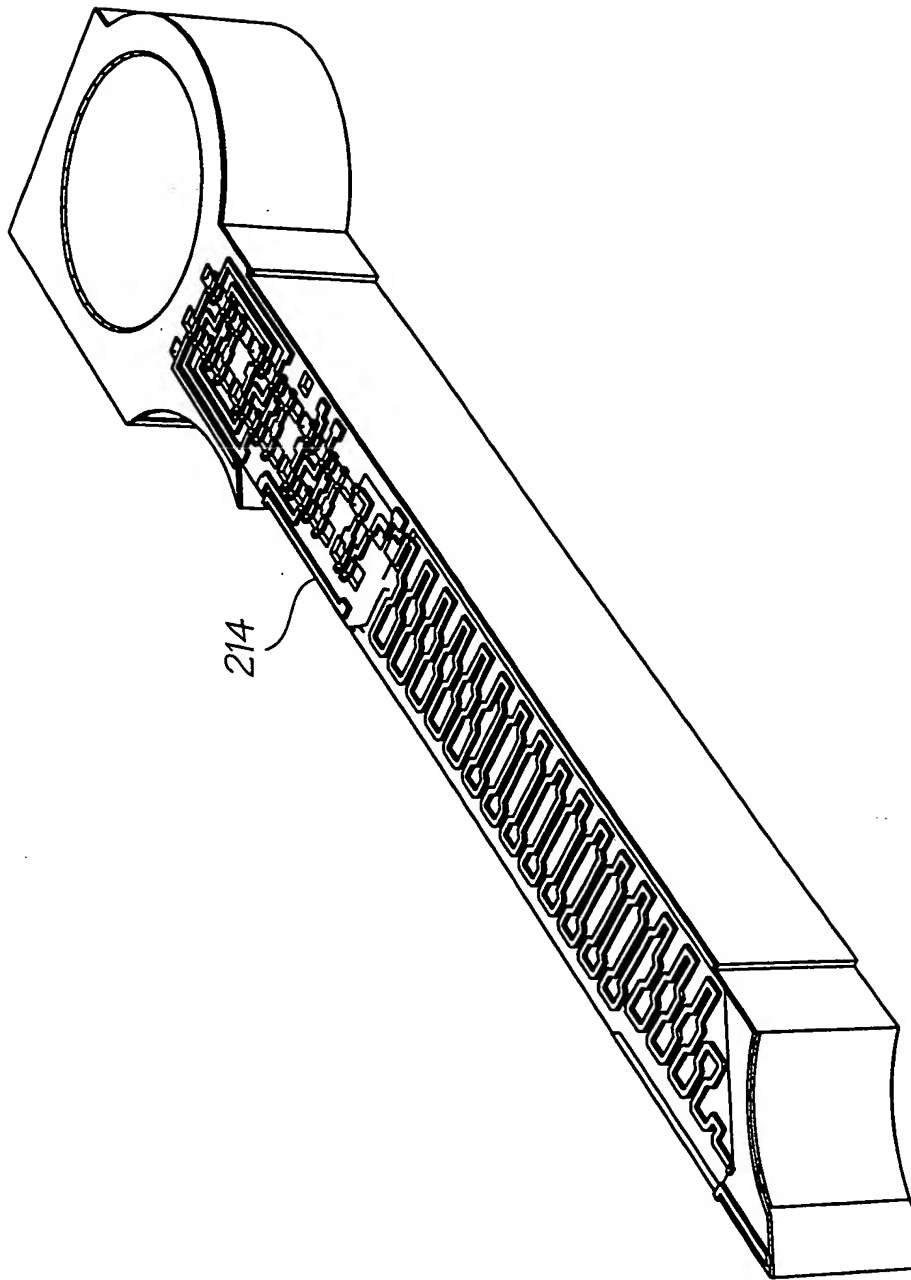
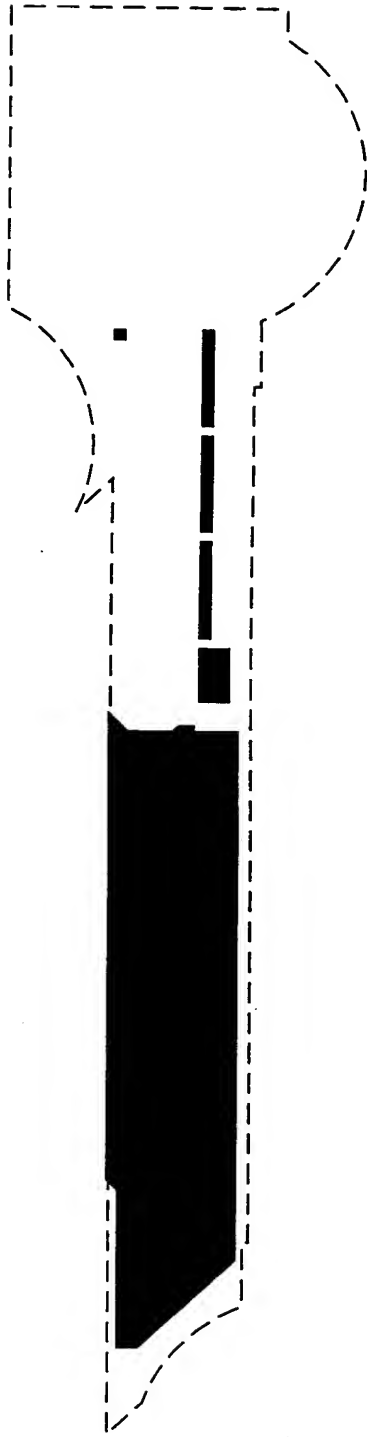


FIG. 27



n+ mask

FIG. 28

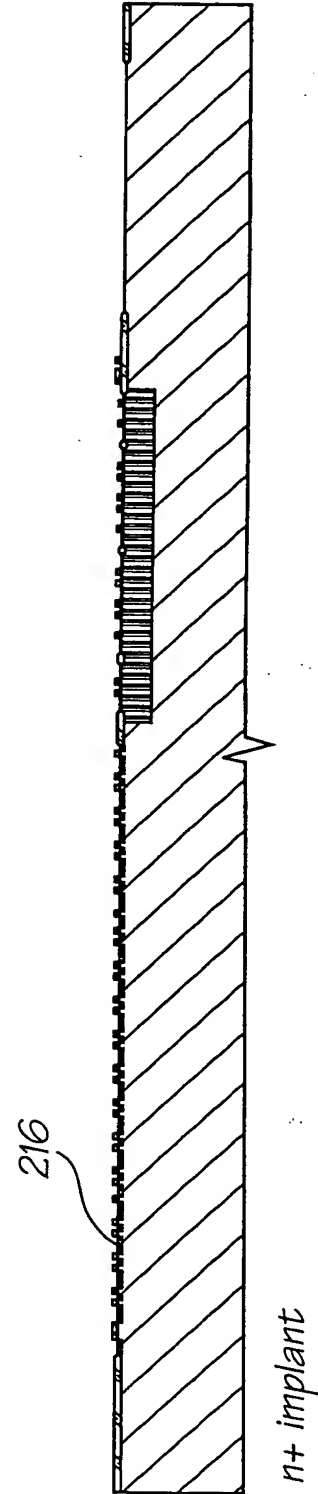


FIG. 29

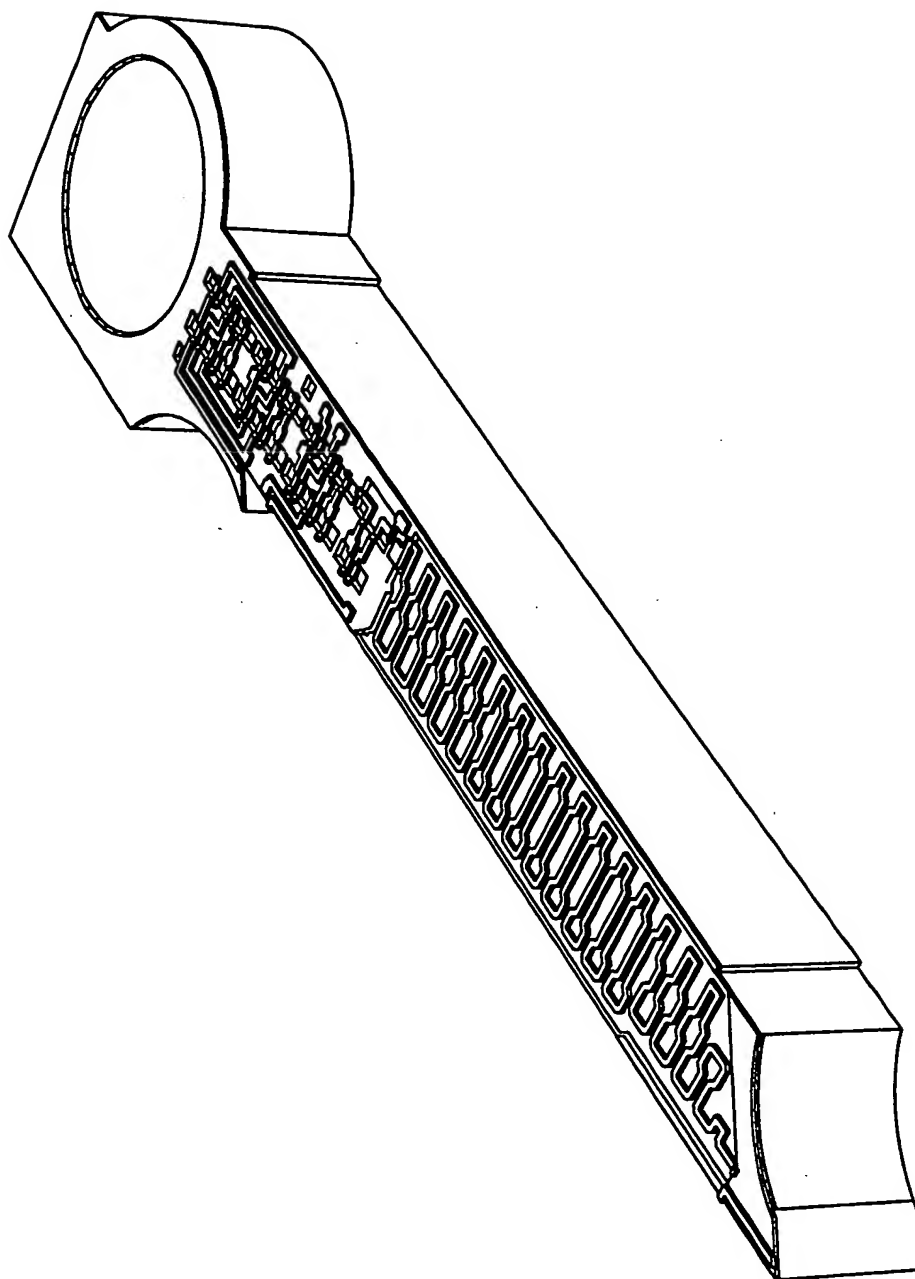


FIG. 30

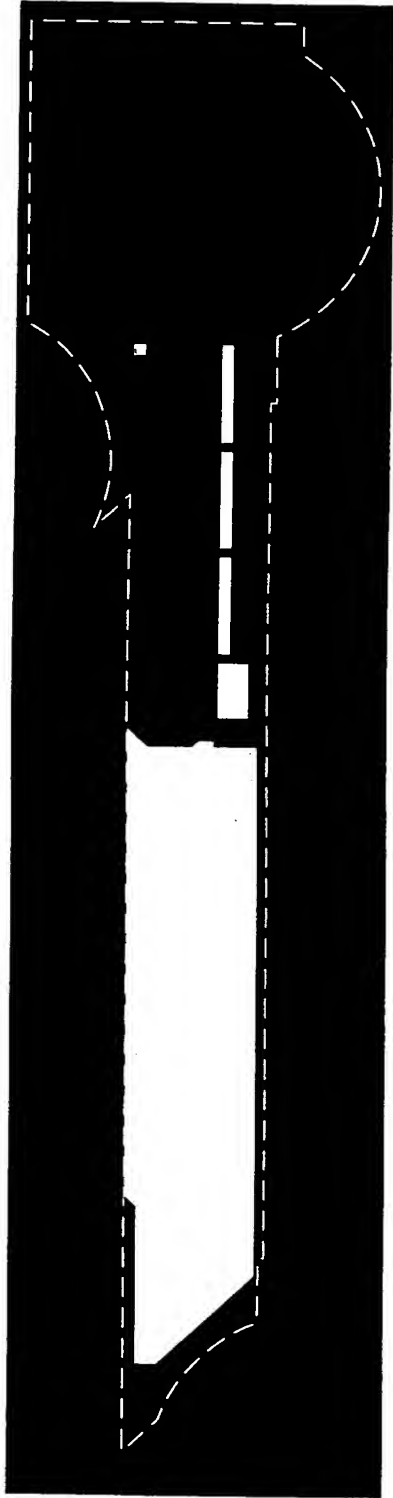


FIG. 31

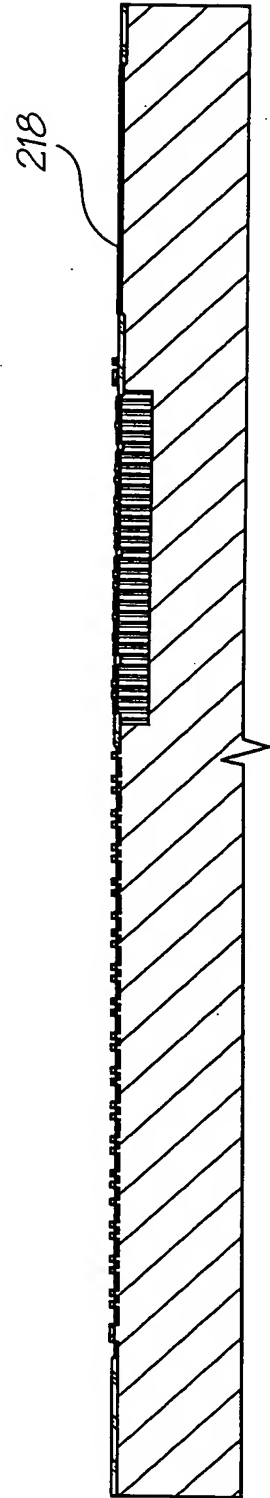


FIG. 32

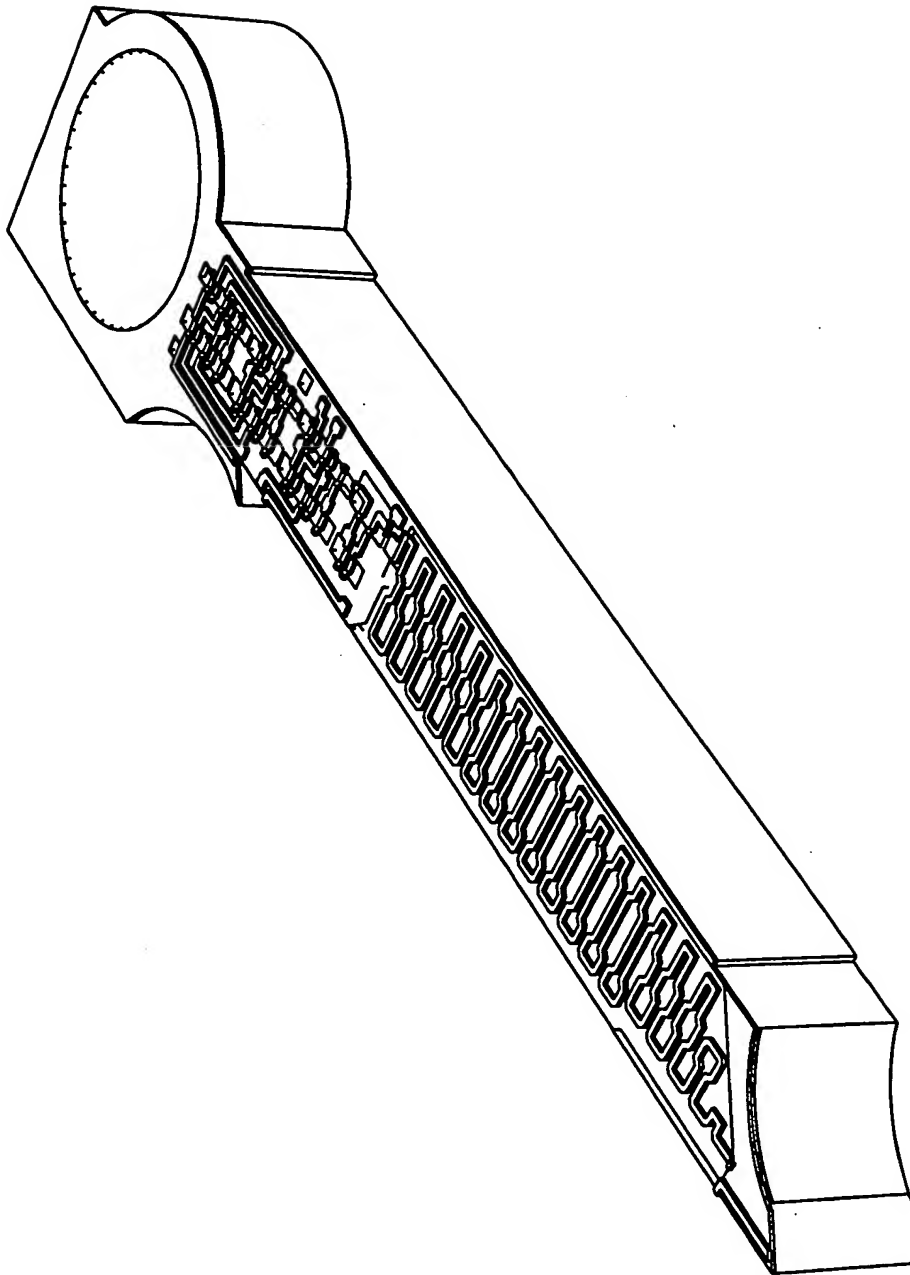
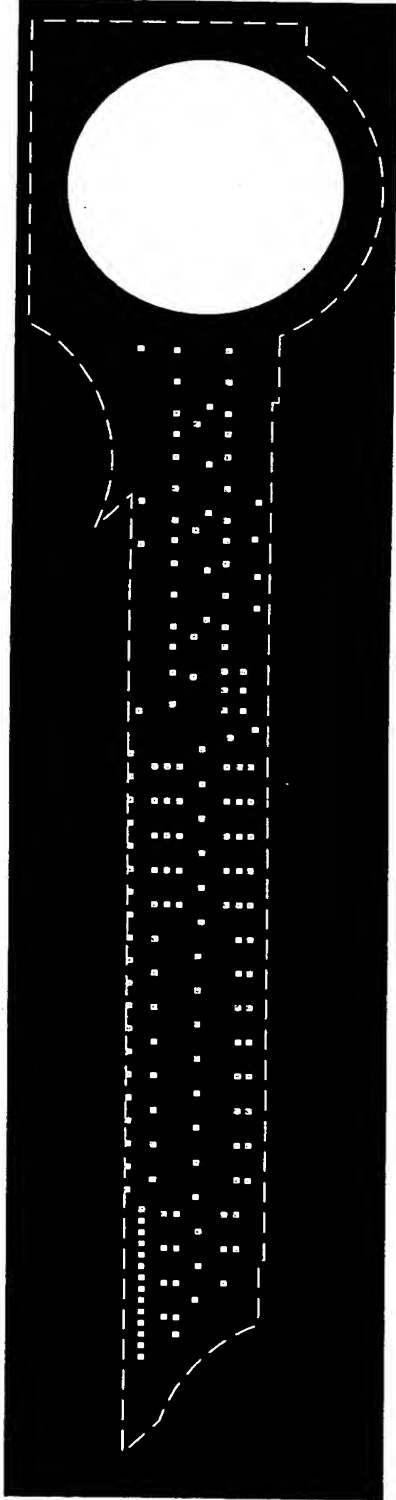
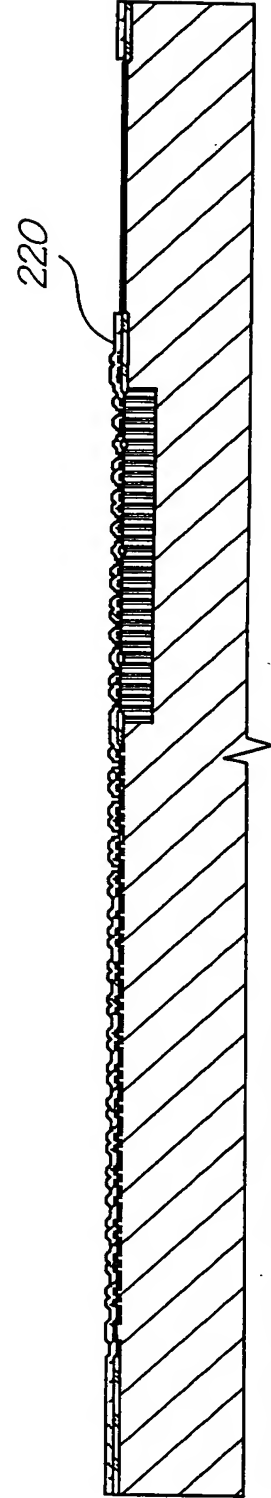


FIG. 33



Contacts mask

FIG. 34



Deposit ILD 1, etch contacts

FIG. 35

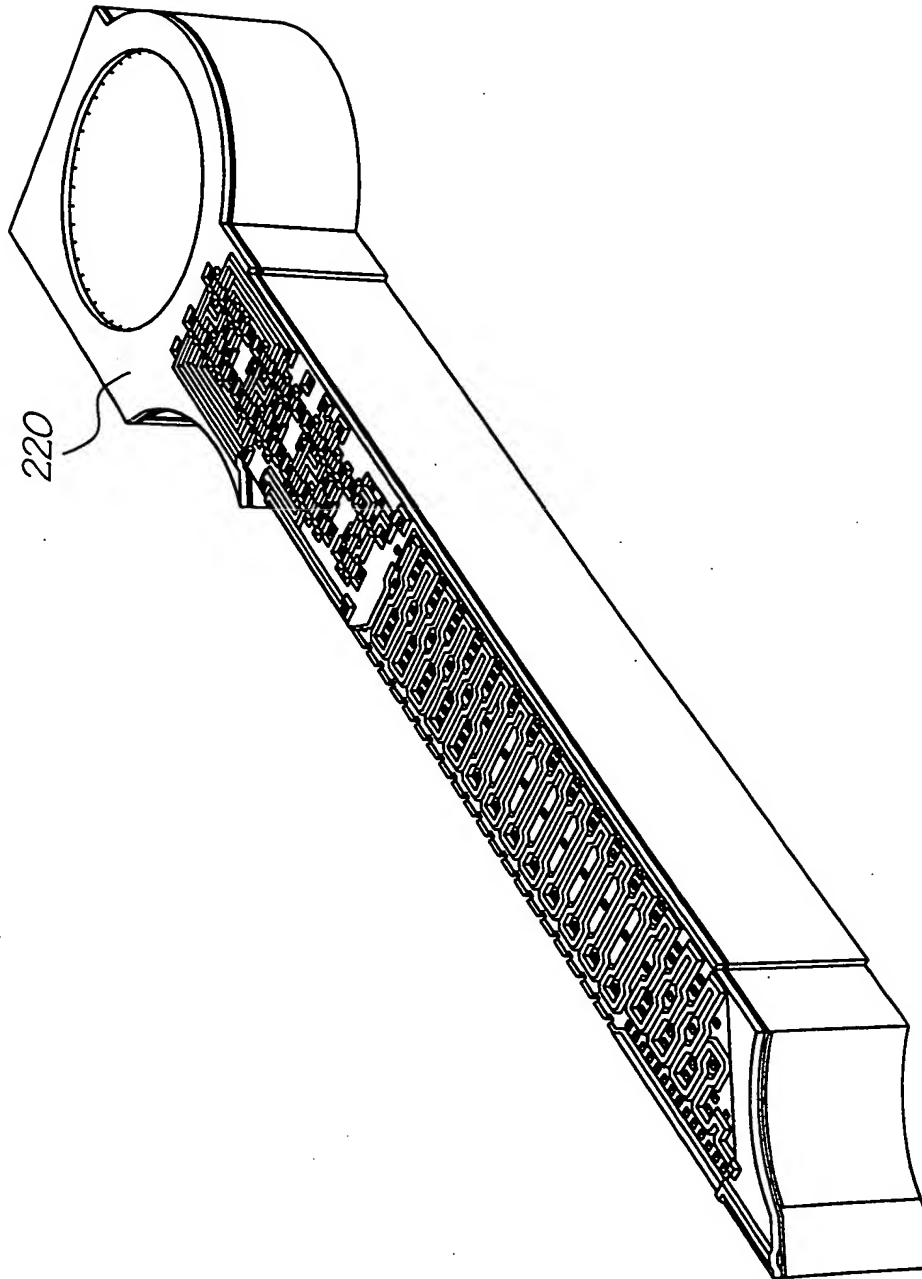
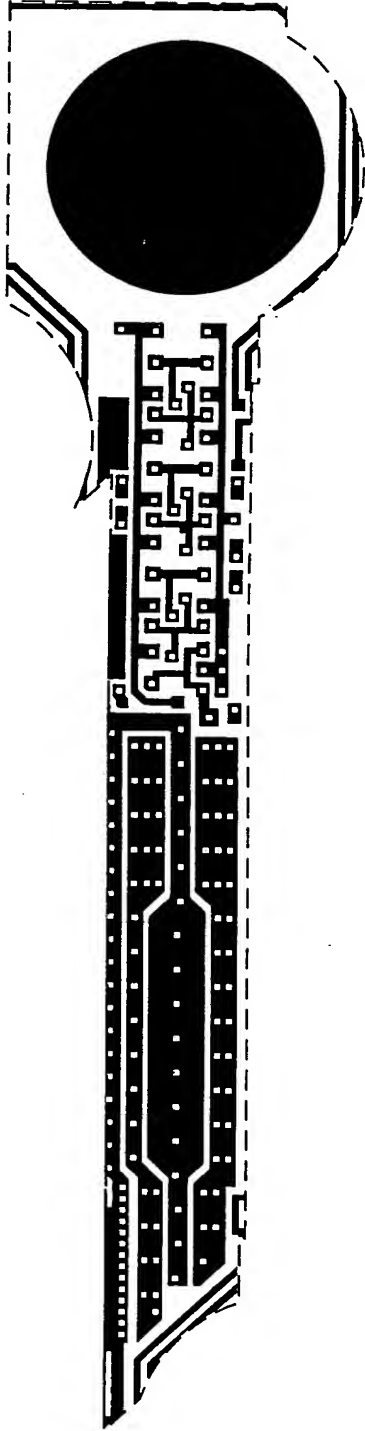
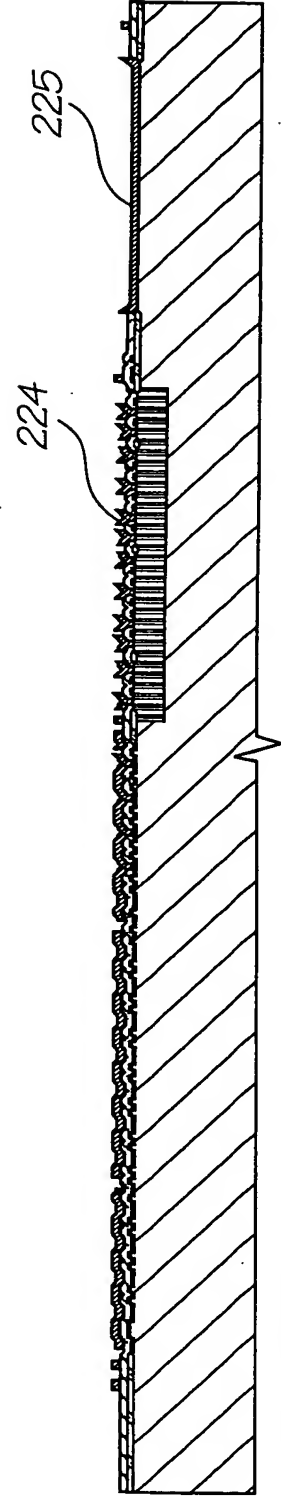


FIG. 36



Metal 1 mask

FIG. 37



Deposit Metal 1

FIG. 38

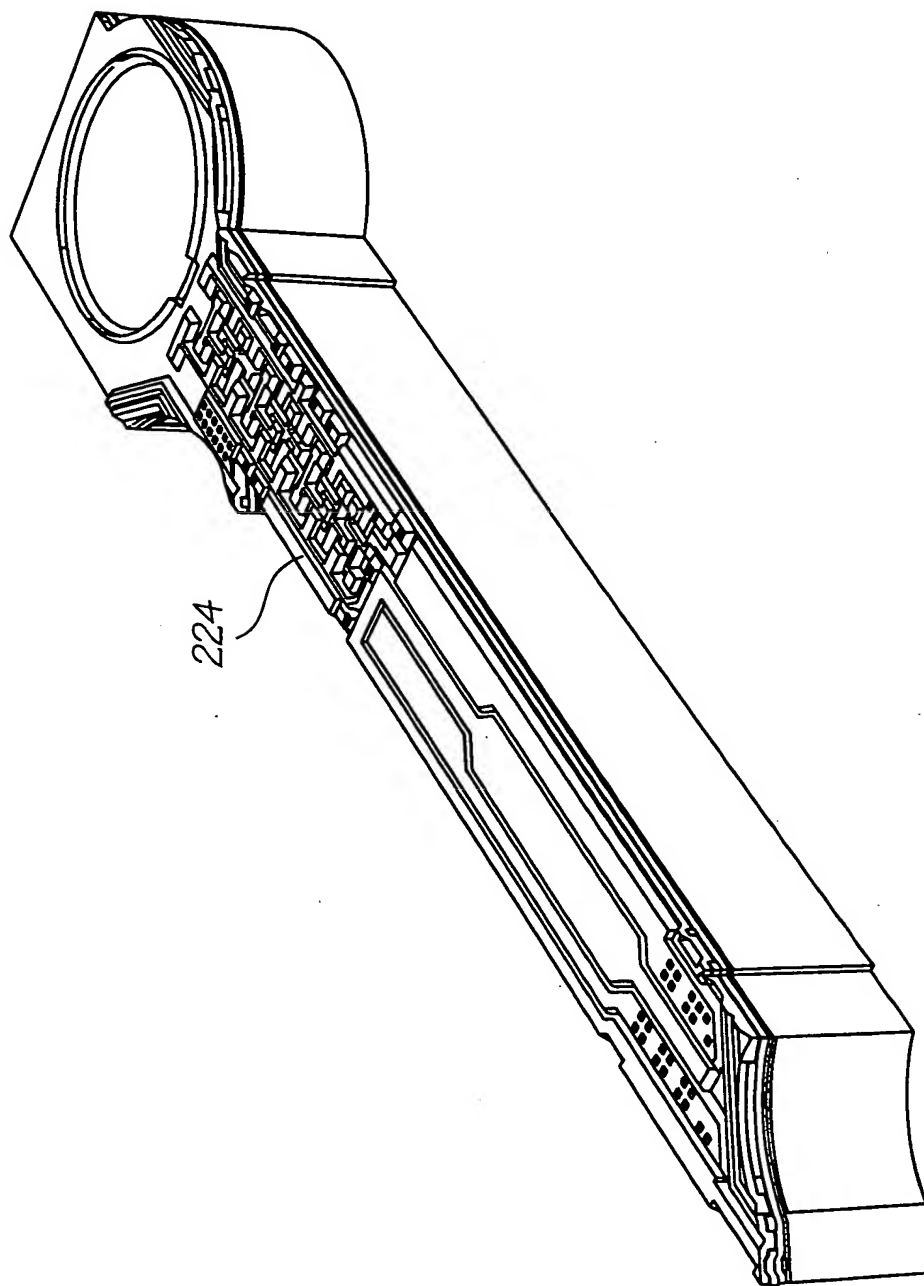
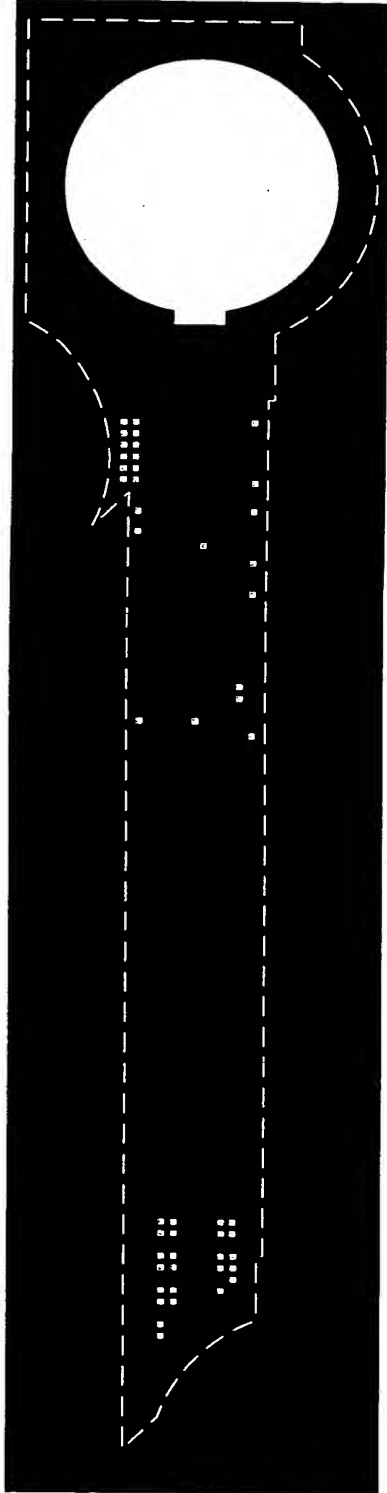
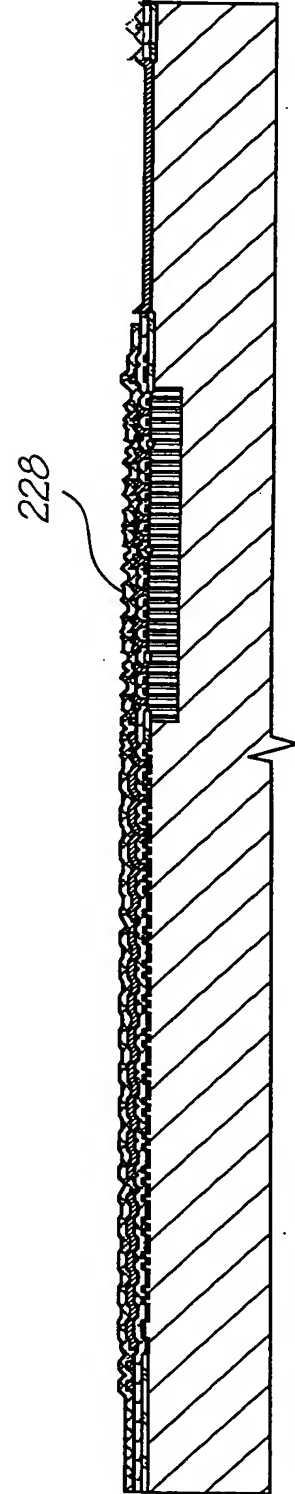


FIG. 39



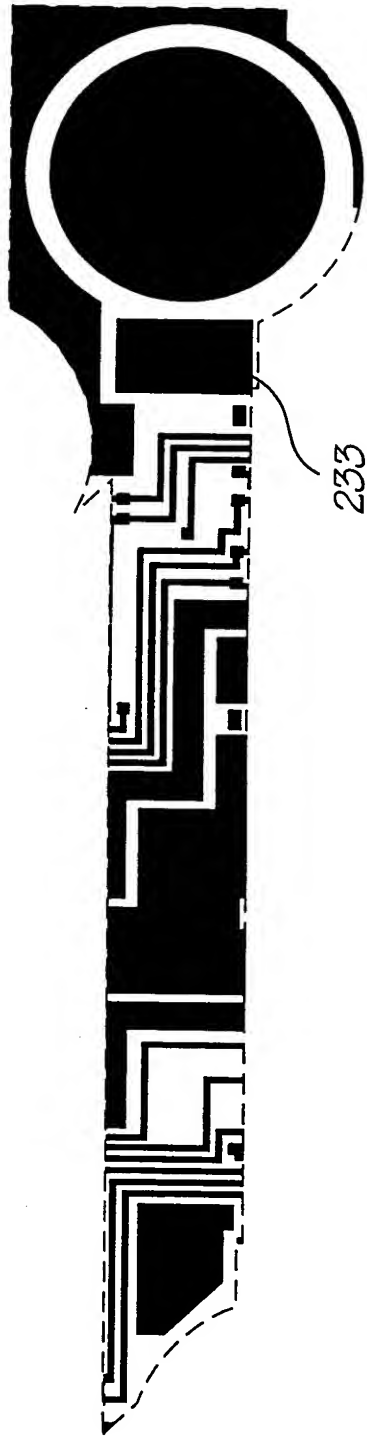
Via 1 mask

FIG. 40



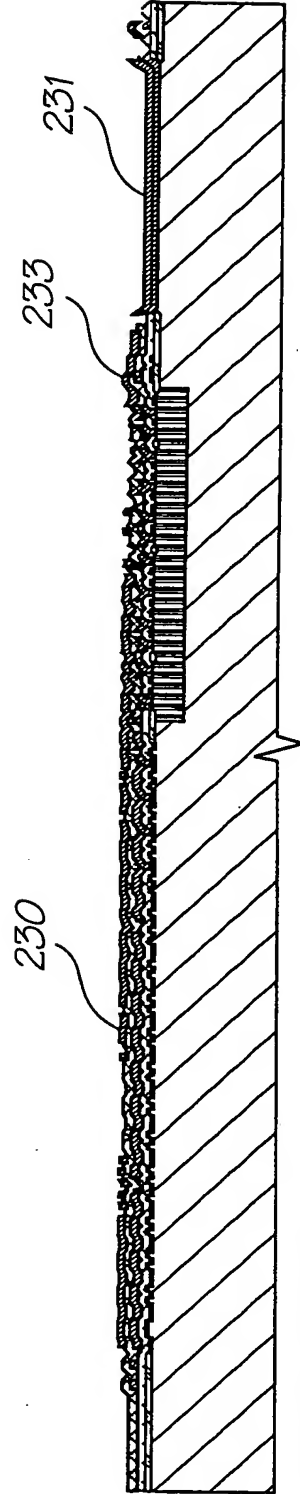
Deposit ILD 2, etch vias

FIG. 41



Metal 2 mask

FIG. 42



Deposit metal 2

FIG. 43

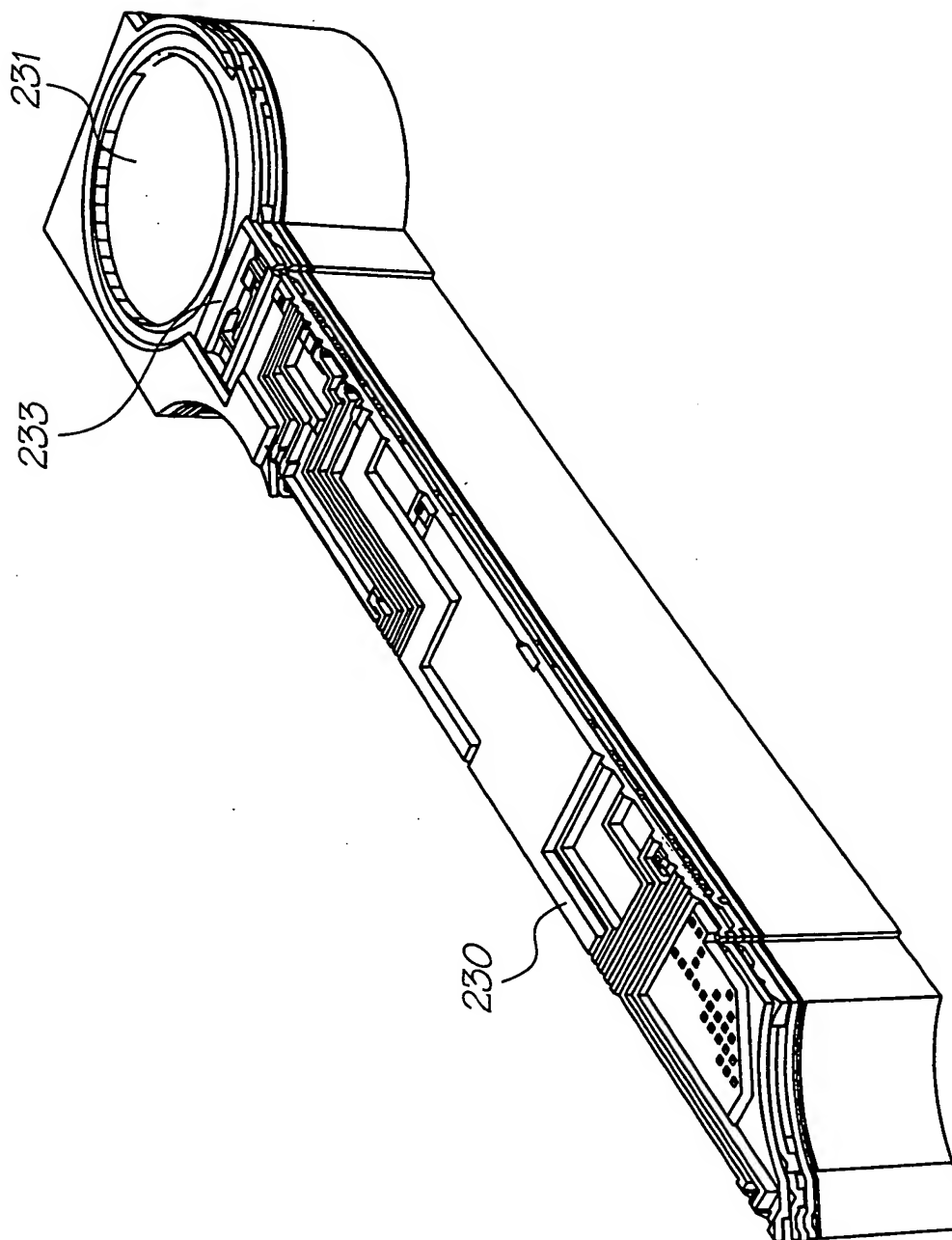
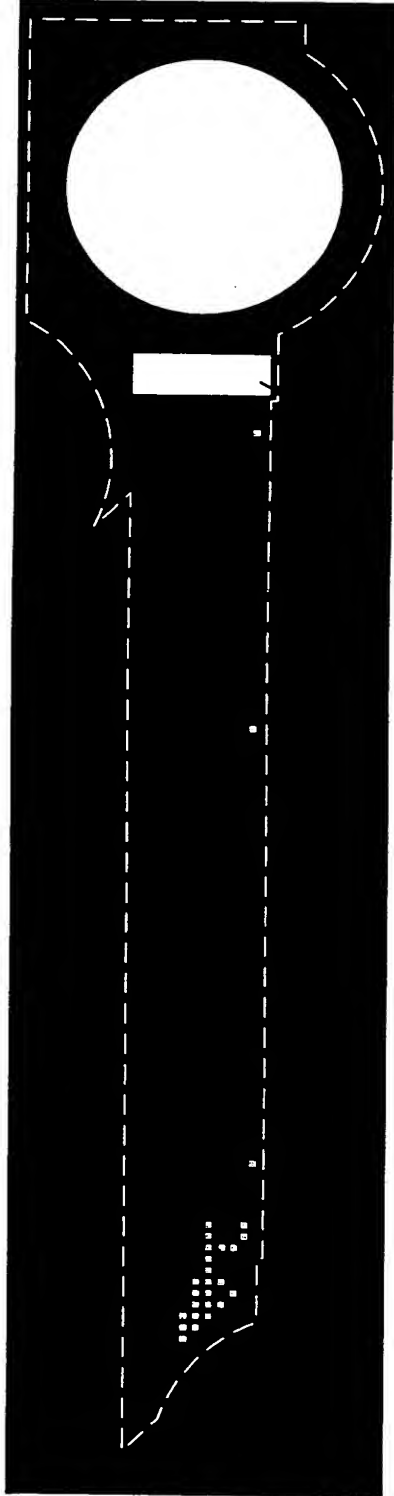
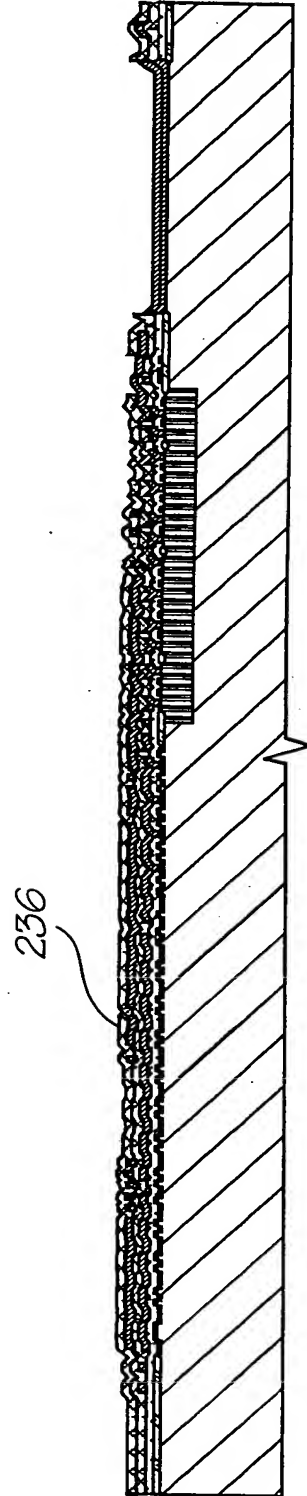


FIG. 44



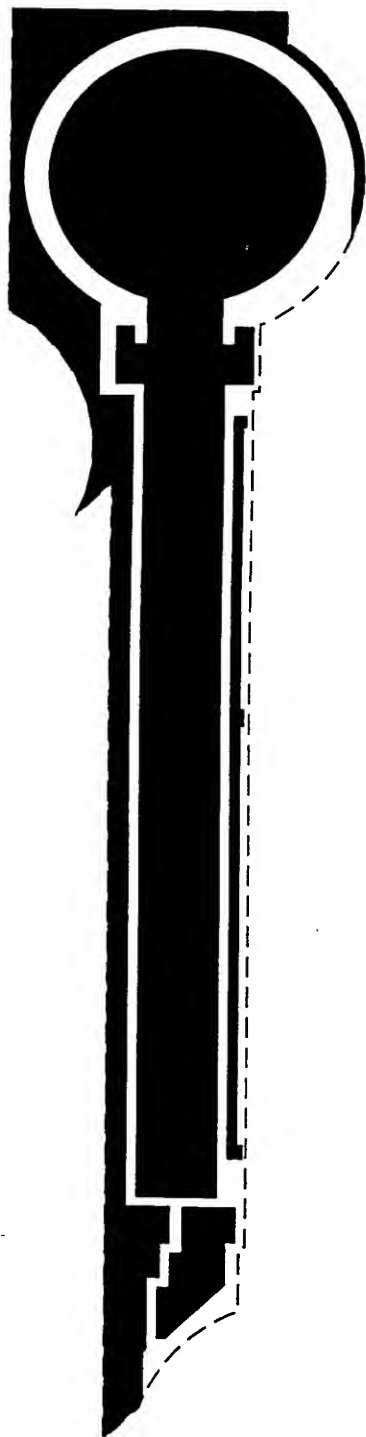
Via 2 mask

FIG. 45



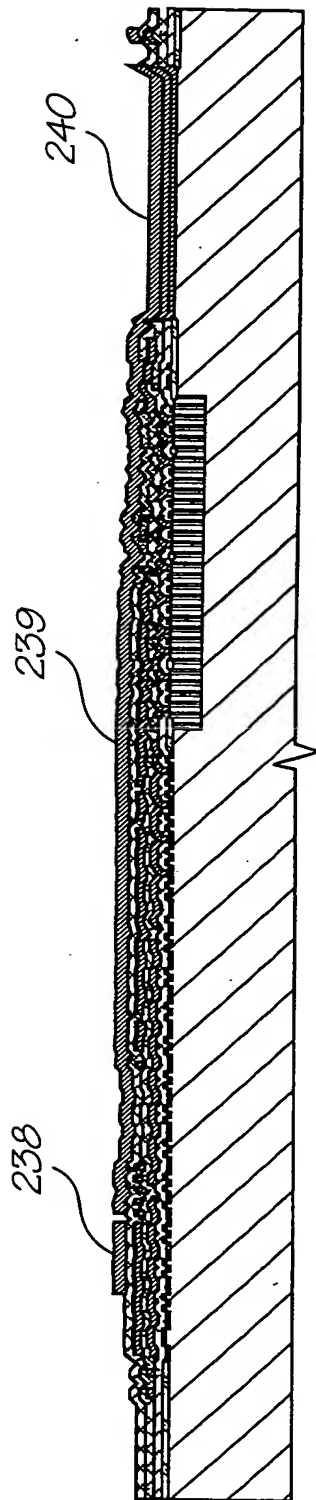
Deposit ILD 3, etch vias

FIG. 46



Metal 3 mask

FIG. 47



Deposit metal 3

FIG. 48

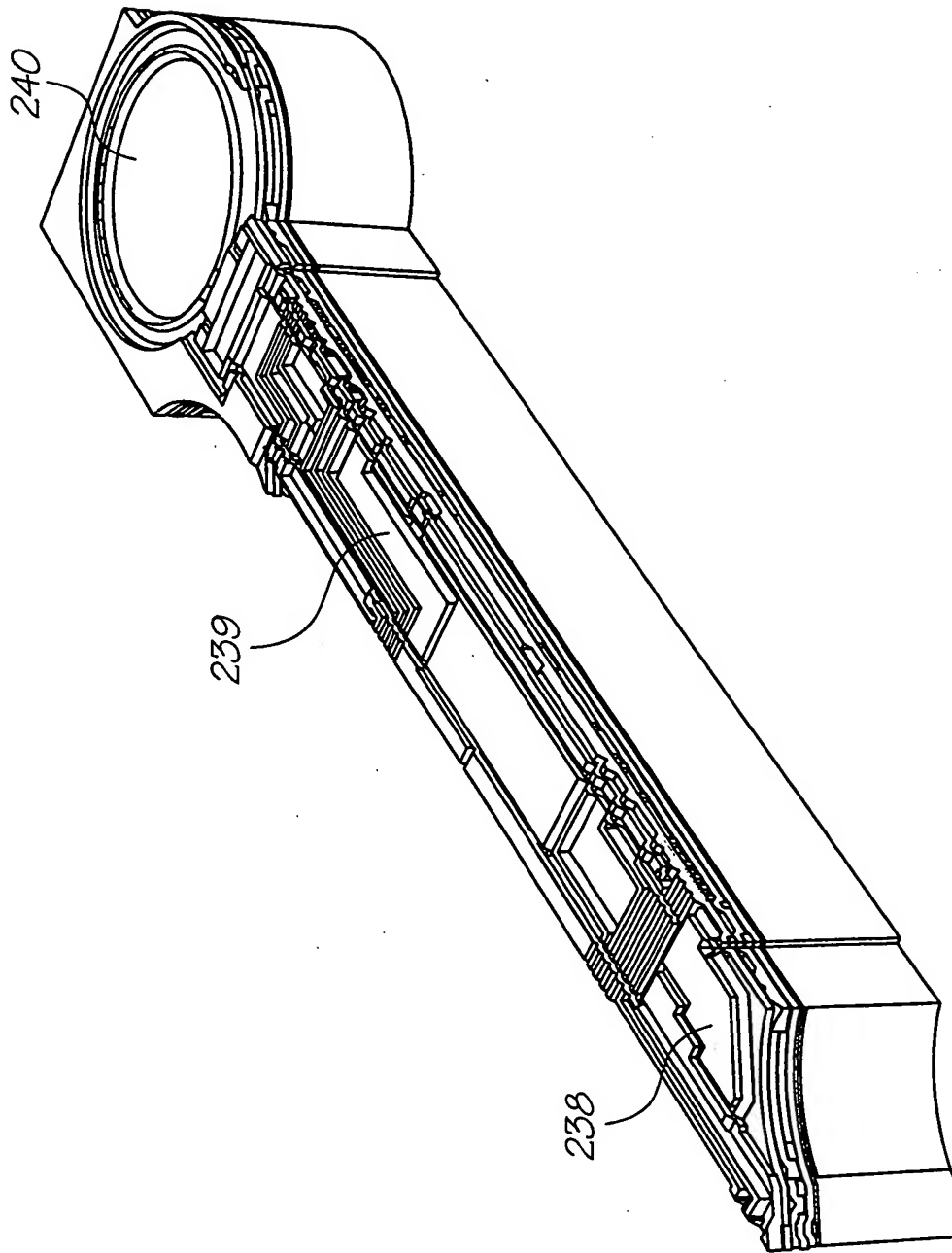
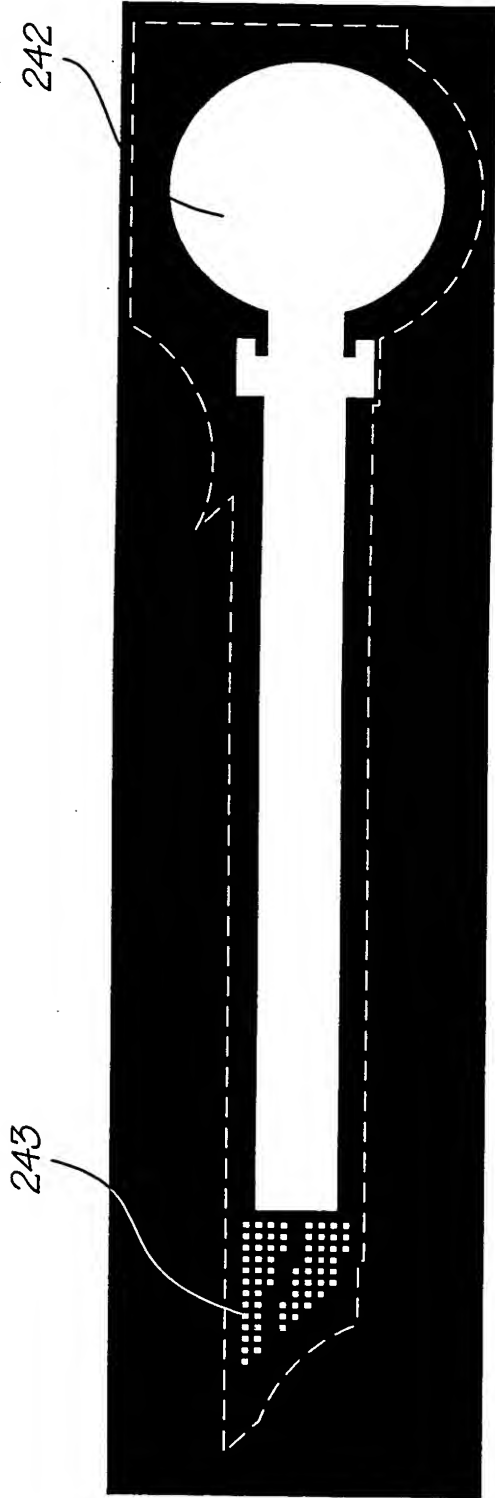


FIG. 49



Via 3 / Passivation mask

FIG. 50

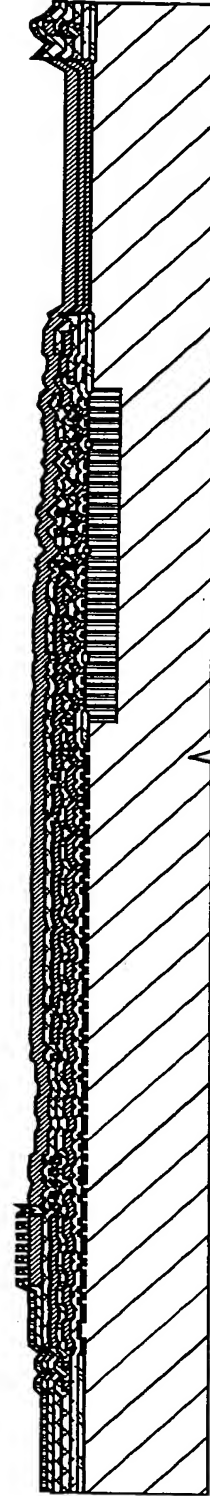


FIG. 51

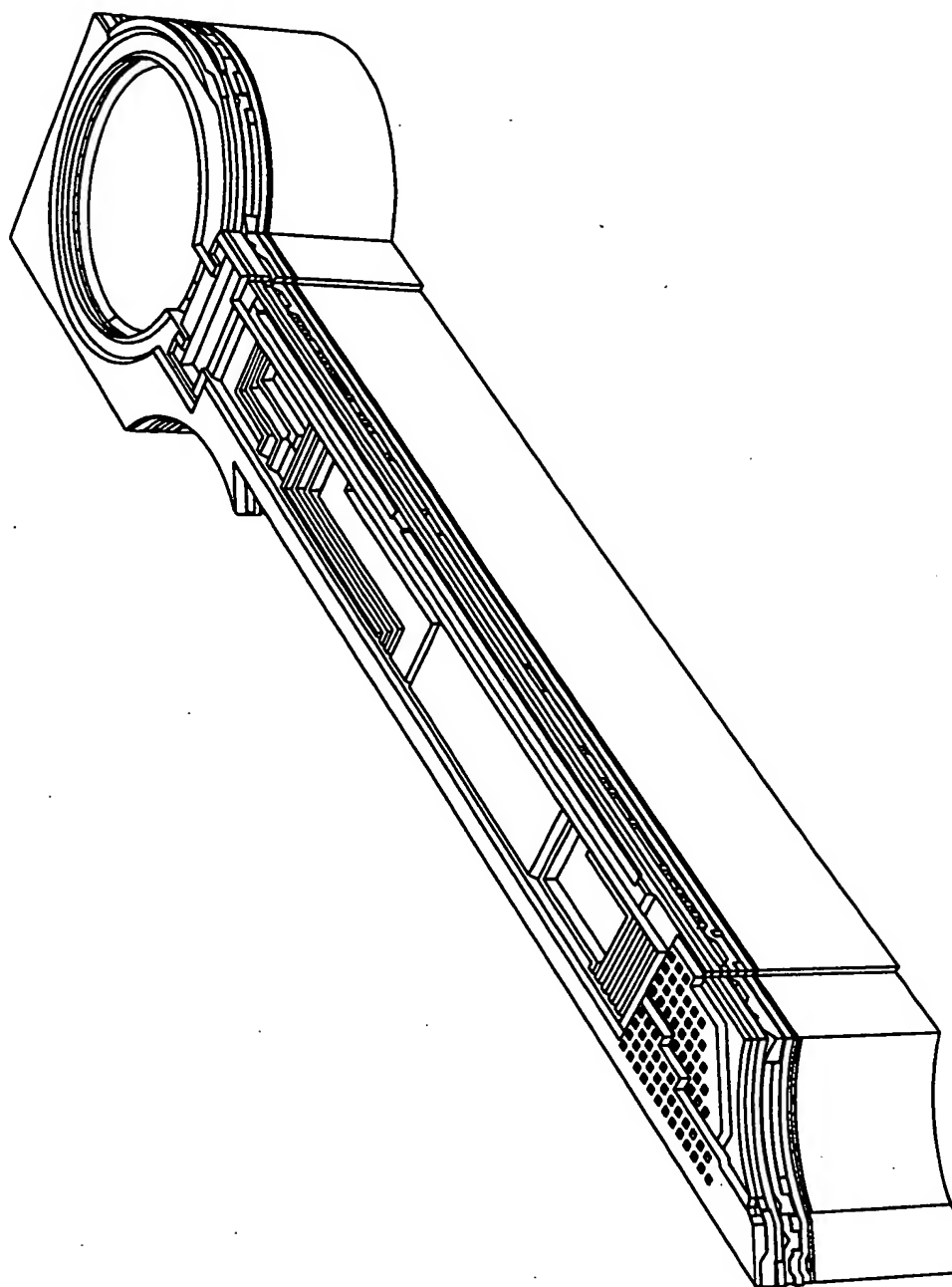
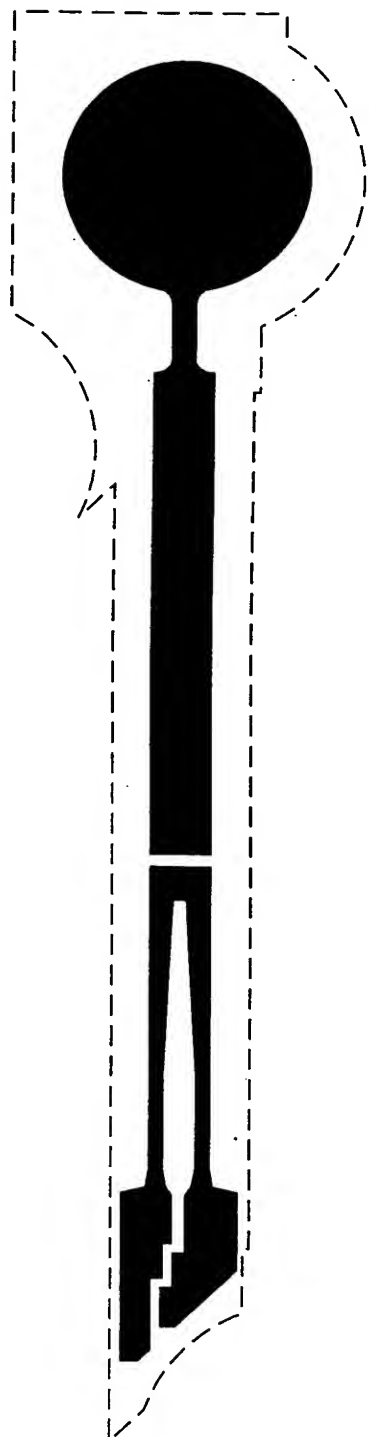
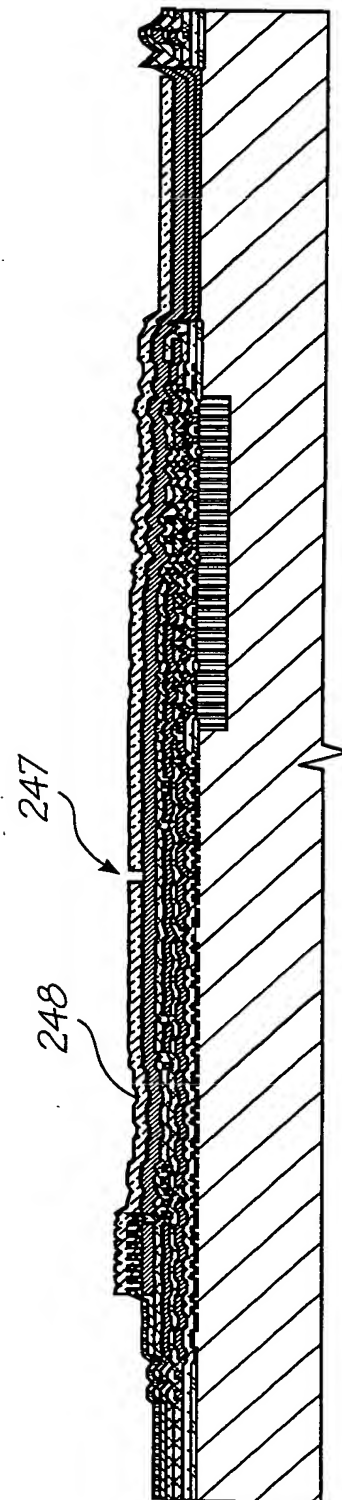


FIG. 52



Heater mask

FIG. 53



Deposit heater TiN

FIG. 54

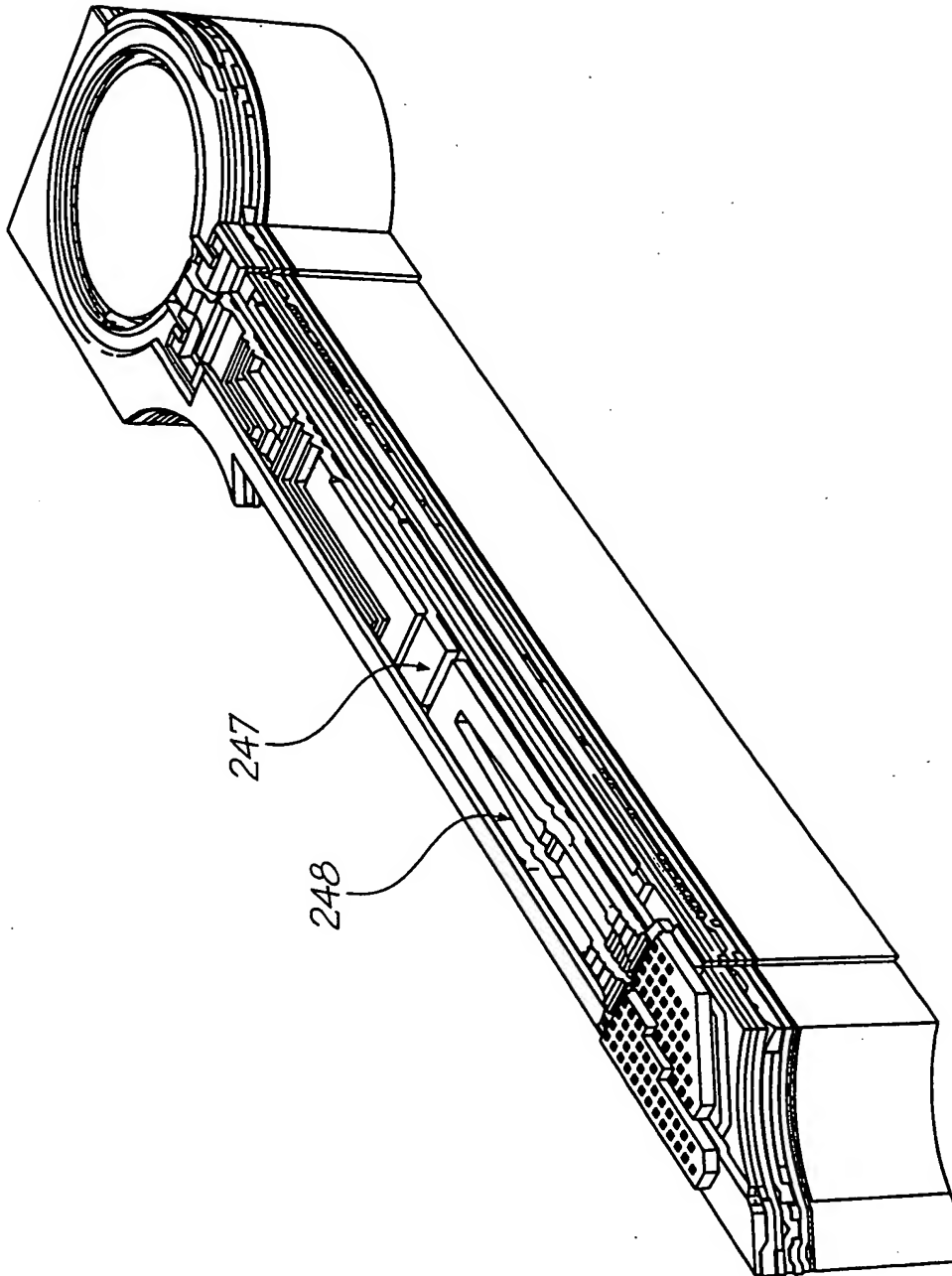
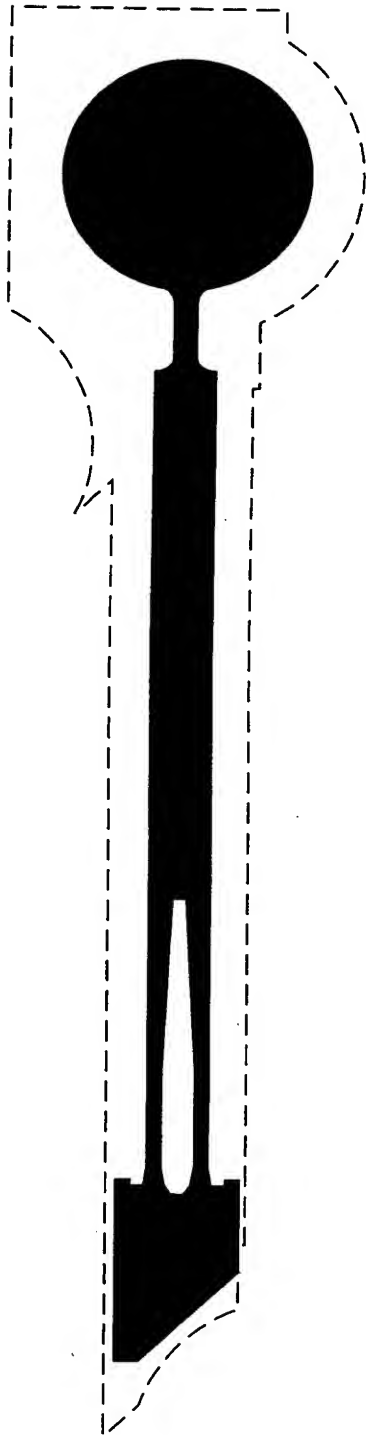
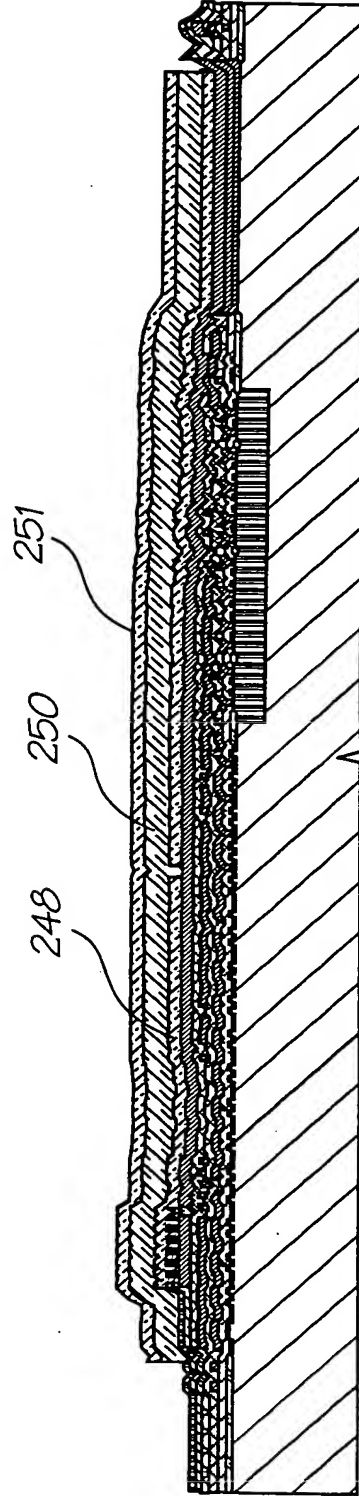


FIG. 55



Actuator / bend compensator mask

FIG. 56



Deposit actuator glass and bend compensator TiN, etch together

FIG. 57

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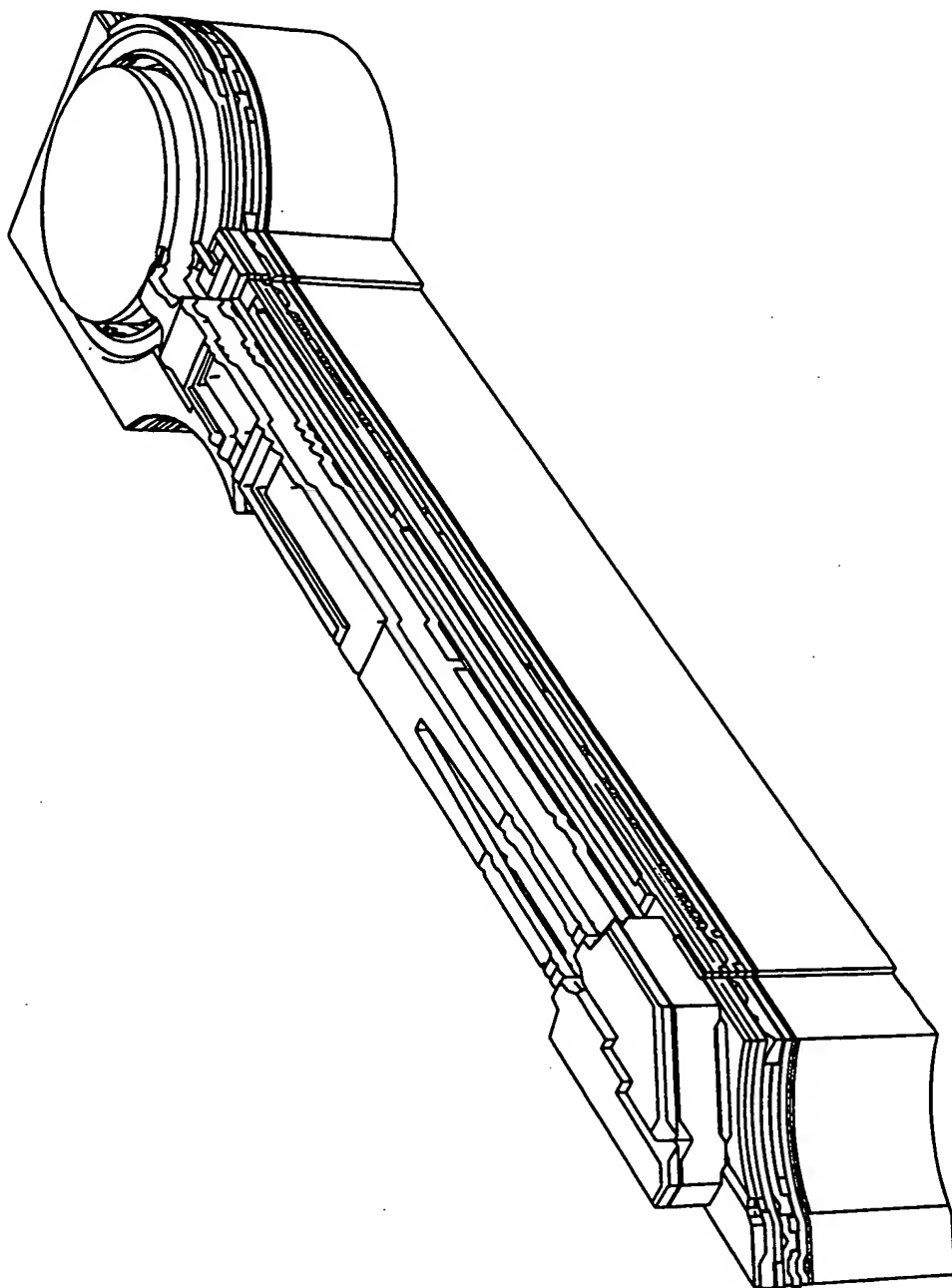
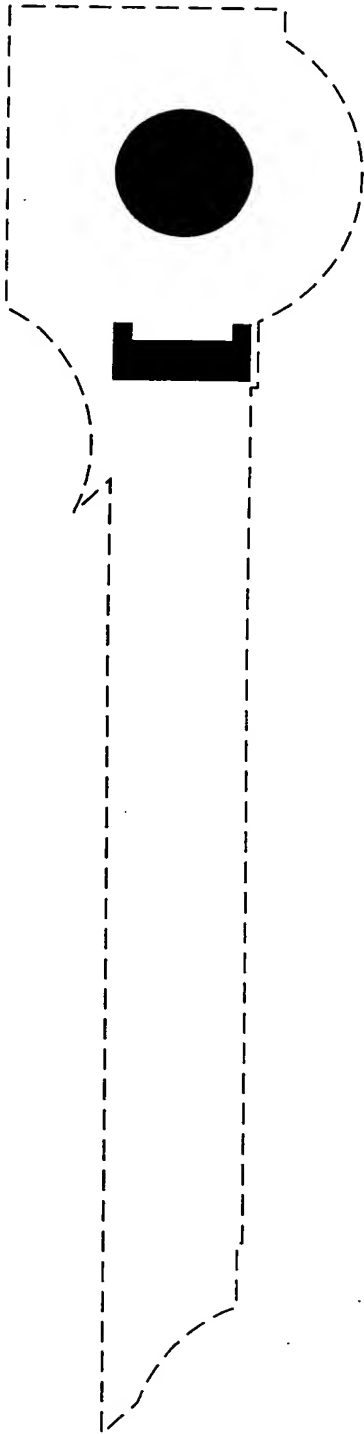
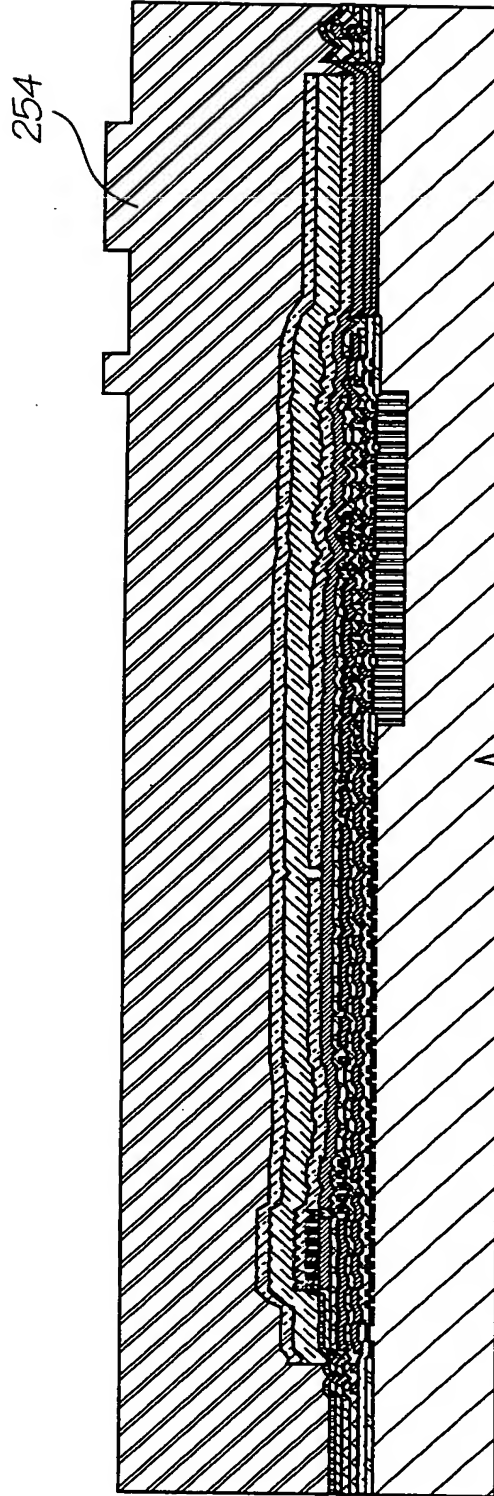


FIG. 58



Nozzle mask

FIG. 59



Deposit sacrificial layer, etch nozzles

FIG. 60

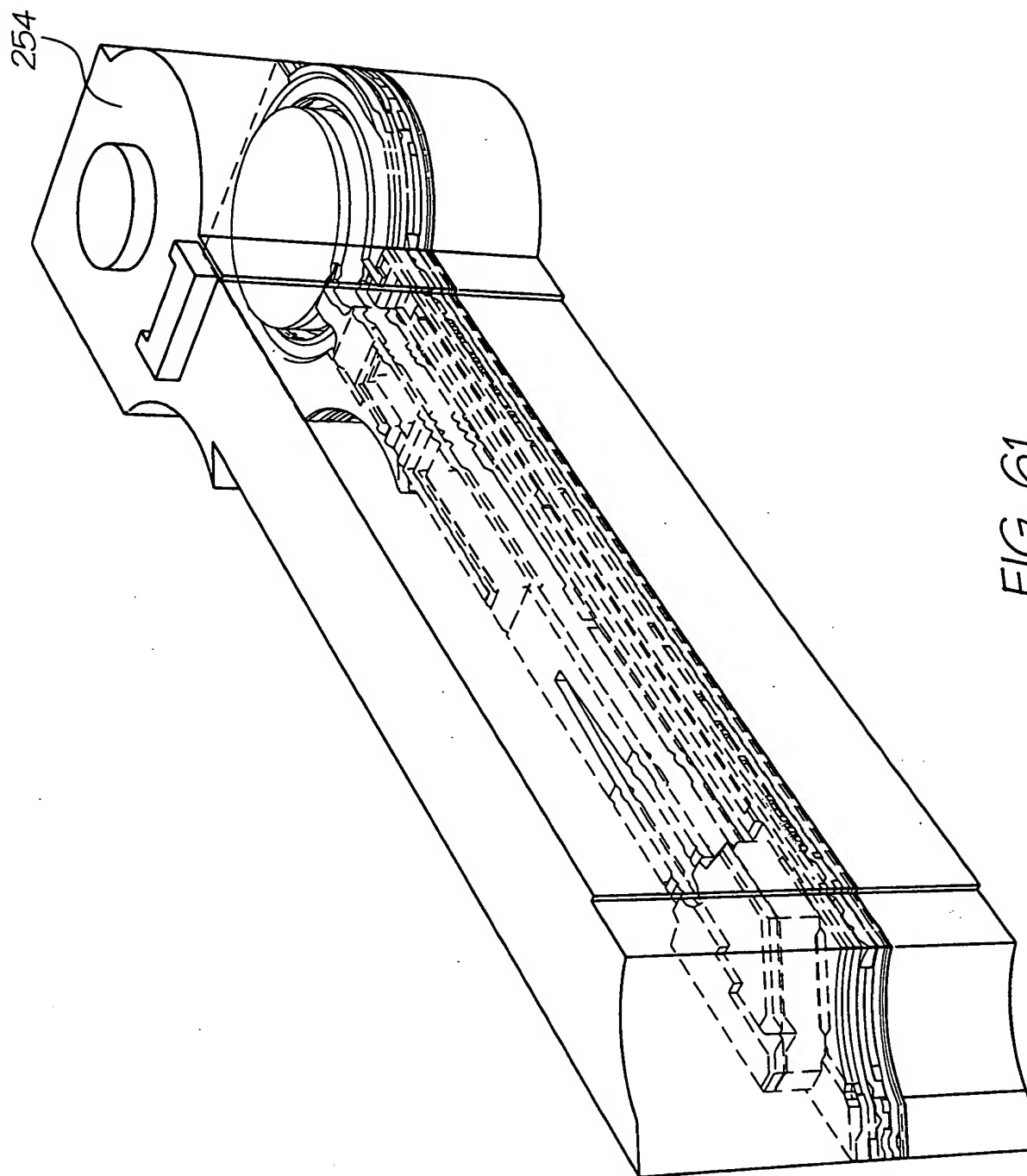
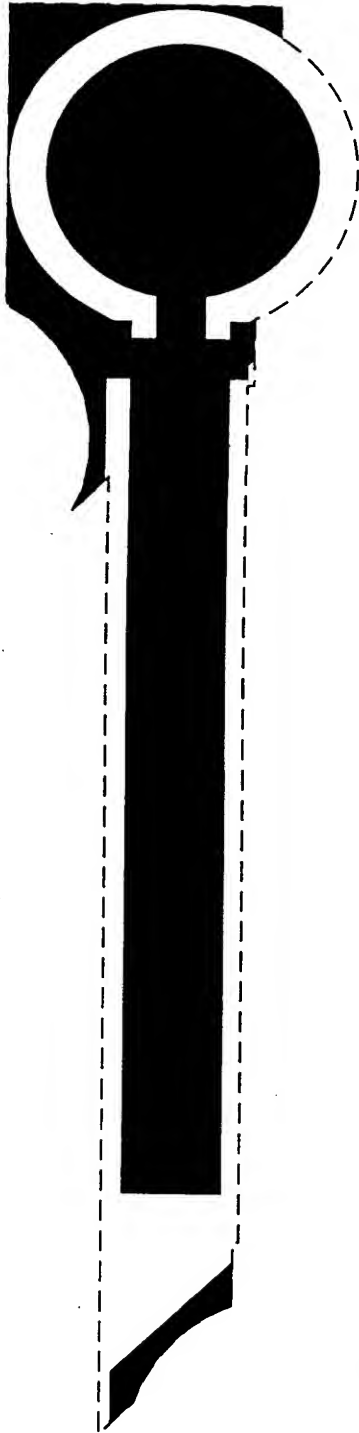
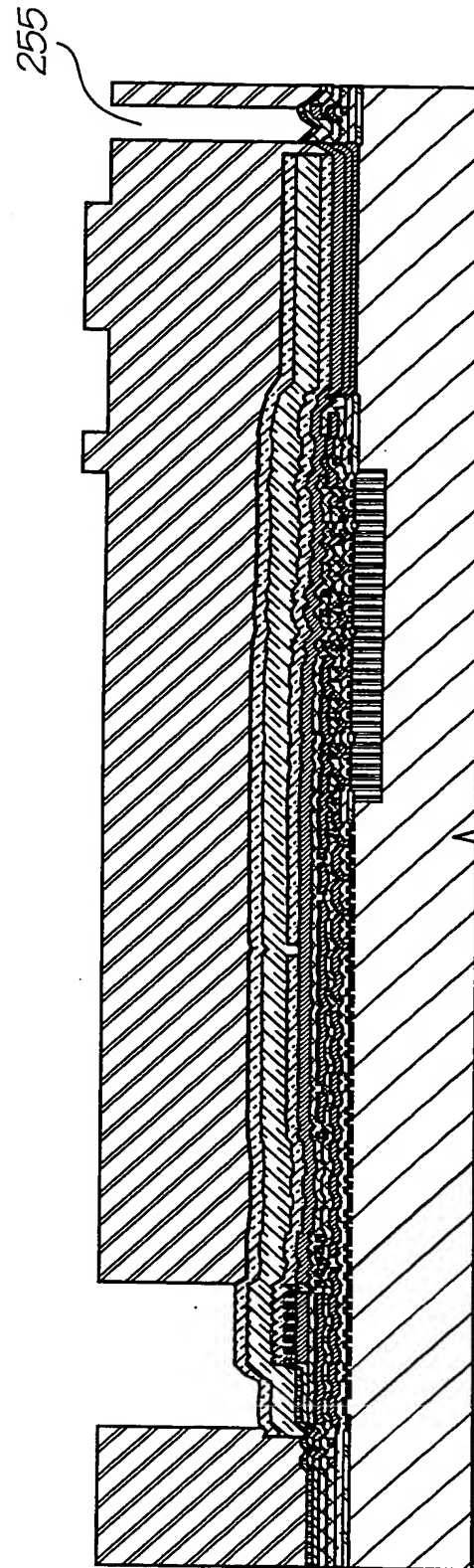


FIG. 61



Chamber mask

FIG. 62



Etch chambers in sacrificial layer

FIG. 63

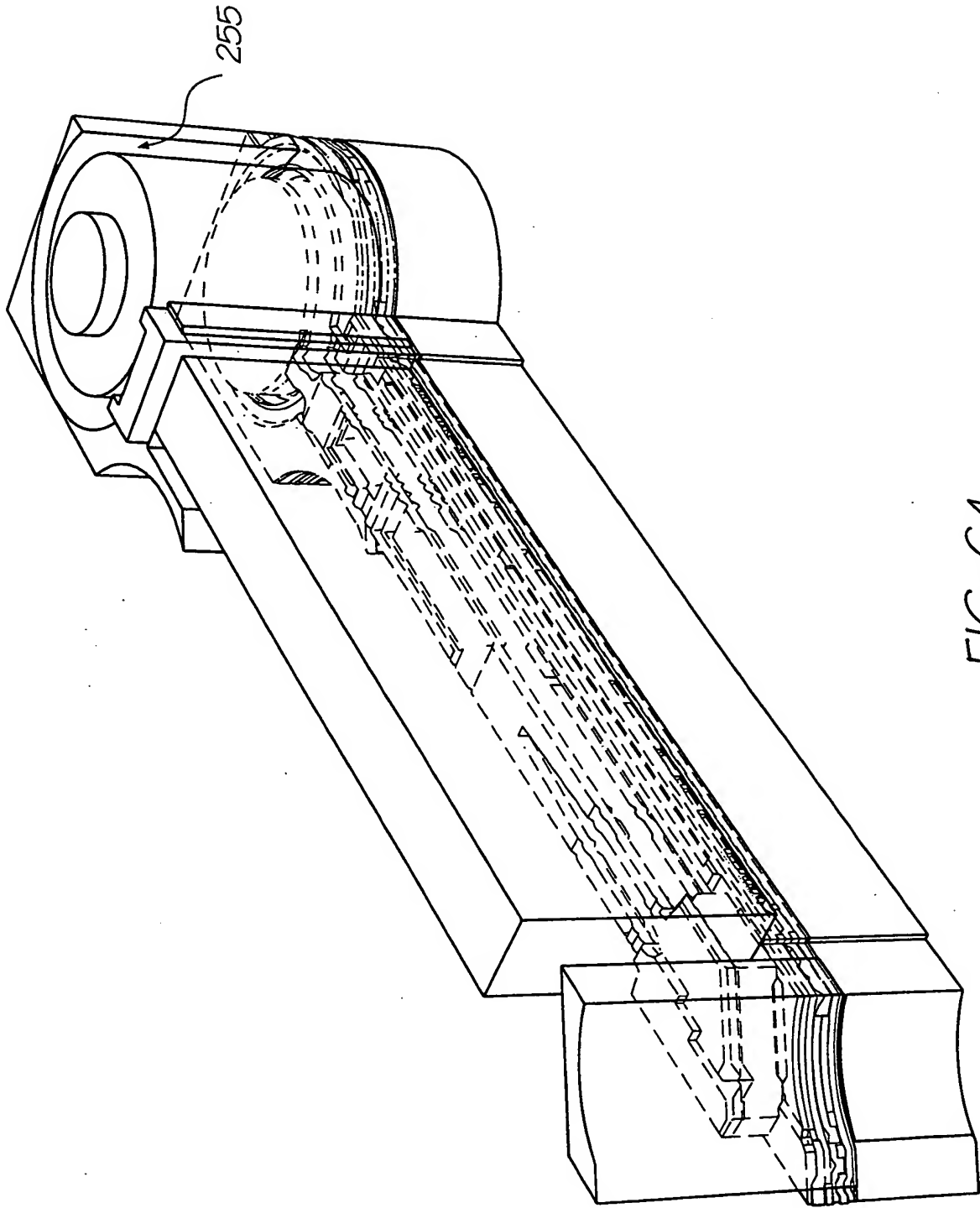


FIG. 64

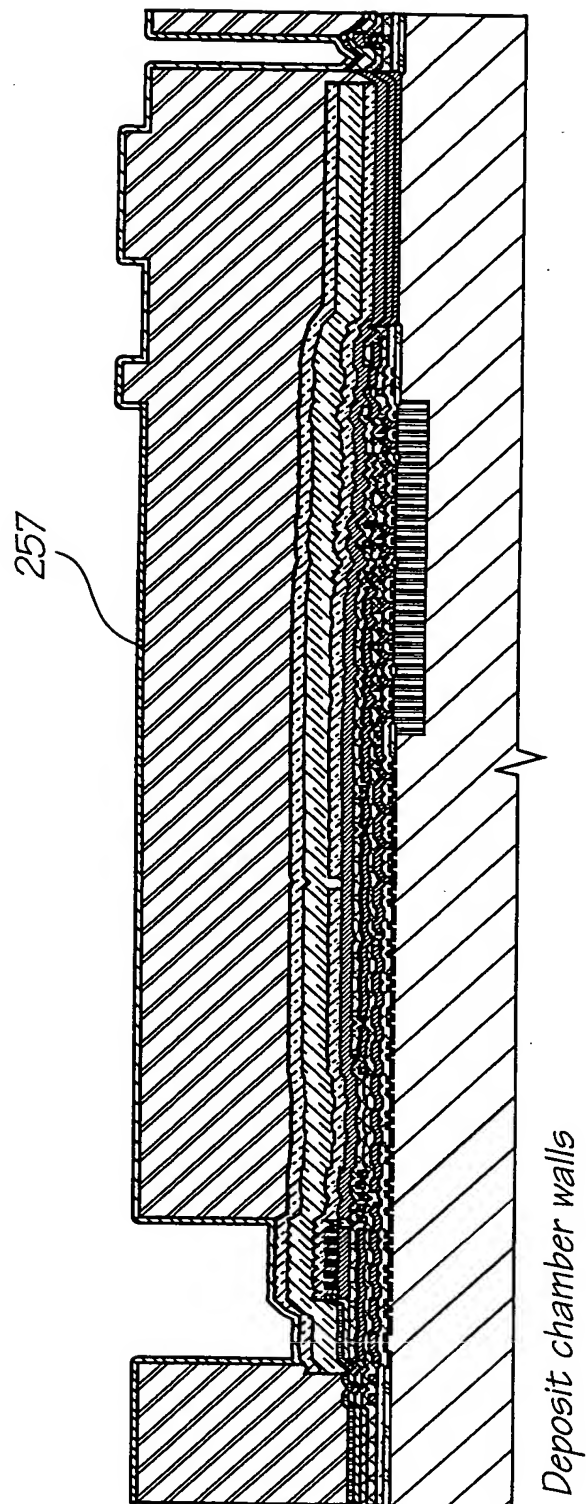


FIG. 65

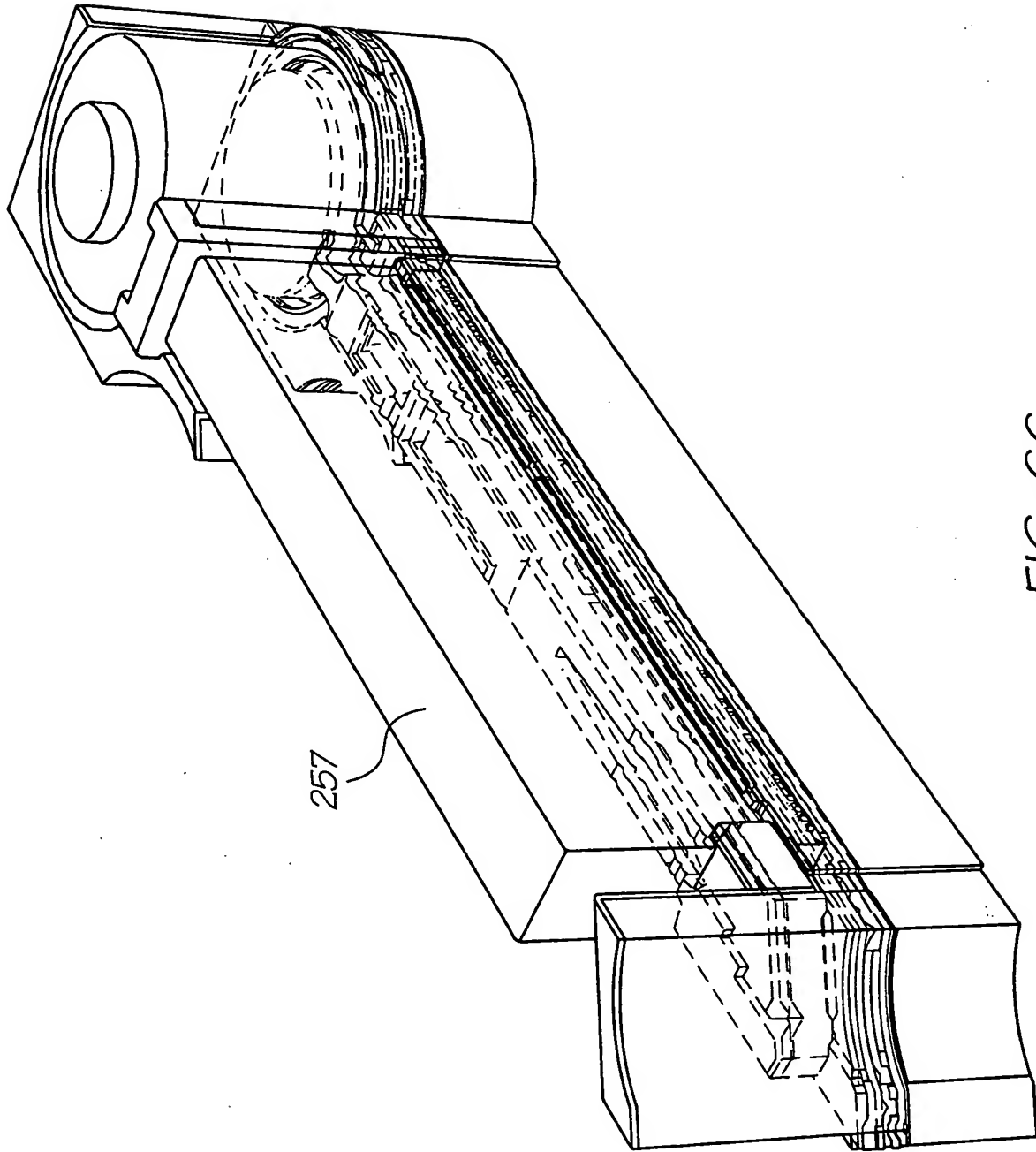
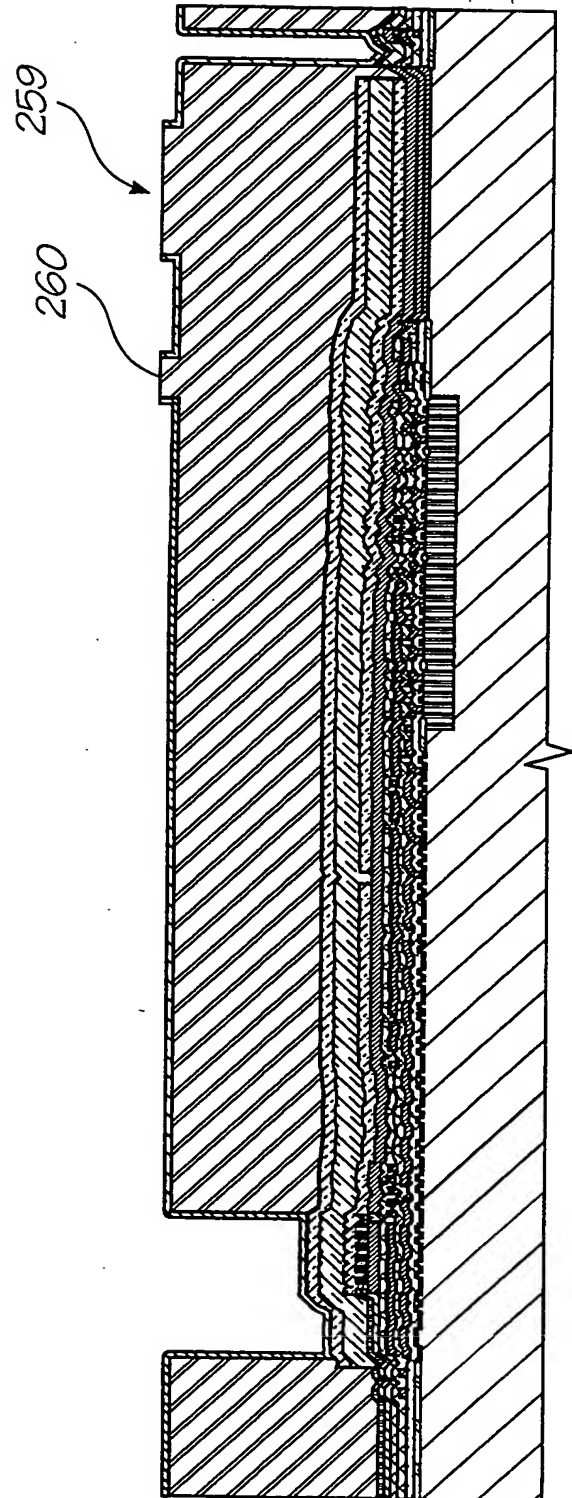


FIG. 66



Form self-aligned nozzles using CMP

FIG. 67

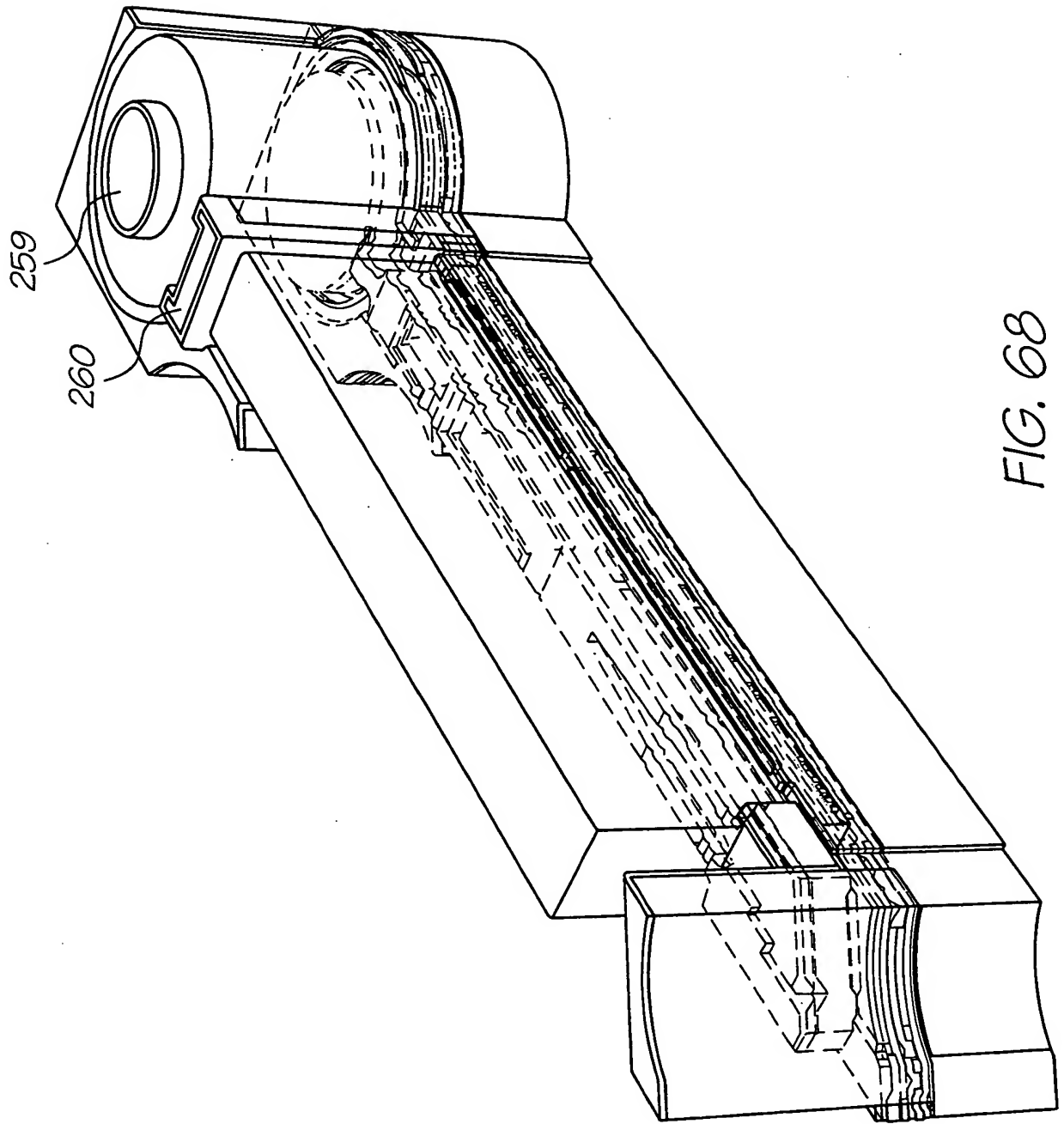
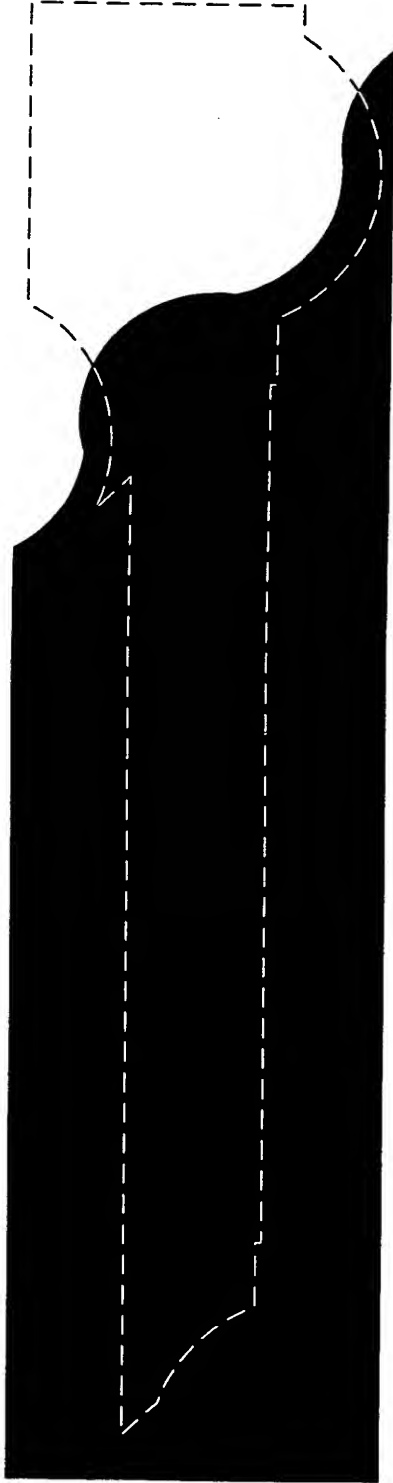
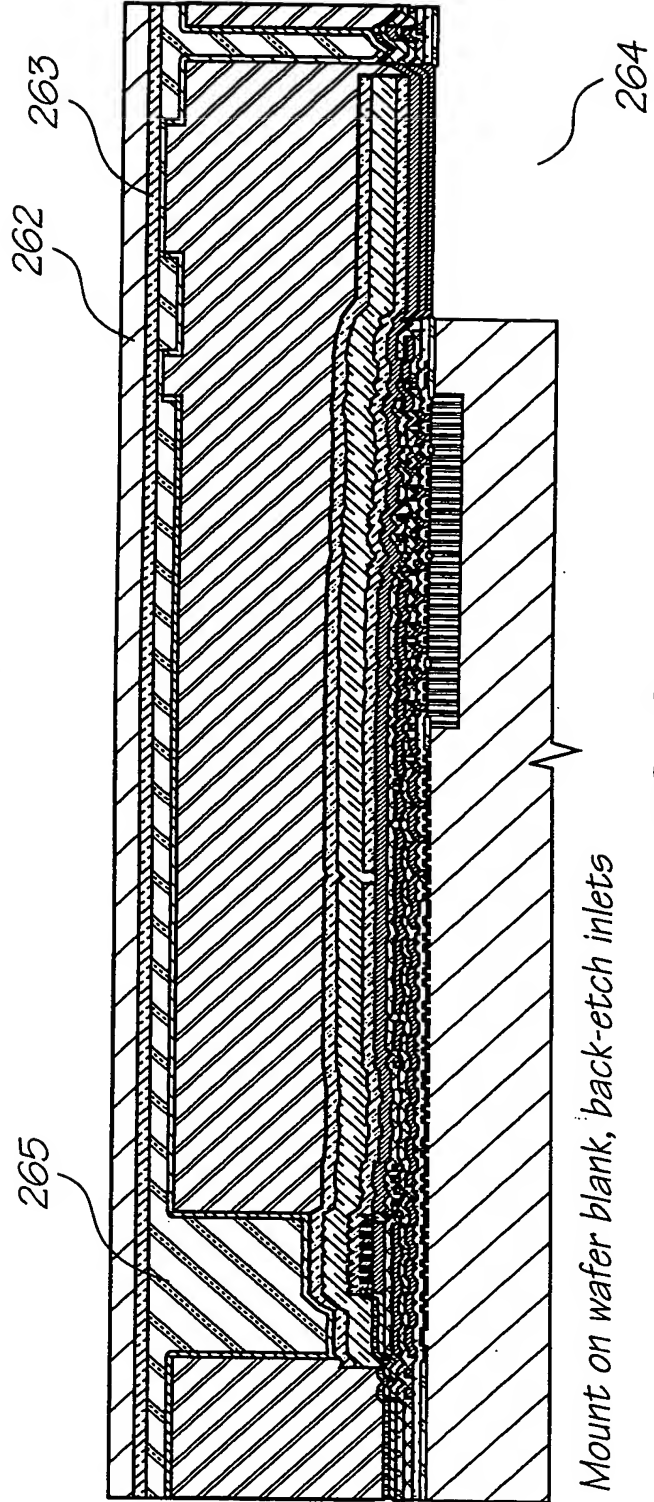


FIG. 68



Back-etch inlet mask

FIG. 70



Mount on wafer blank, back-etch inlets

FIG. 69

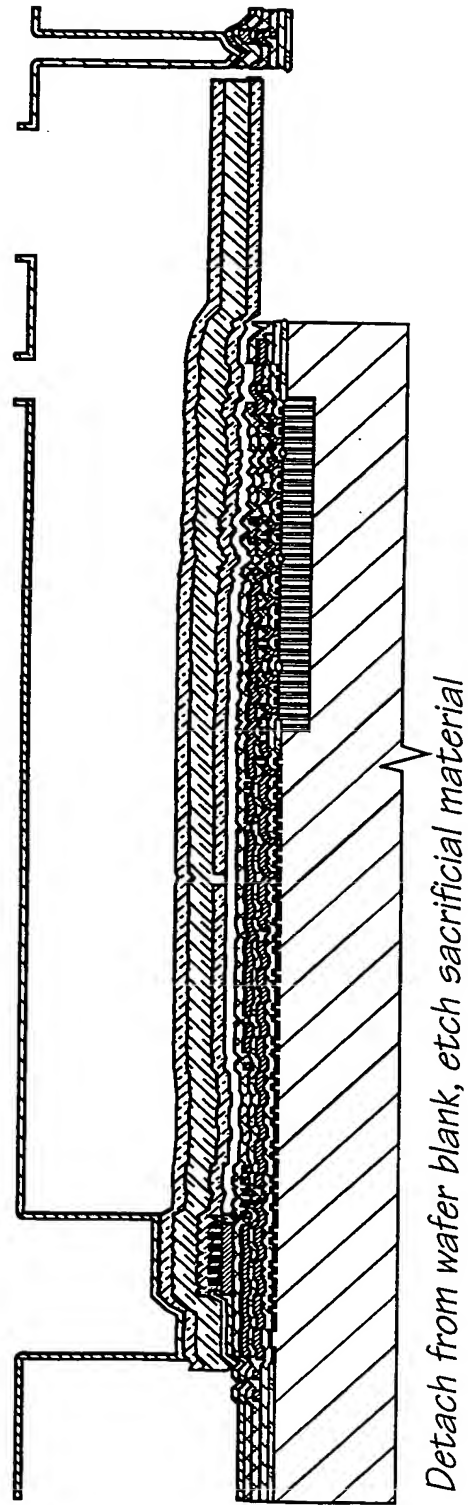


FIG. 71

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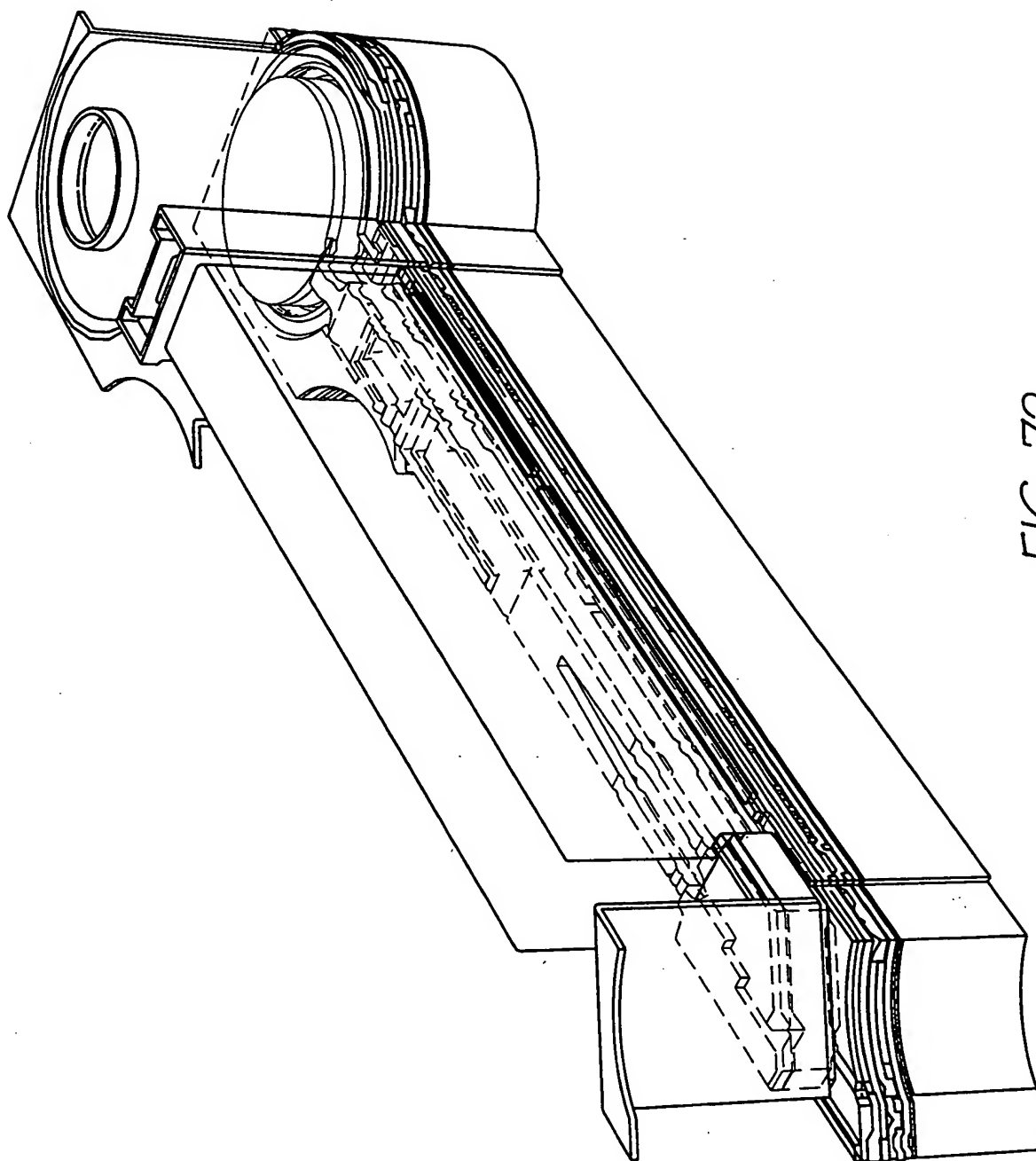


FIG. 72

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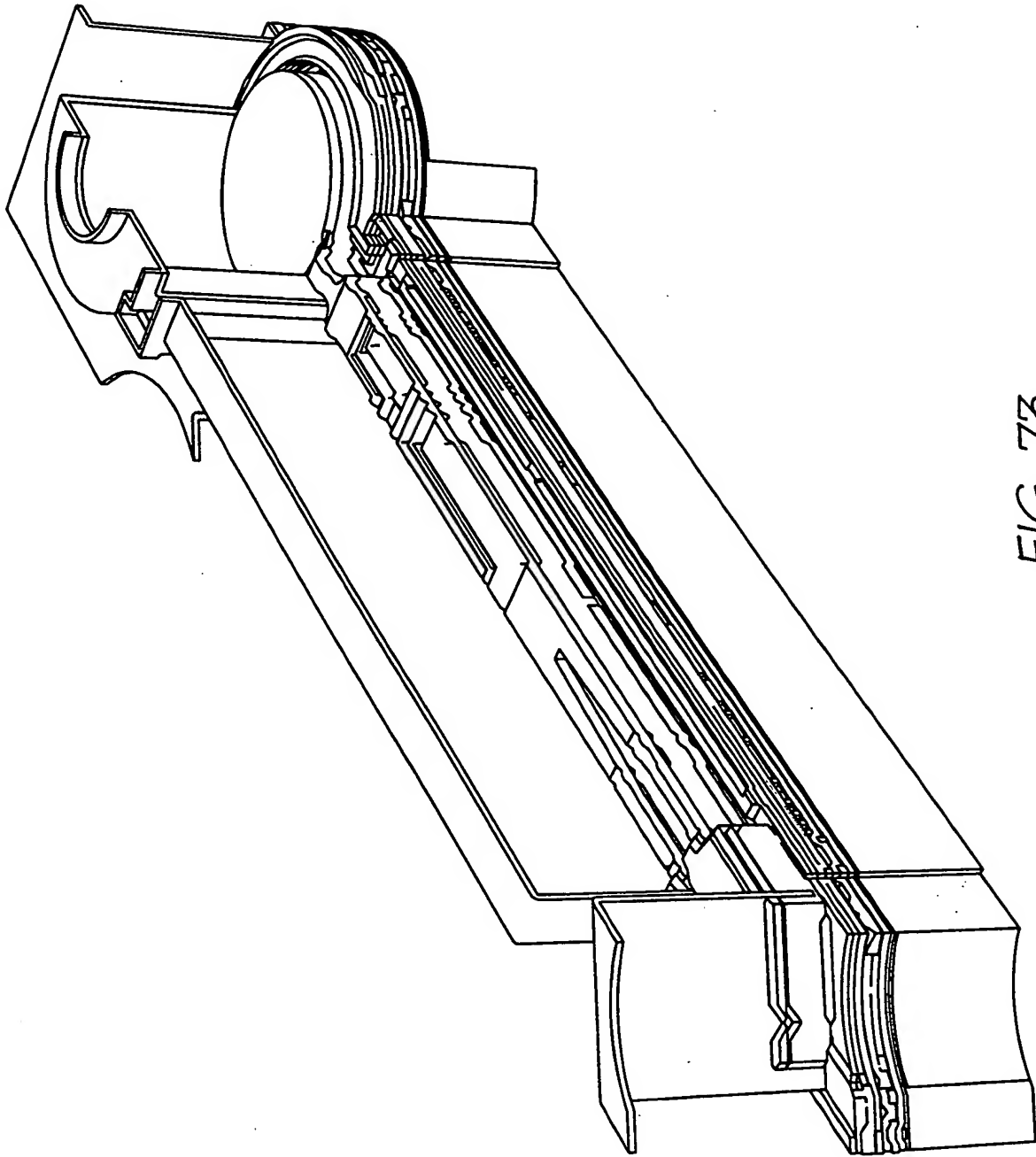


FIG. 73

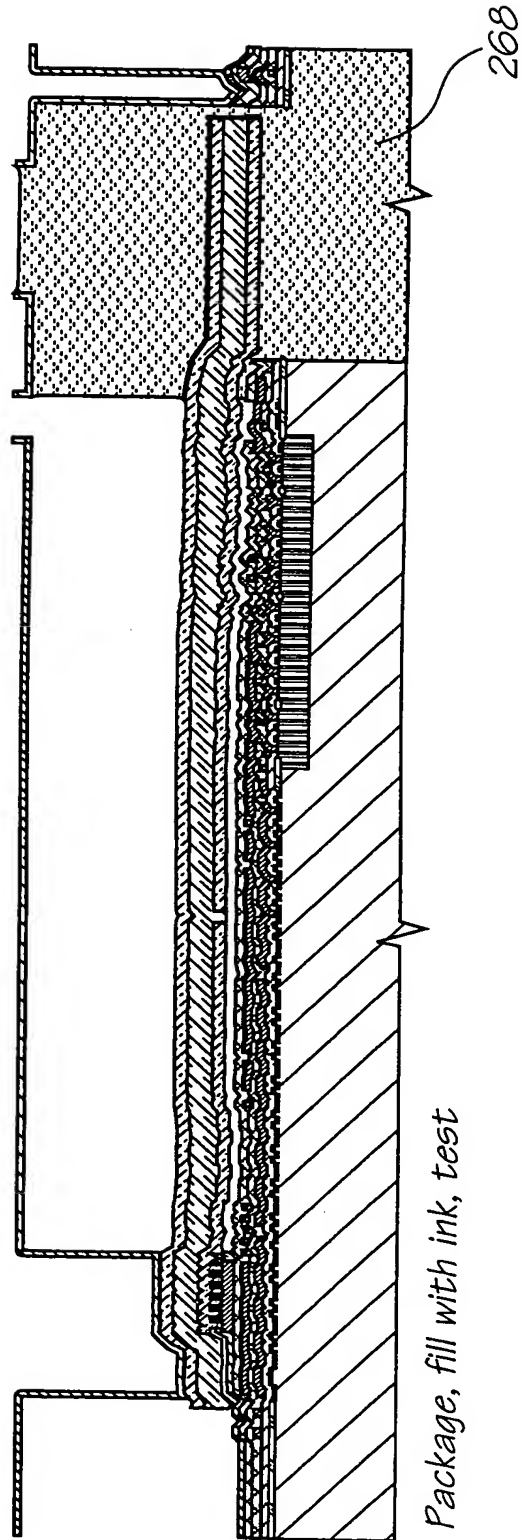


FIG. 74

4-24-50



FIG. 75

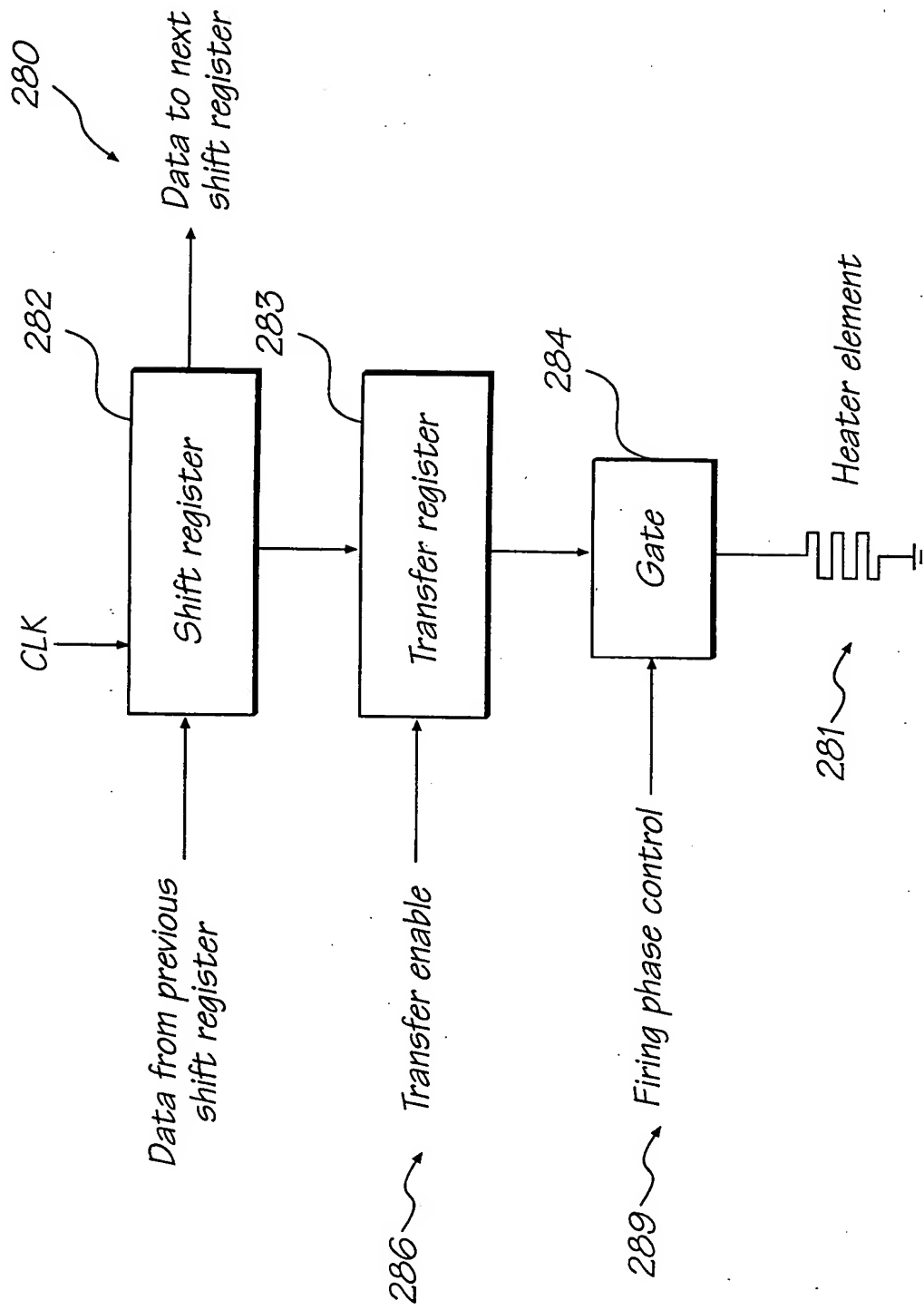


FIG. 76

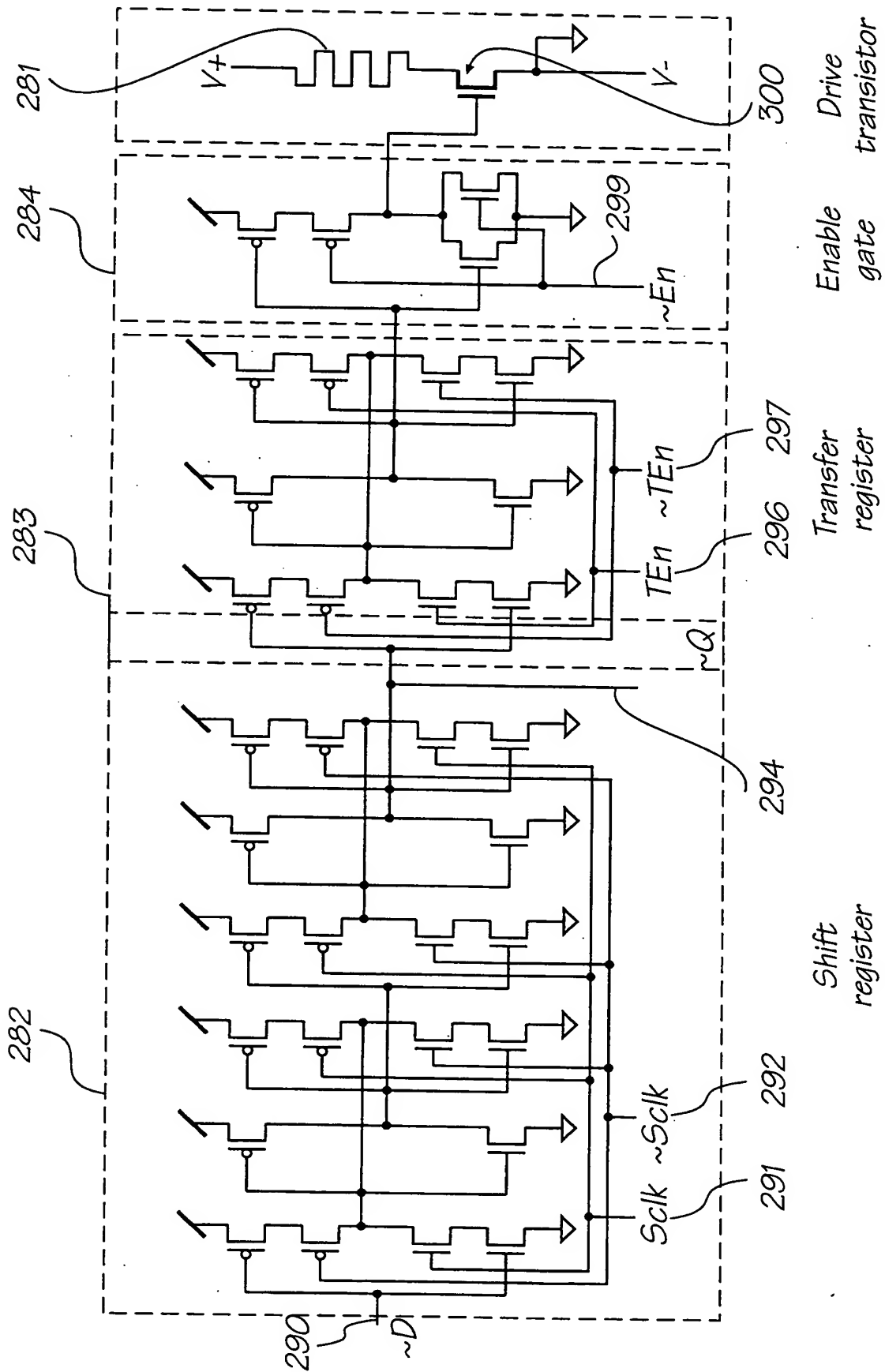


FIG. 77

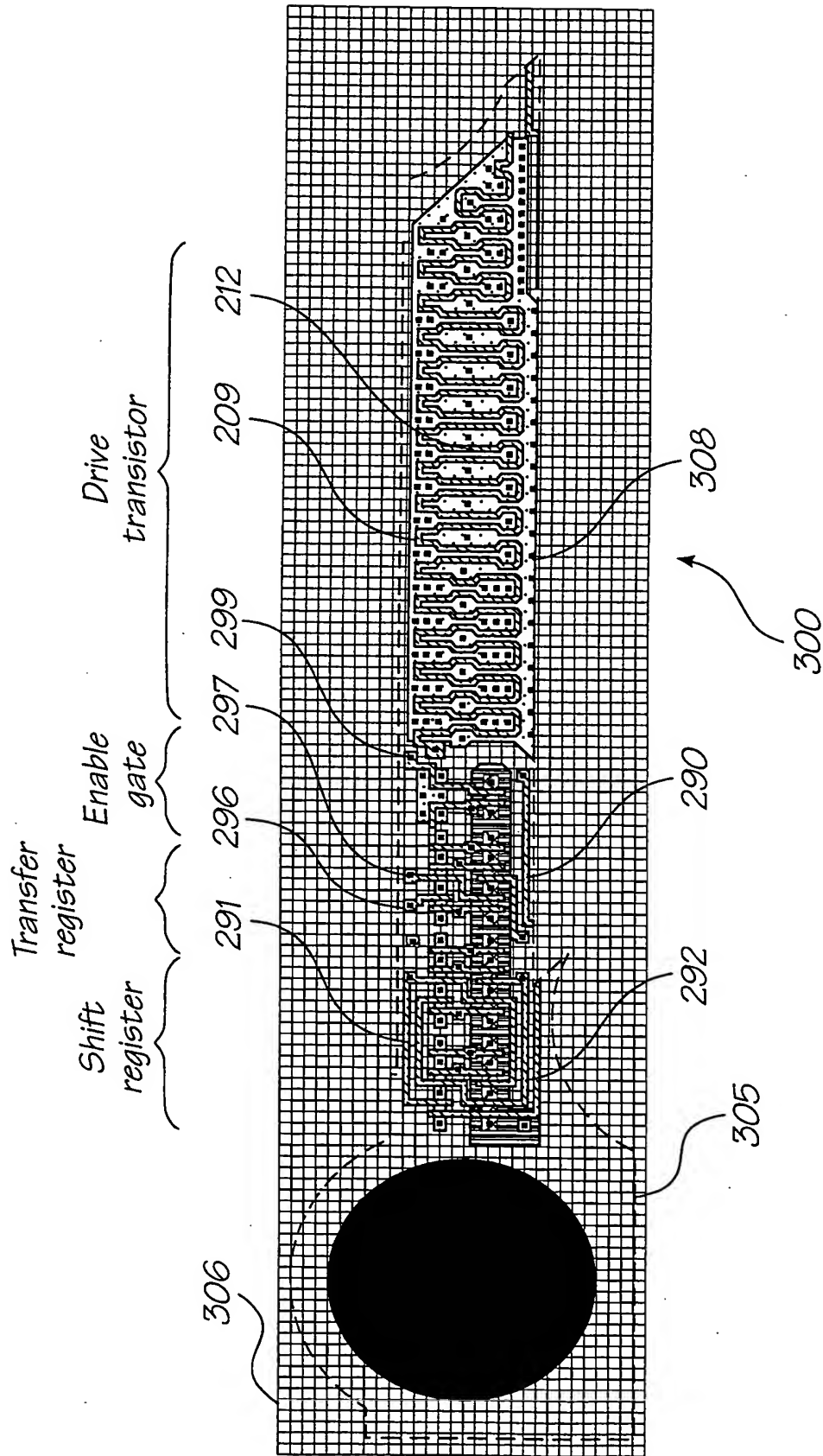


FIG. 79

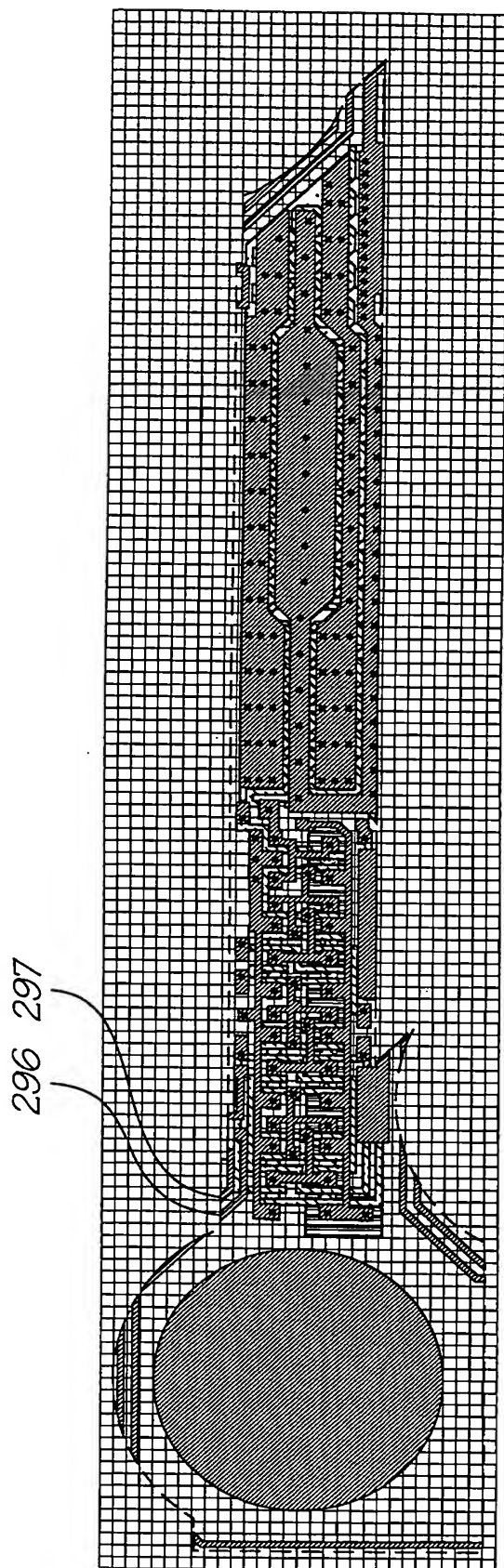


FIG. 80

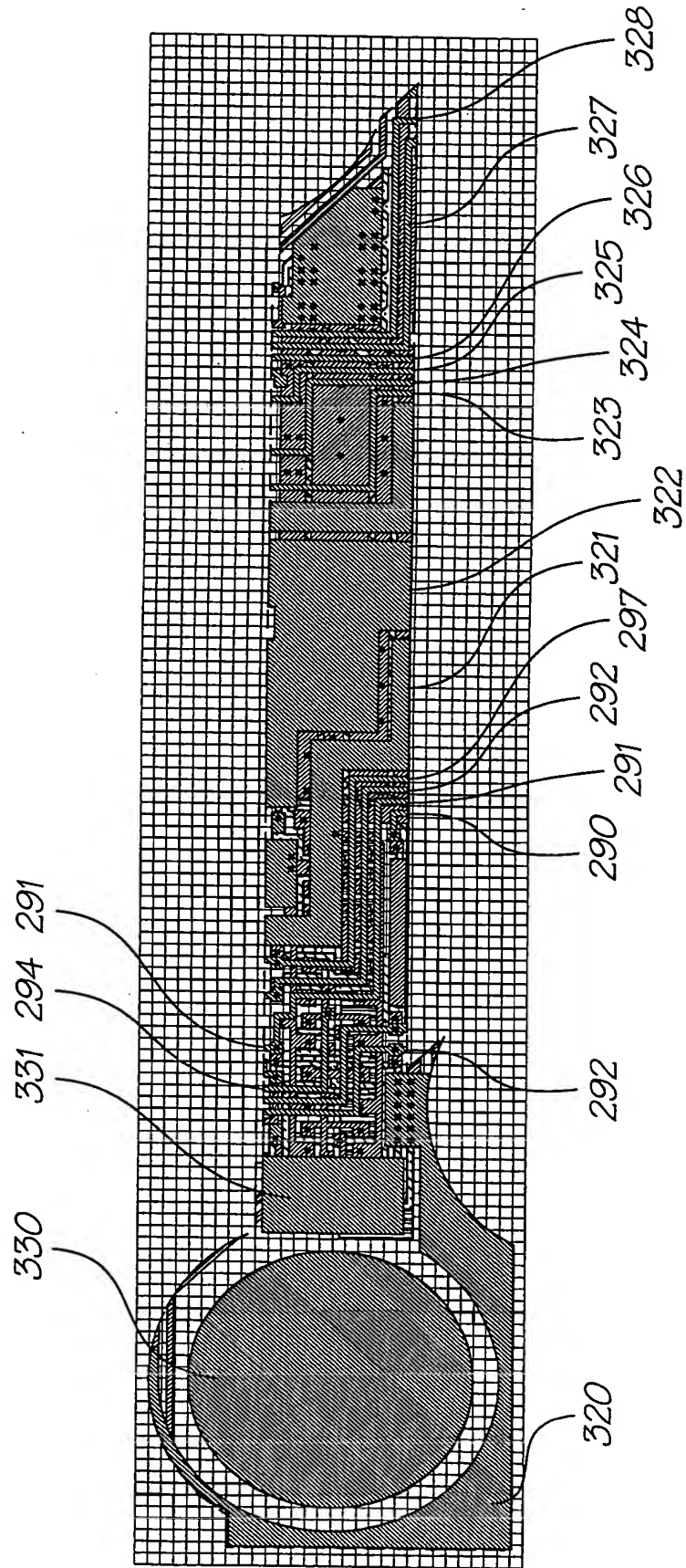


FIG. 81

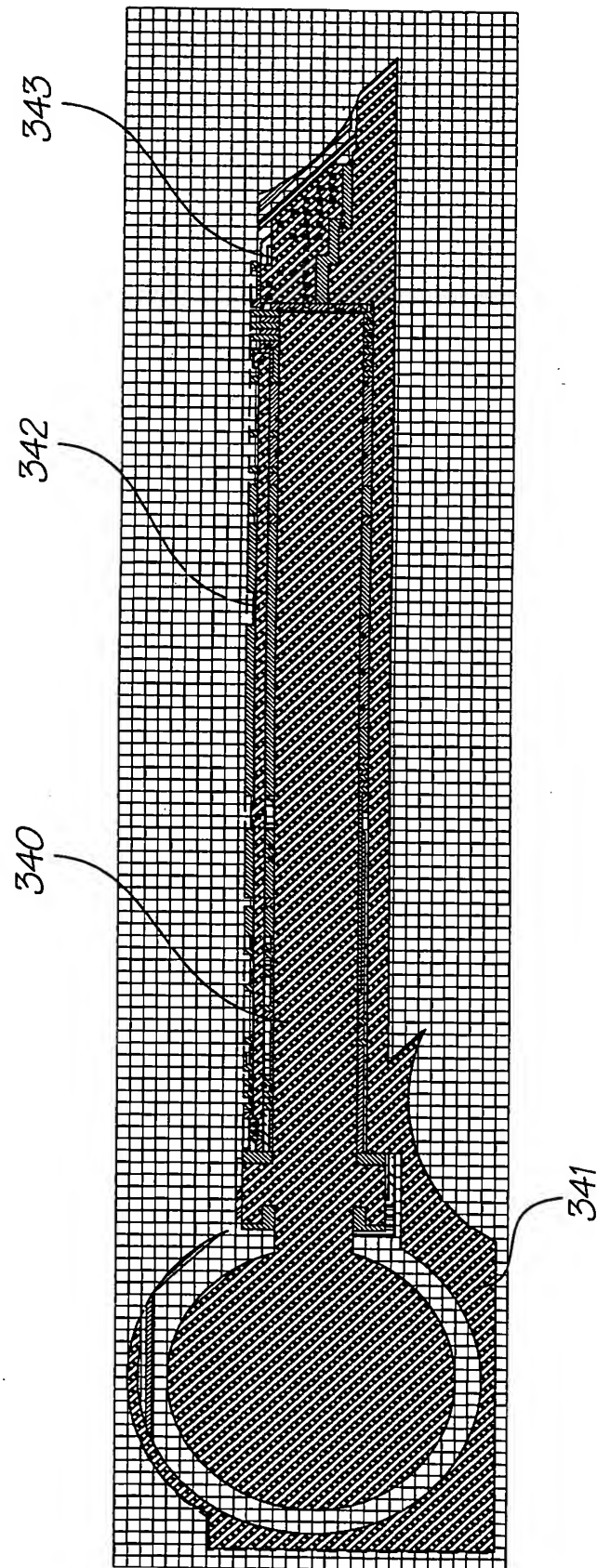


FIG. 82

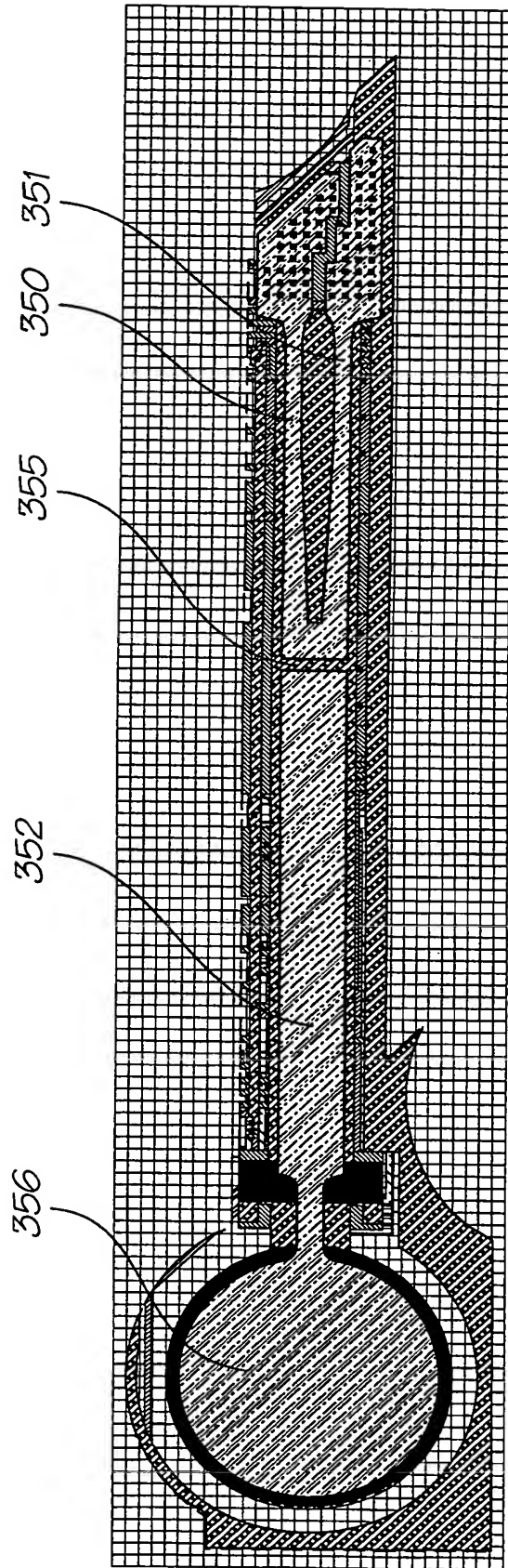


FIG. 83

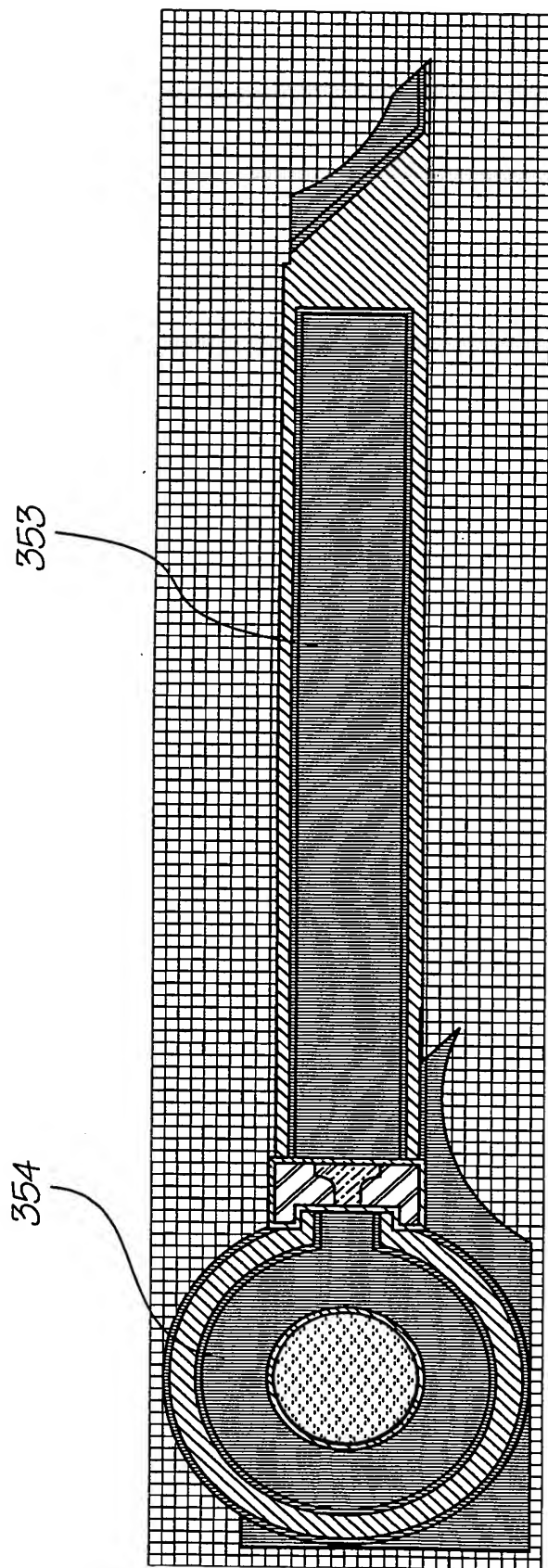


FIG. 84

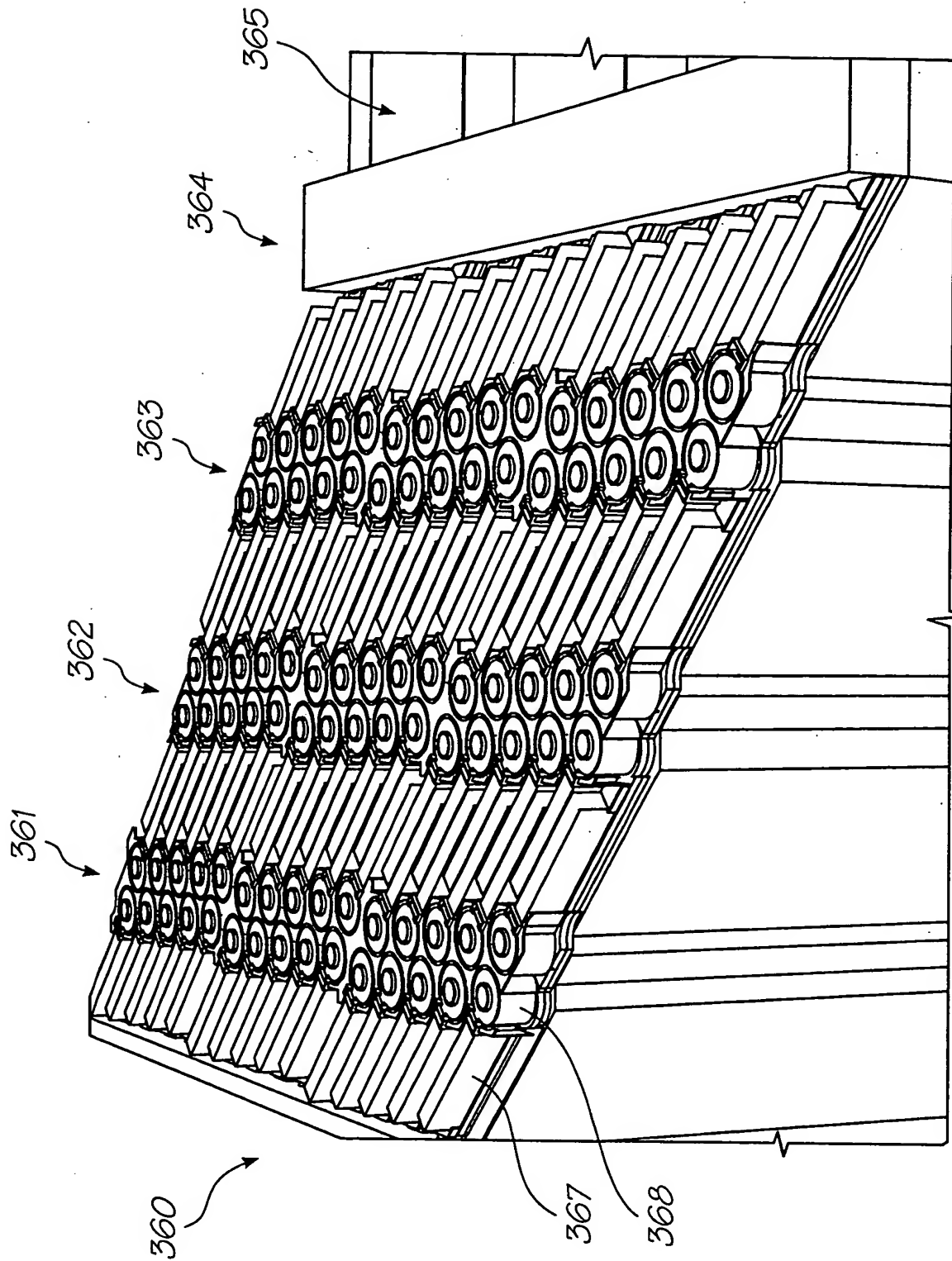


FIG. 85

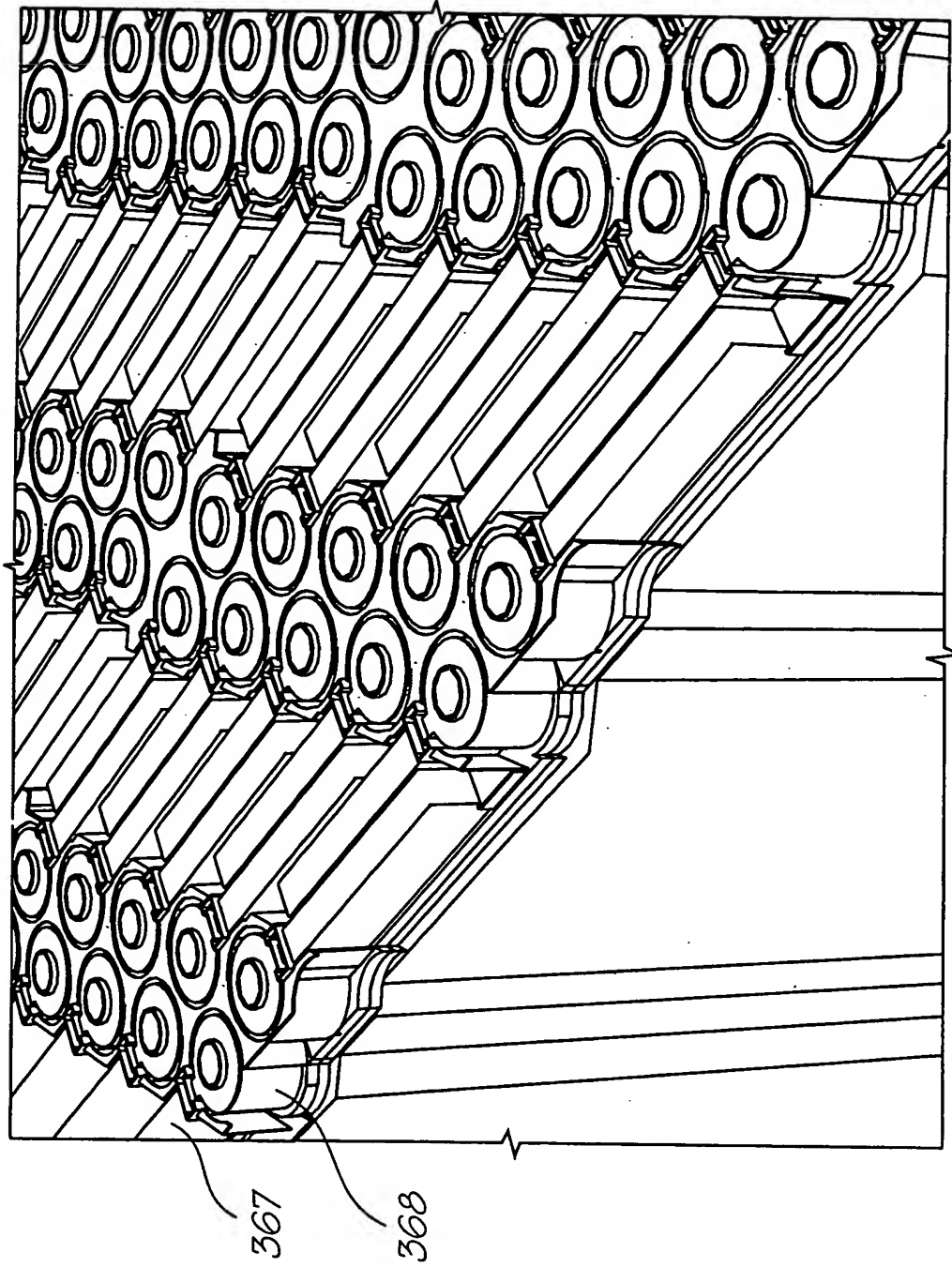


FIG. 86

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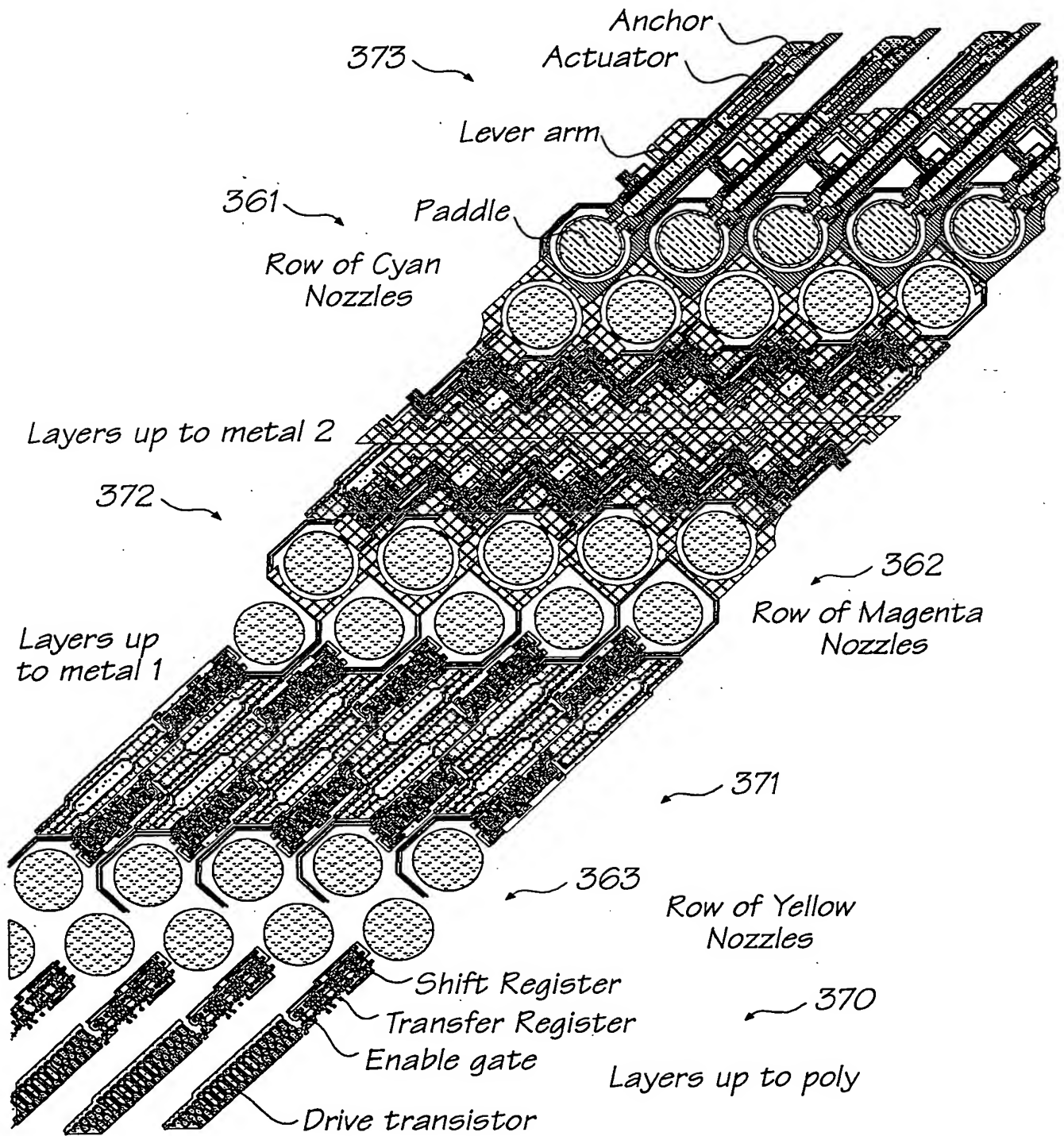


FIG. 87

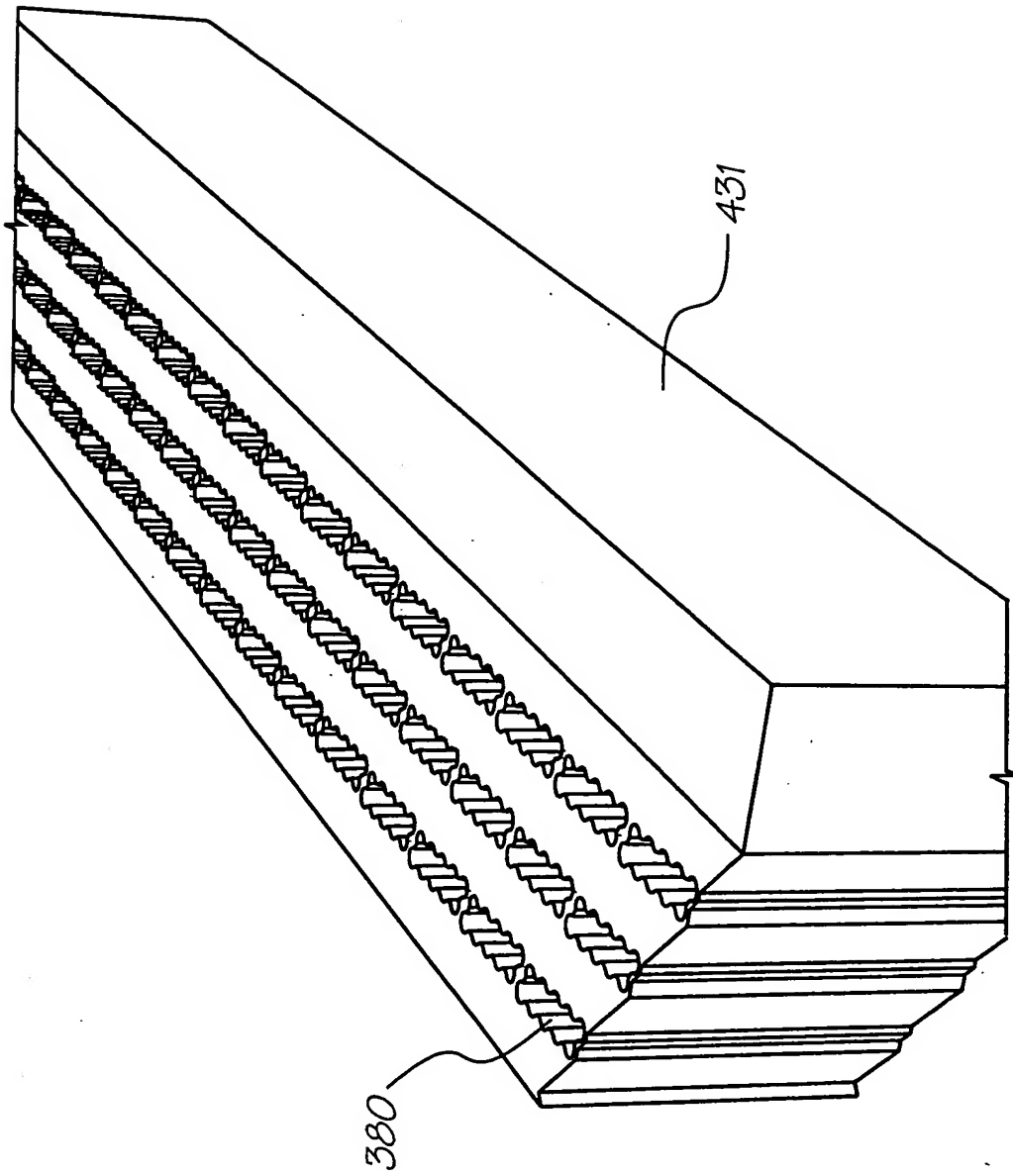


FIG. 88

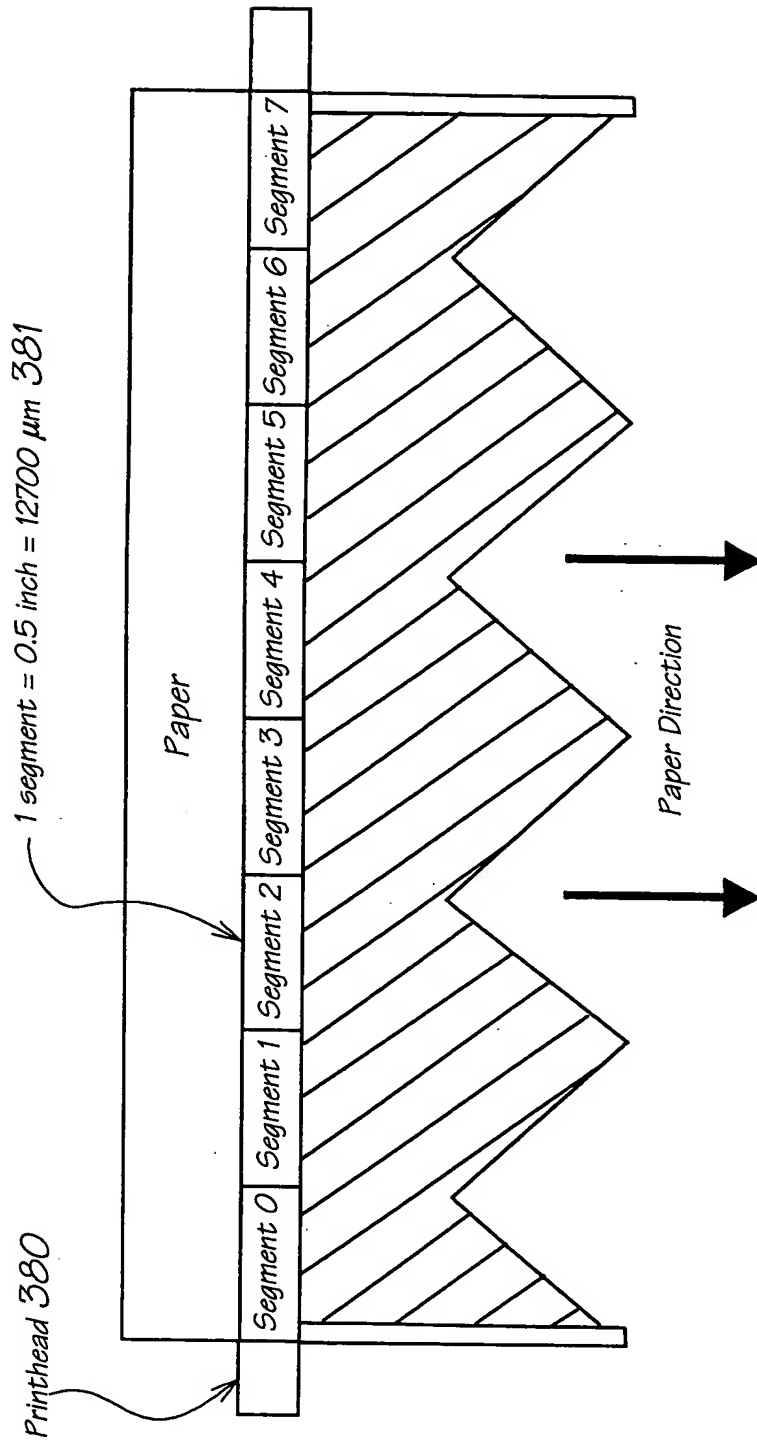
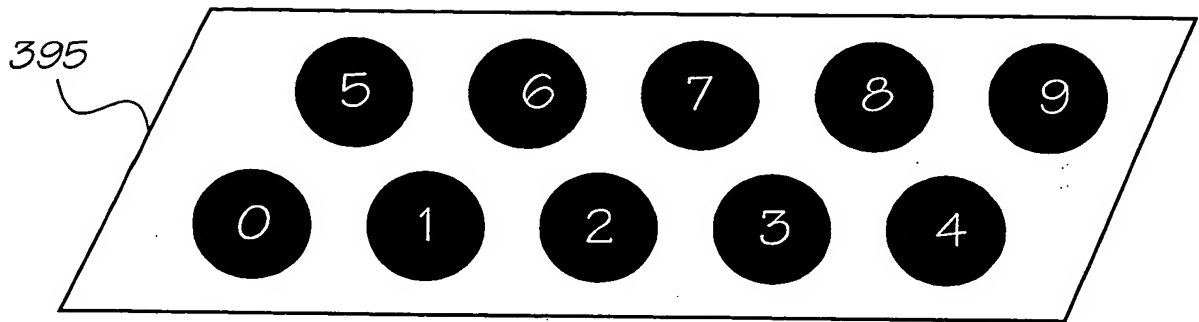


FIG. 89

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A single pod, numbered by firing order

FIG. 90

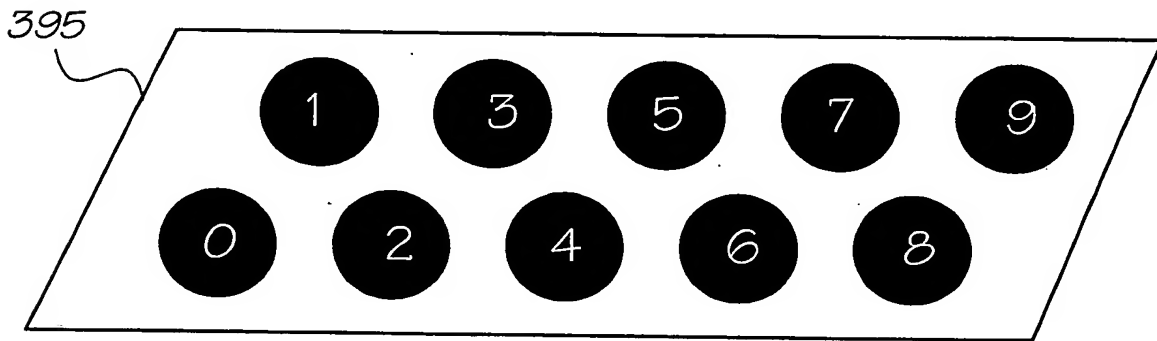


FIG. 91

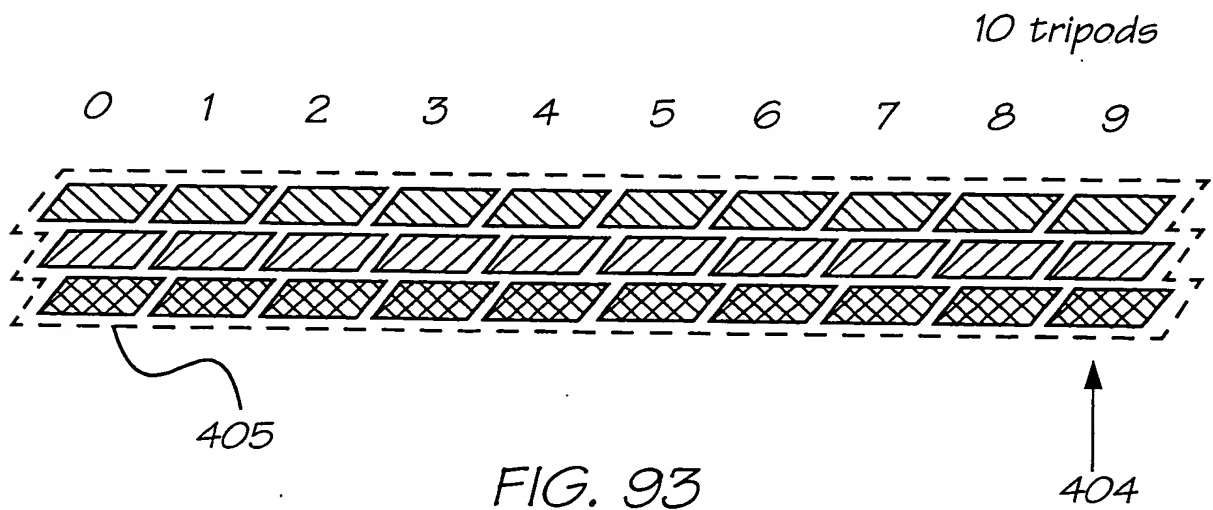


FIG. 93

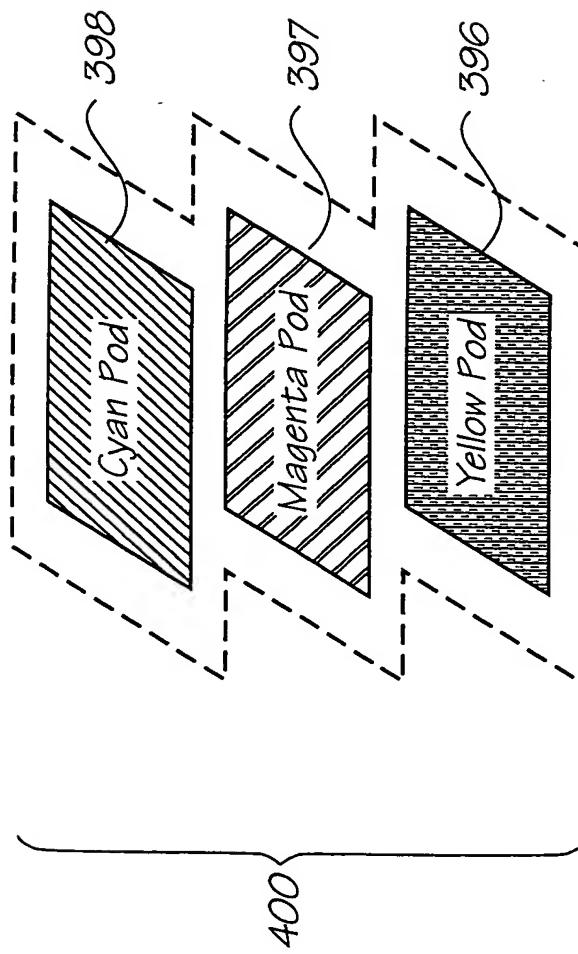


FIG. 92

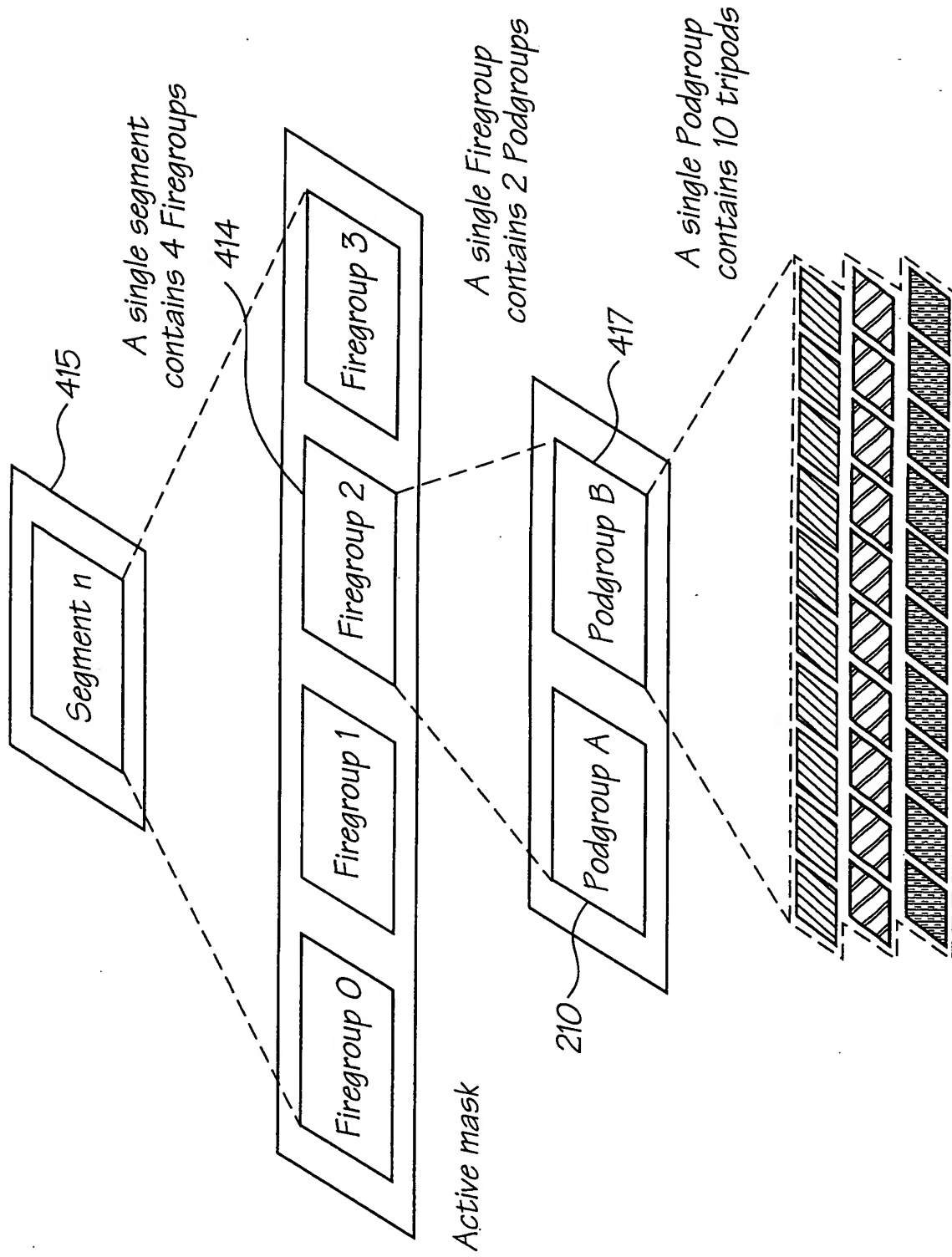


FIG. 94

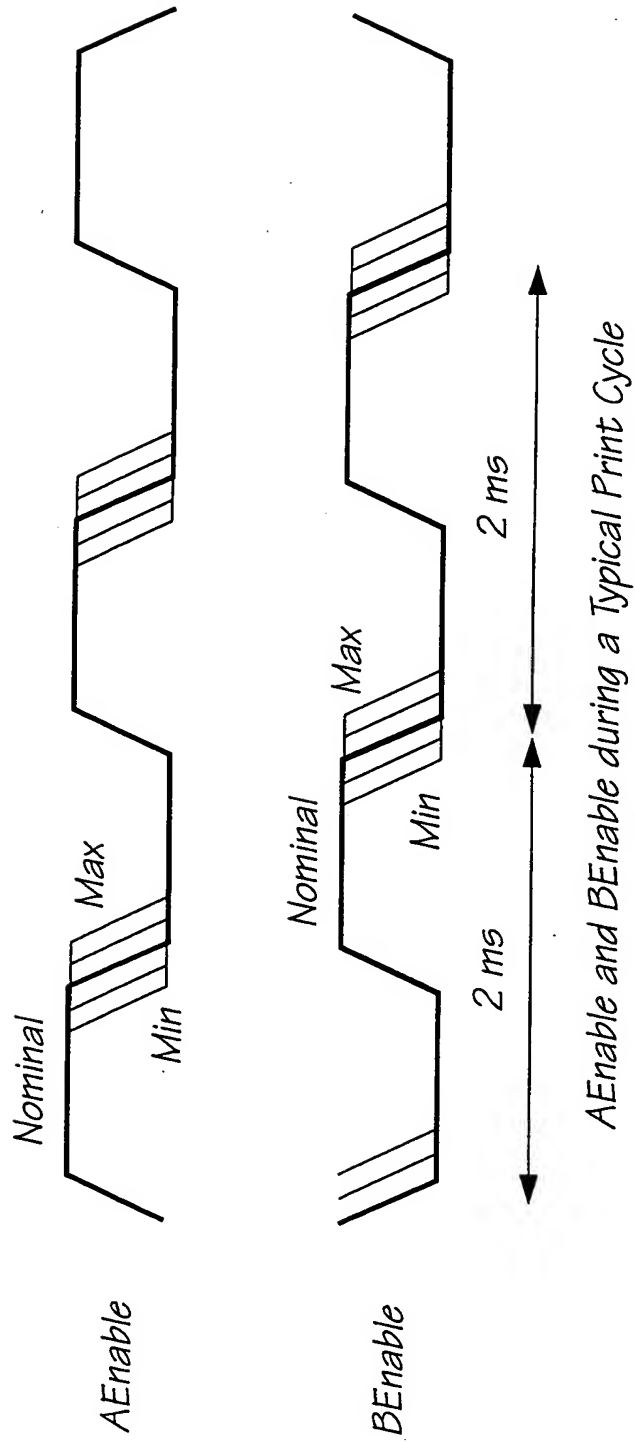


FIG. 95

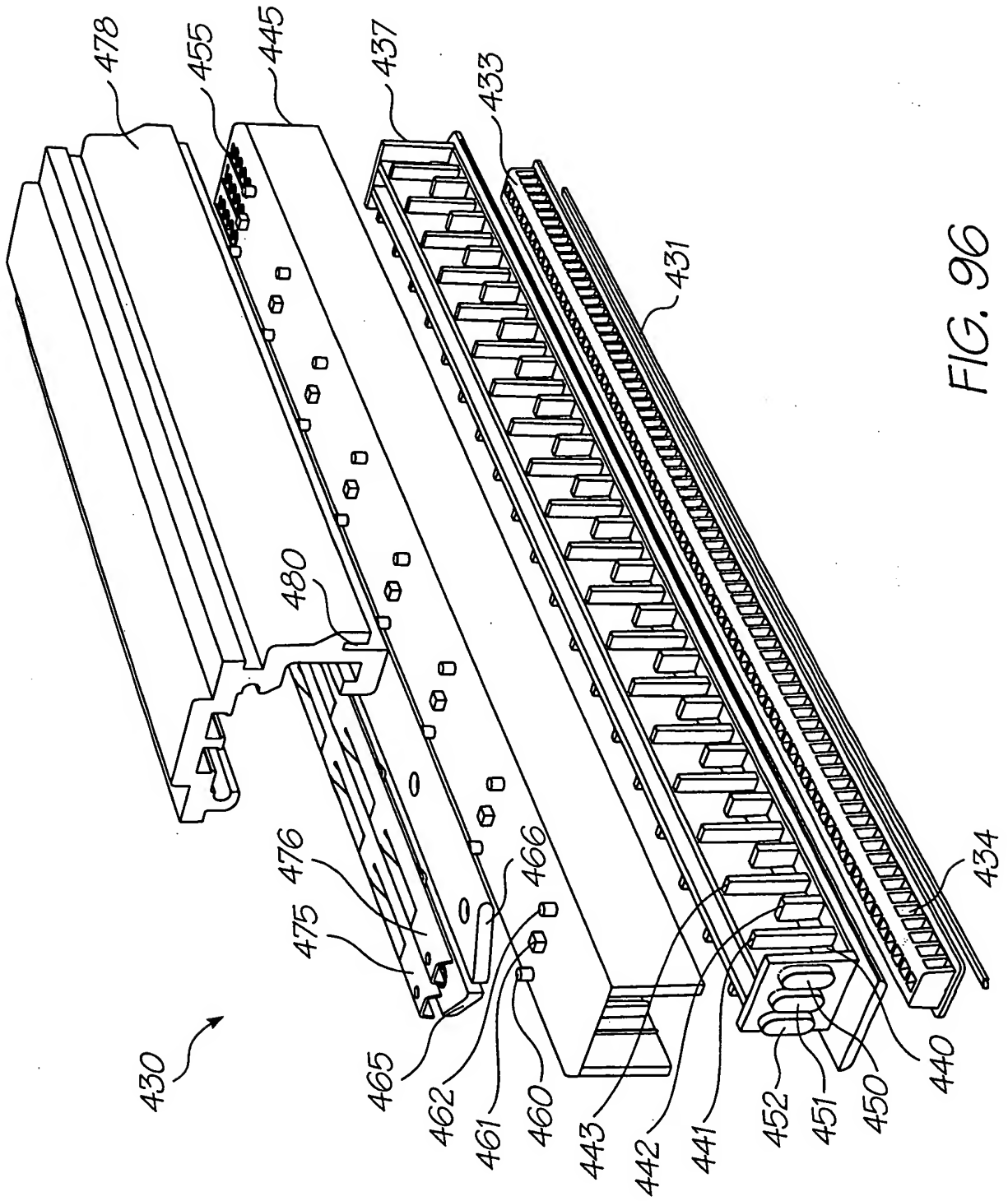


FIG. 96

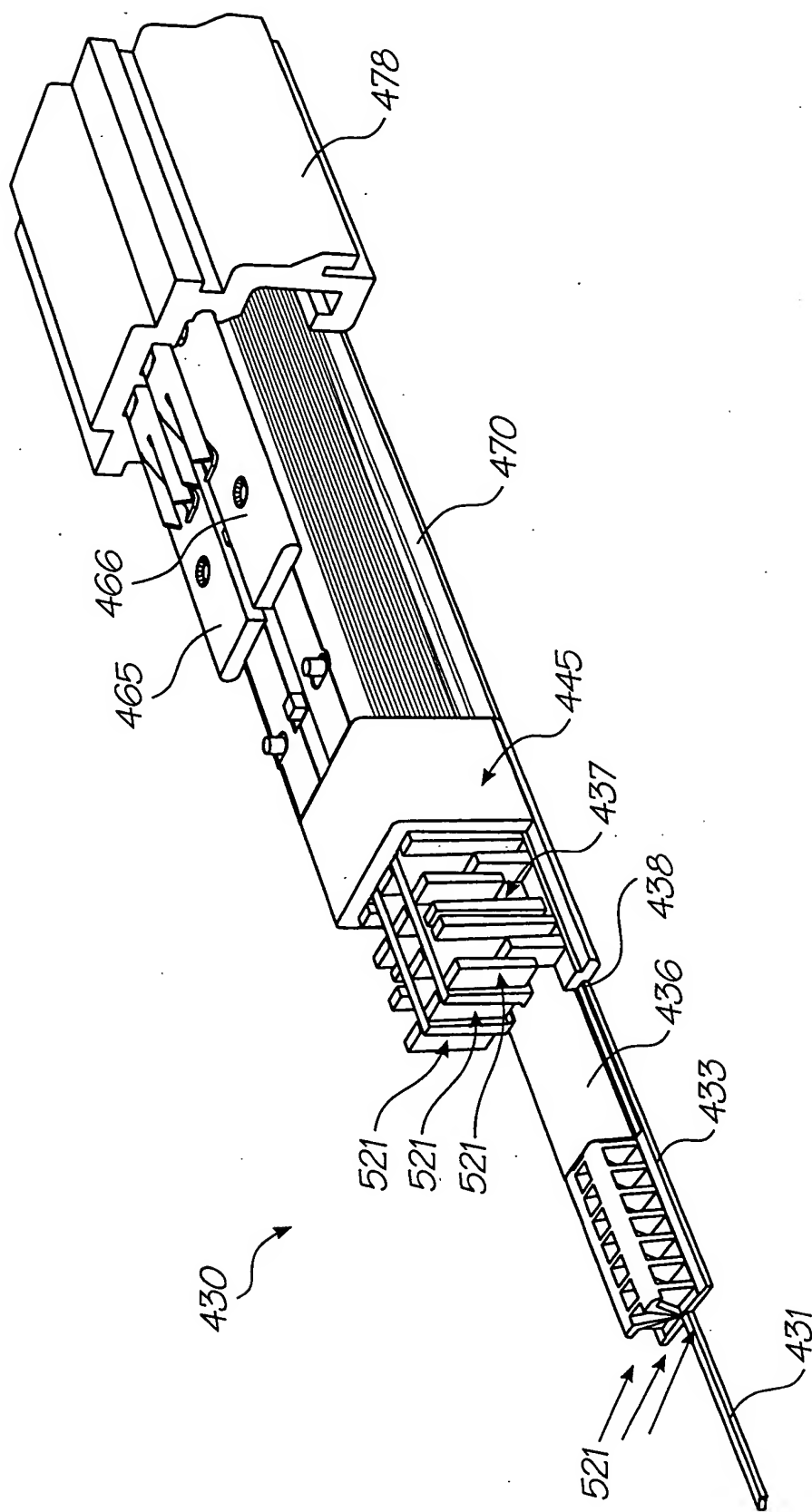


FIG. 97

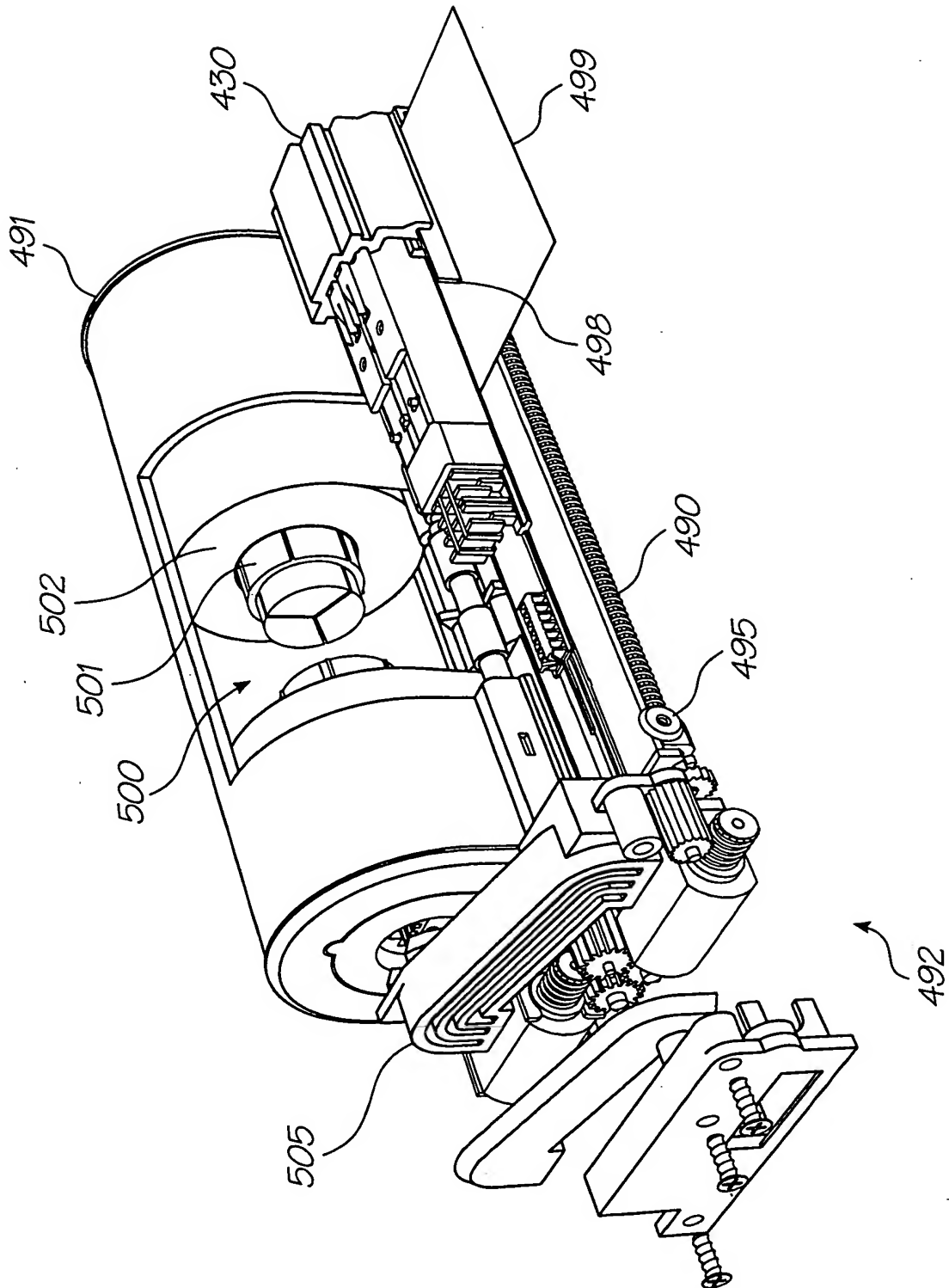


FIG. 98

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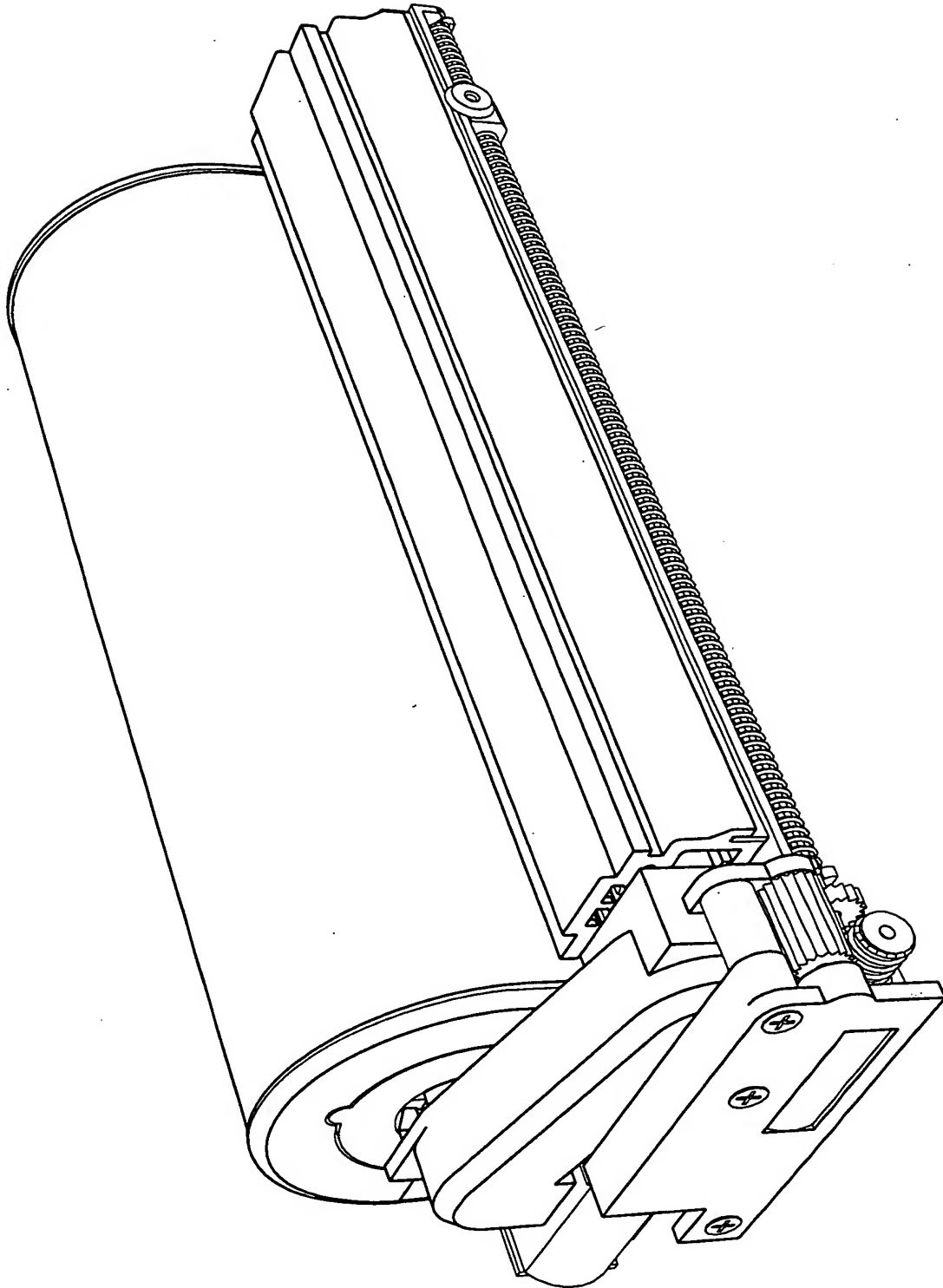


FIG. 99

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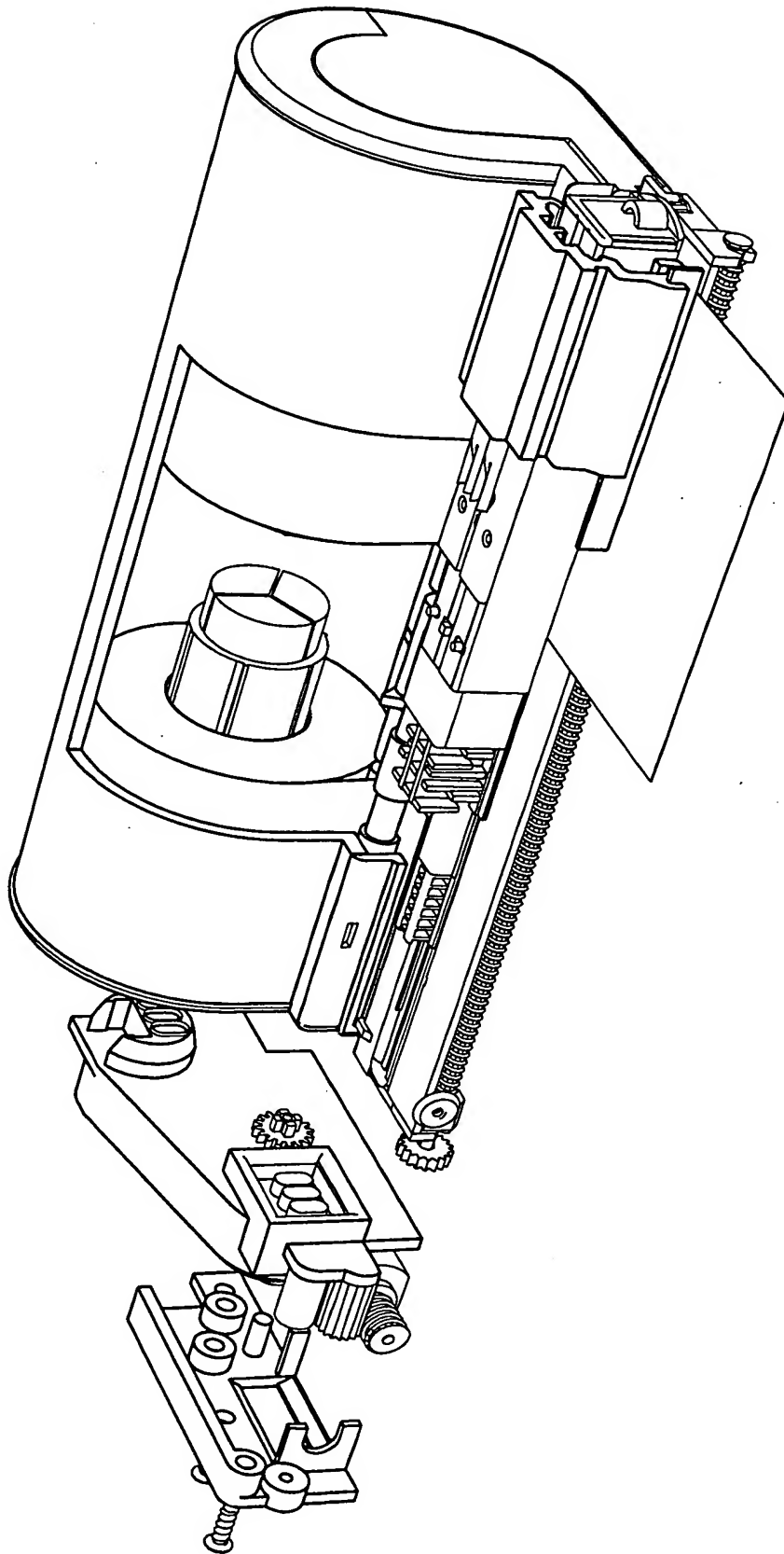


FIG. 100

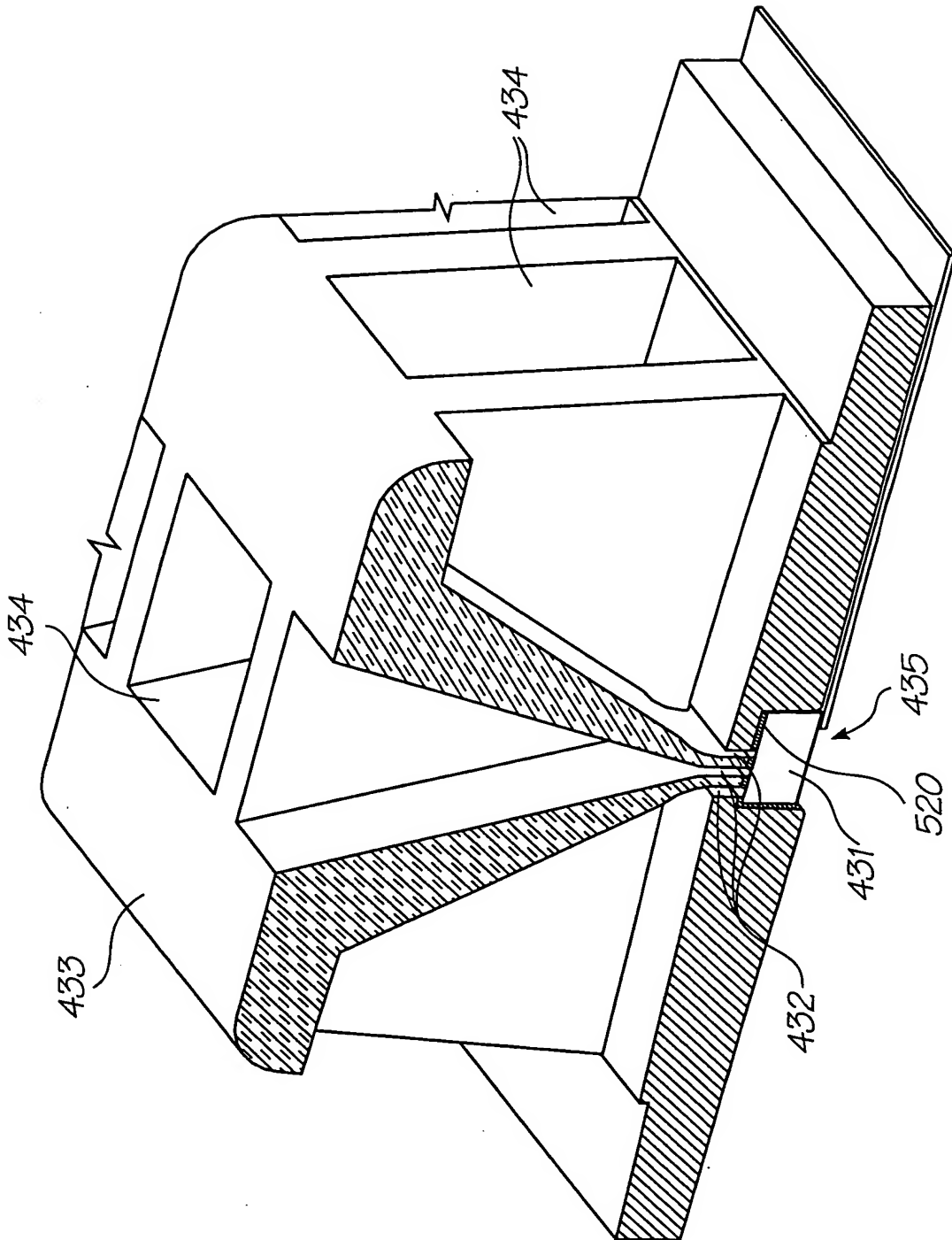


FIG. 101

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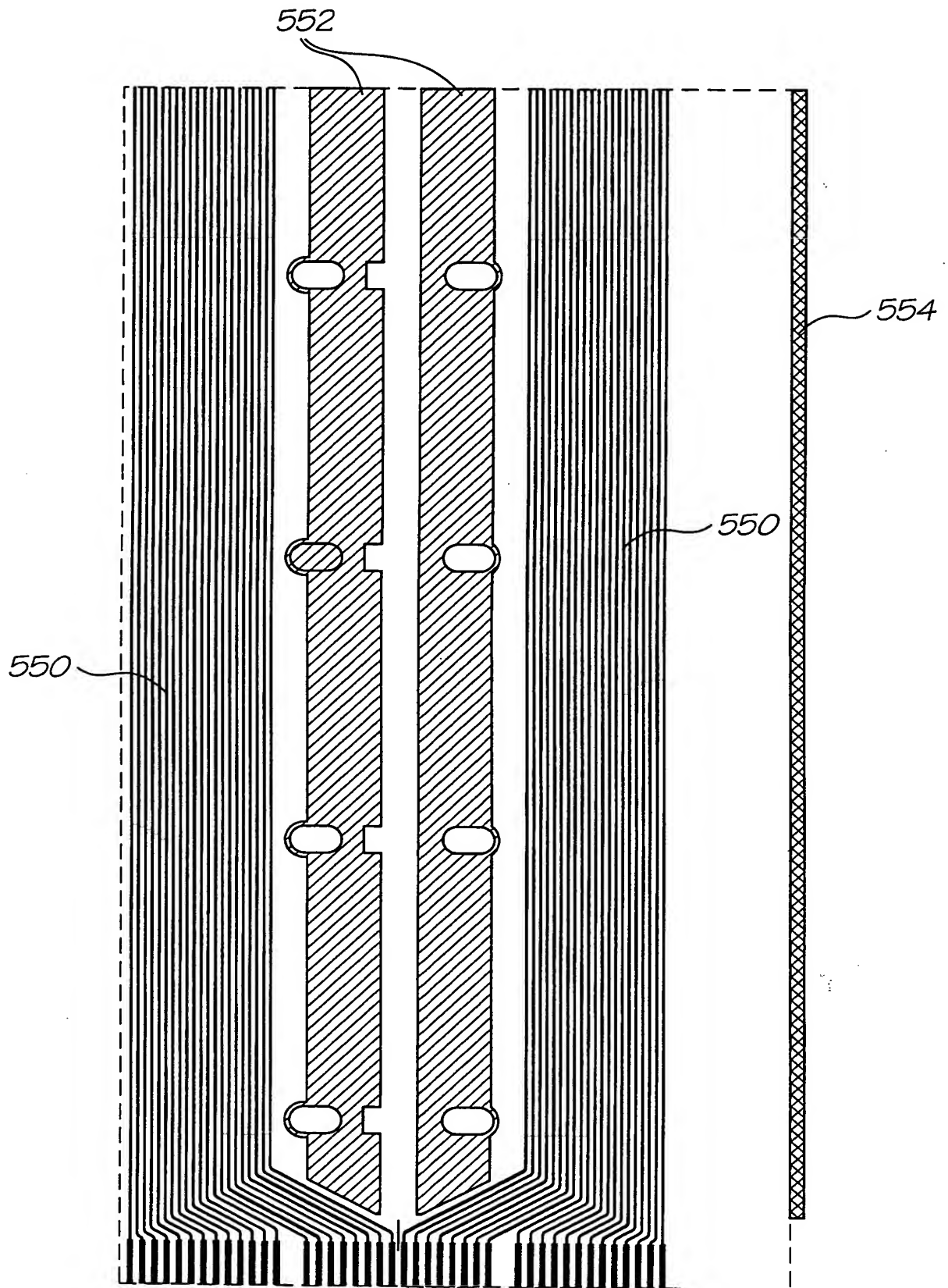


FIG. 102

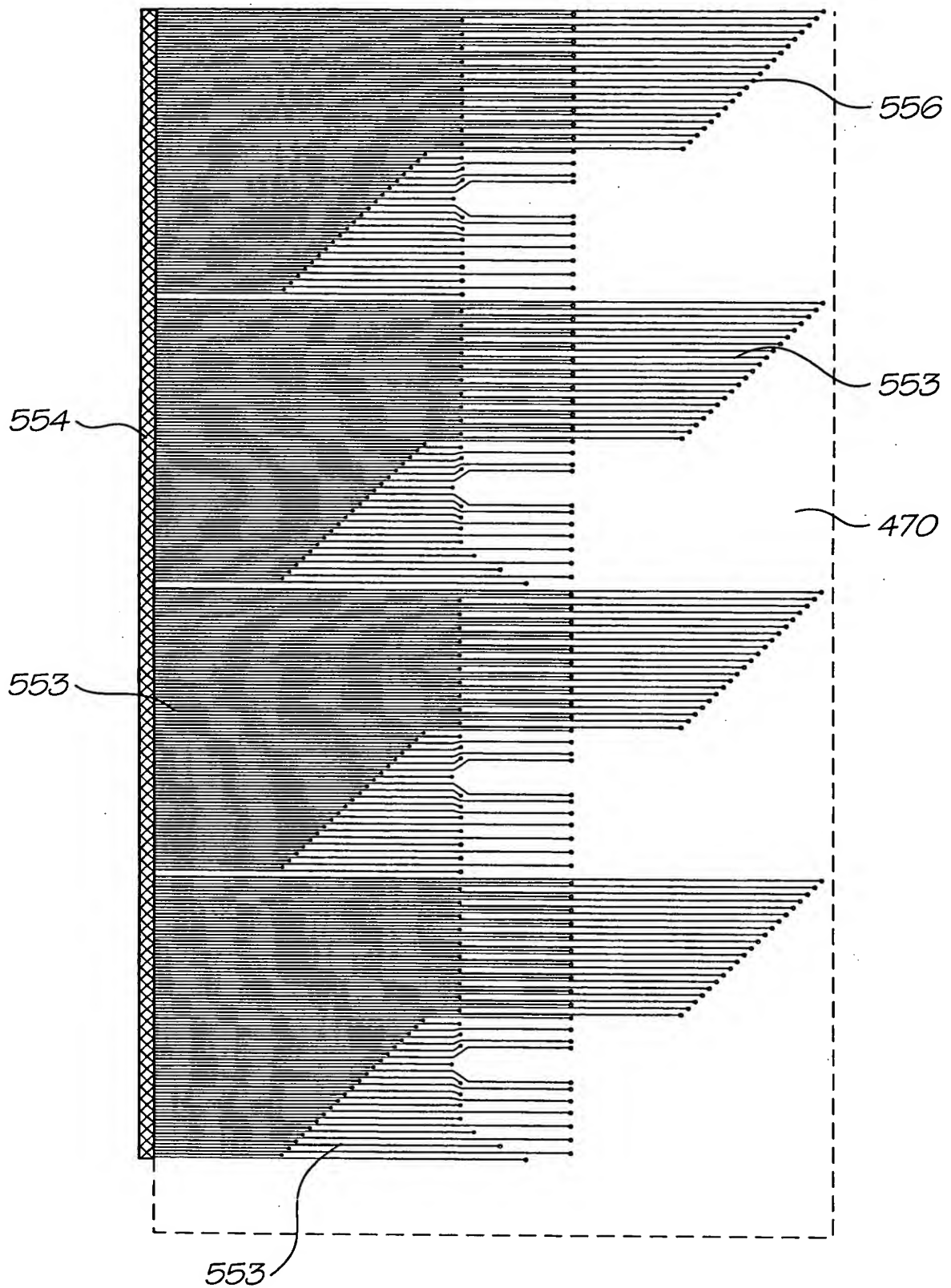


FIG. 103

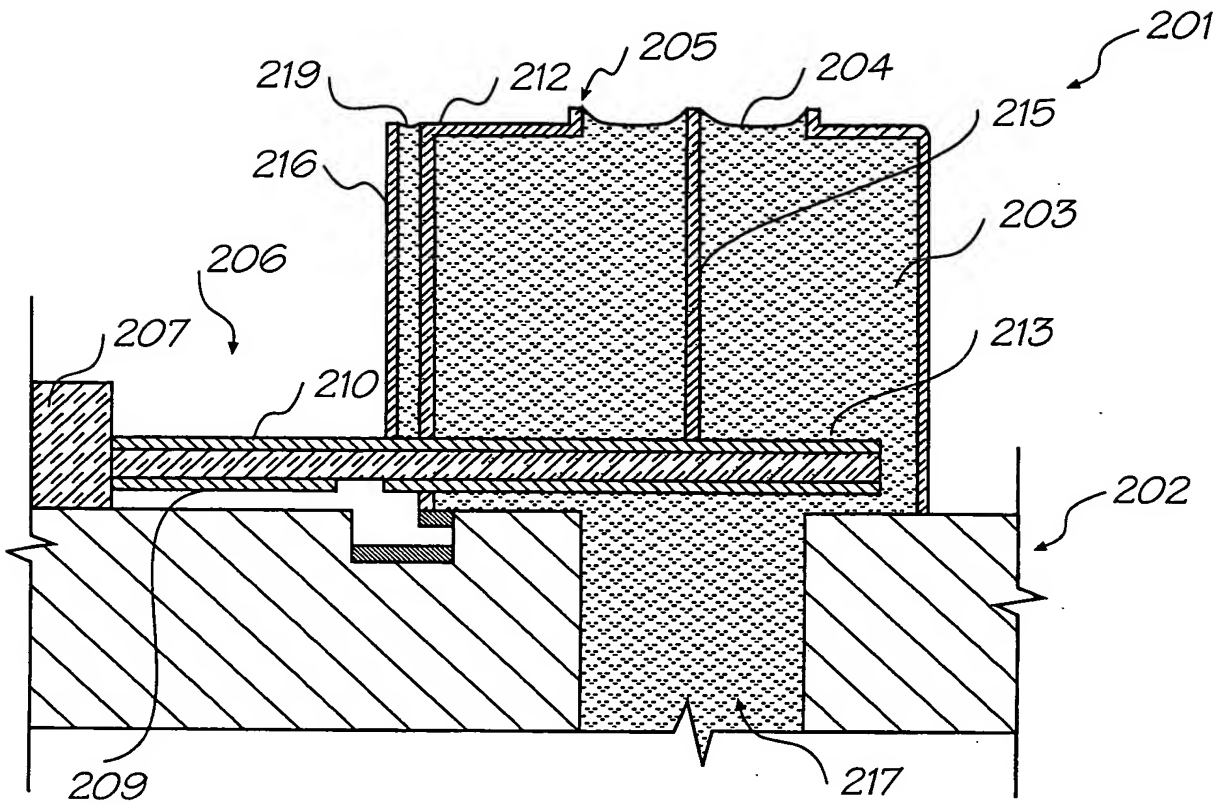


FIG. 104

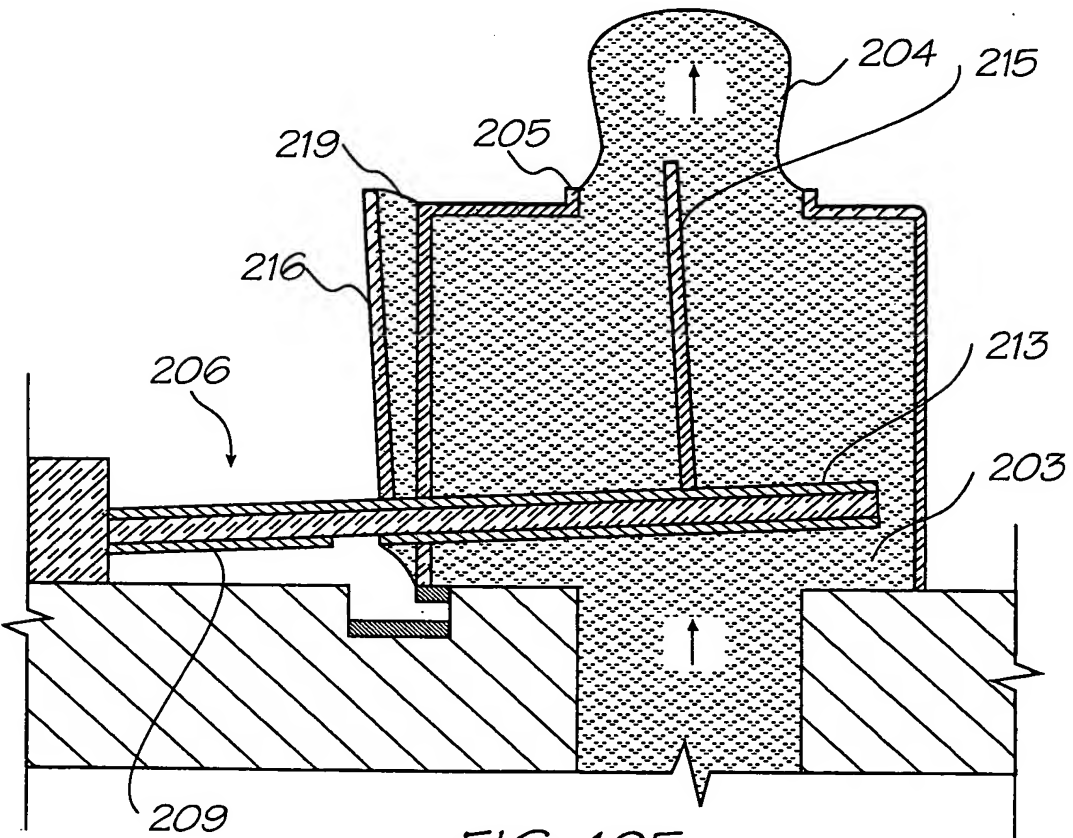


FIG. 105

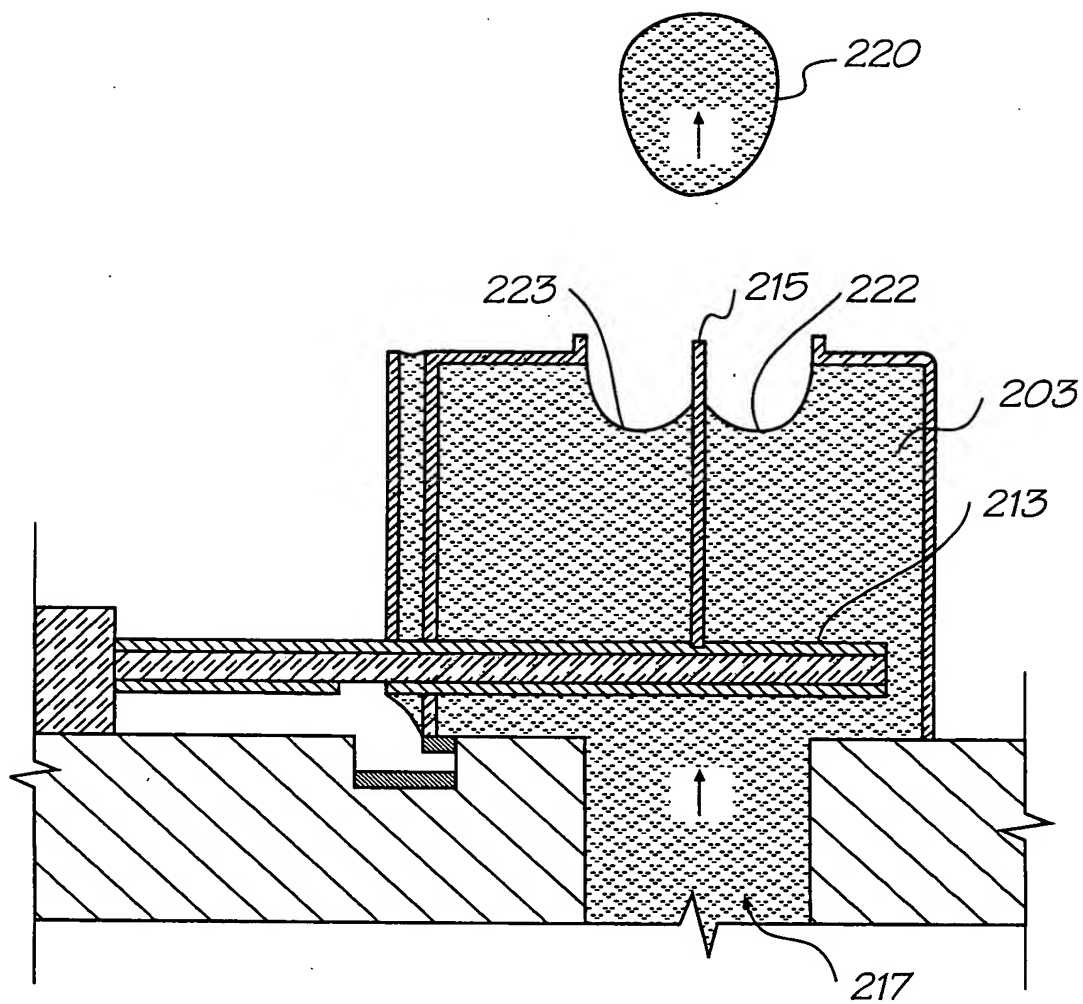


FIG. 106

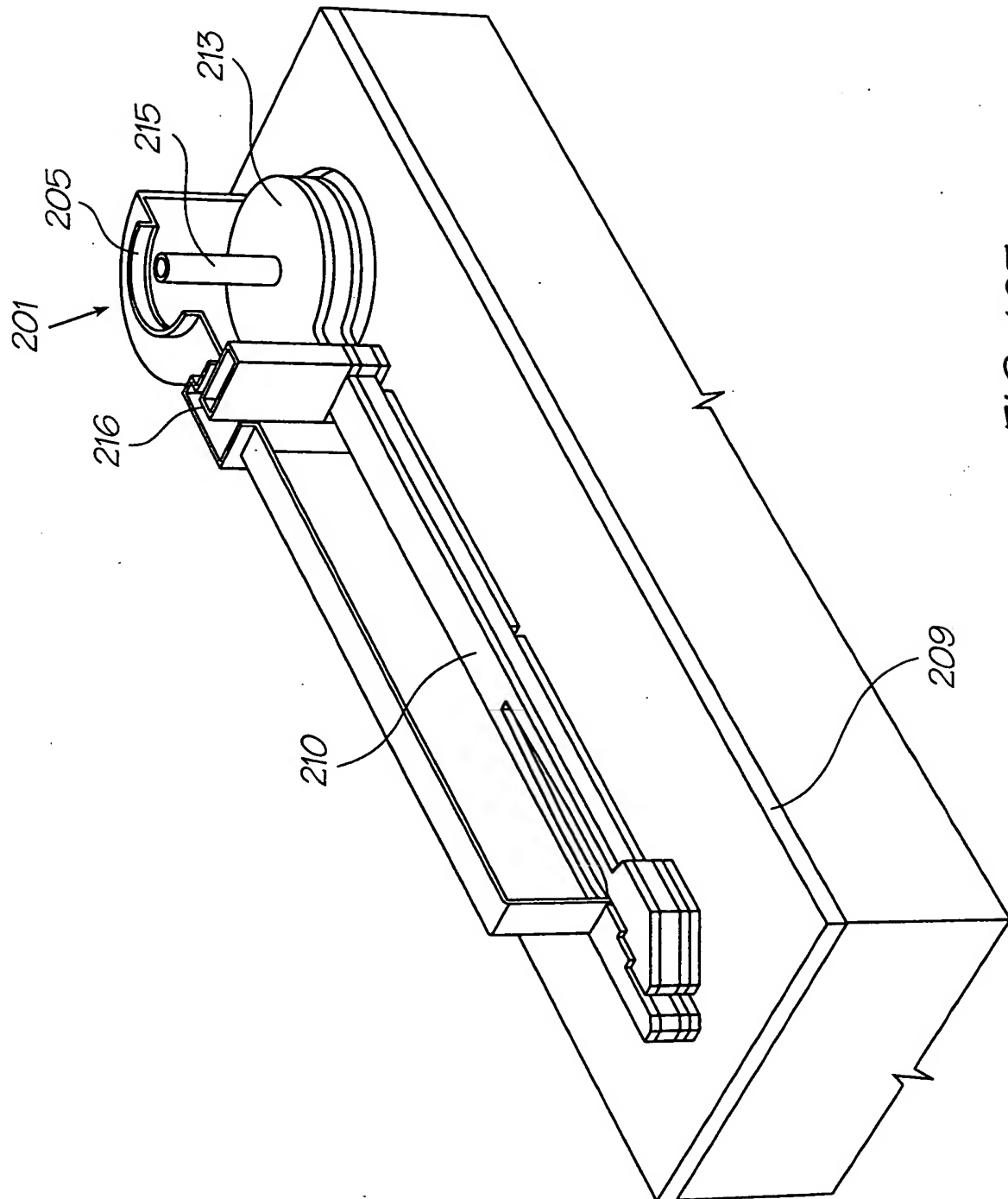


FIG. 107

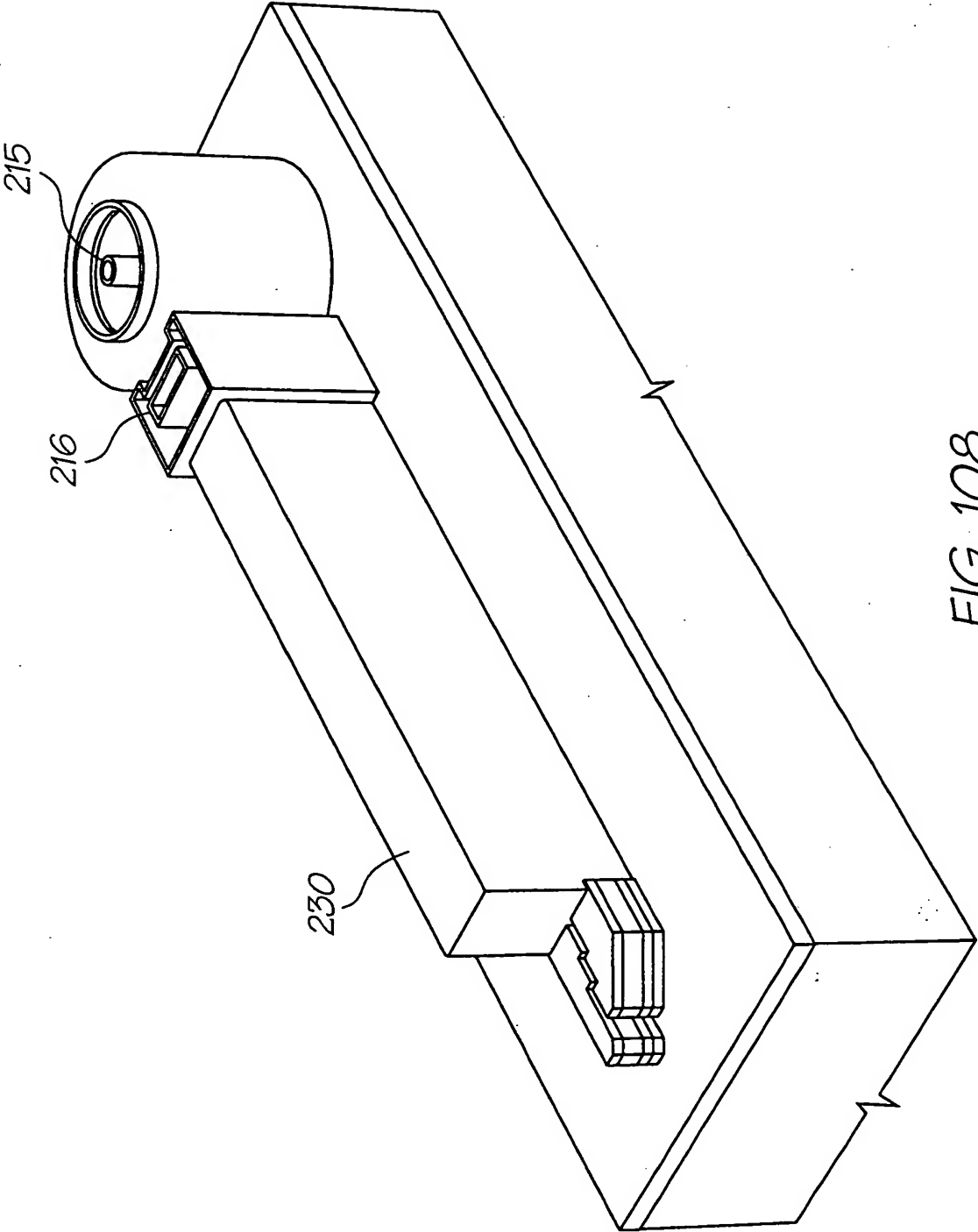


FIG. 108

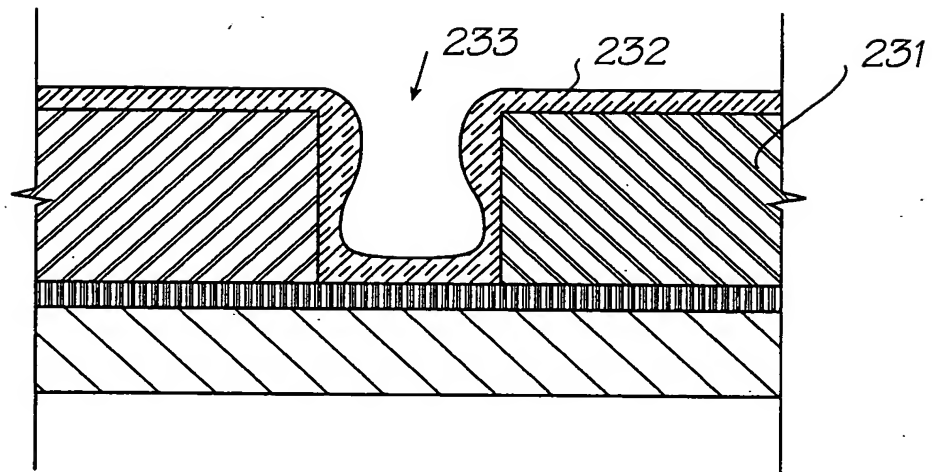


FIG. 109

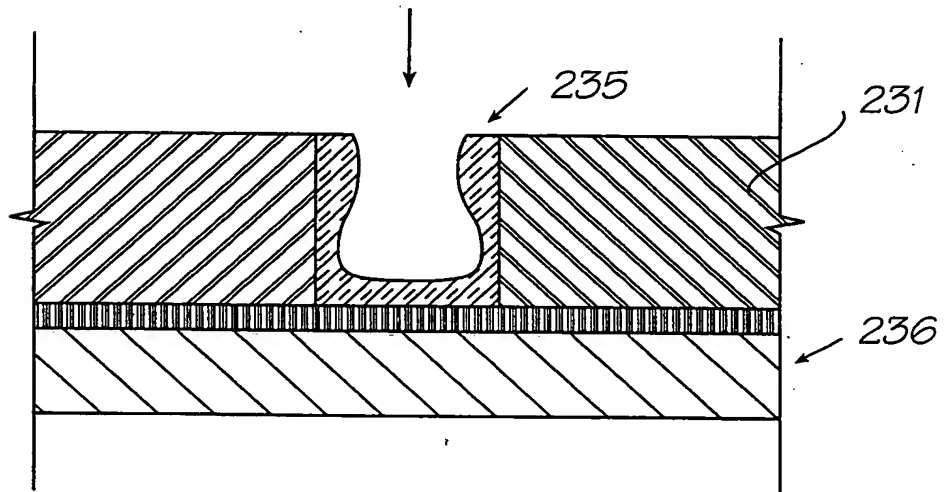


FIG. 110

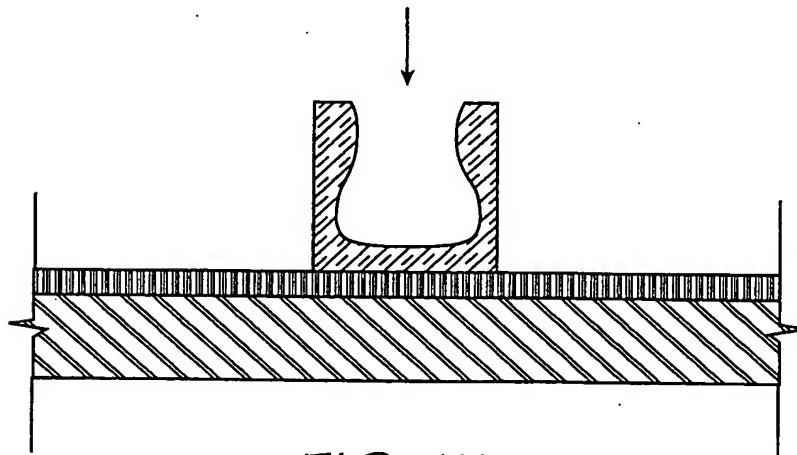


FIG. 111